



**THE DATASHEET OF  
CY8C6245LQI-S3D02**





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## General Description

PSoC® 6 MCU is a high-performance, ultra-low-power and secured MCU platform, purpose-built for IoT applications. Based on the PSoC 6 MCU platform, this product line is a combination of a dual CPU microcontroller with low-power flash technology, digital programmable logic, high-performance analog-to-digital conversion and standard communication and timing peripherals.

## Features

### 32-bit Dual CPU Subsystem

- 150-MHz Arm® Cortex®-M4F (CM4) CPU with single-cycle multiply, floating point, and memory protection unit (MPU)
- 100-MHz Cortex-M0+ (CM0+) CPU with single-cycle multiply and MPU
- User-selectable core logic operation at either 1.1 V or 0.9 V
- Active CPU current slope with 1.1-V core operation
  - Cortex-M4: 40  $\mu$ A/MHz
  - Cortex-M0+: 20  $\mu$ A/MHz
- Active CPU current slope with 0.9-V core operation
  - Cortex-M4: 22  $\mu$ A/MHz
  - Cortex-M0+: 15  $\mu$ A/MHz
- Three DMA controllers

### Memory Subsystem

- 512-KB application flash, 32-KB auxiliary flash (AUXflash), and 32-KB supervisory flash (SFlash); read-while-write (RWW) support. Two 8-KB flash caches, one for each CPU.
- 256-KB SRAM with programmable power control and retention granularity
- One-time-programmable (OTP) 1-Kb eFuse array

### Low-Power 1.7-V to 3.6-V Operation

- Six power modes for fine-grained power management
- Deep Sleep mode current of 7  $\mu$ A with 64-KB SRAM retention
- On-chip DC-DC buck converter, <1  $\mu$ A quiescent current
- Backup domain with 64 bytes of memory and real-time clock

### Flexible Clocking Options

- 8-MHz internal main oscillator (IMO) with  $\pm 2\%$  accuracy
- Ultra-low-power 32-kHz internal low-speed oscillator (ILO)
- On-chip crystal oscillators (16 to 35 MHz, and 32 kHz)
- Phase-locked loop (PLL) for multiplying clock frequencies
- Frequency-locked loop (FLL) for multiplying IMO frequency
- Integer and fractional peripheral clock dividers

### Quad-SPI (QSPI)/Serial Memory Interface (SMIF)

- Execute-In-Place (XIP) from external quad SPI flash
- On-the-fly encryption and decryption
- 4-KB cache for greater XIP performance with lower power
- Supports single, dual, and quad interfaces with throughput up to 320 Mbps

### Segment LCD Drive

- Supports up to 63 segments and up to 8 commons.
- Operates in system Deep Sleep mode

### Serial Communication

- Seven run-time configurable serial communication blocks (SCBs)
  - Six SCBs: configurable as SPI, I<sup>2</sup>C, or UART
  - One Deep Sleep SCB: configurable as SPI or I<sup>2</sup>C
- USB Full-Speed device interface
- One SD Host Controller/eMMC/SD controller
- One CAN FD block

### Timing and Pulse-Width Modulation

- Twelve timer/counter/pulse-width modulators (TCPWMs)
- Center-aligned, edge, and pseudo-random modes
- Comparator-based triggering of kill signals

### Programmable Analog

- 12-bit 2-Msps SAR ADC with differential and single-ended modes and 16-channel sequencer with result averaging
- Two low-power comparators available in system Deep Sleep and Hibernate modes
- Built-in temperature sensor connected to ADC

### Up to 64 Programmable GPIOs

- Two Smart I/O™ ports (8 I/Os) enable Boolean operations on GPIO pins; available during system Deep Sleep
- Programmable drive modes, strengths, and slew rates
- Two overvoltage-tolerant (OVT) pins

### Capacitive Sensing

- Cypress CapSense® sigma-delta (CSD) provides best-in-class signal-to-noise ratio (SNR), liquid tolerance, and proximity sensing
- Enables dynamic usage of both self and mutual sensing
- Automatic hardware tuning (SmartSense™)

**Security Built into Platform Architecture**

- ROM-based root of trust via uninterruptible “Secure Boot”
- Authentication during boot using hardware hashing
- Step-wise authentication of execution images
- Secured execution of code in execute-only mode for protected routines
- All debug and test ingress paths can be disabled
- Up to eight protection contexts

**Cryptography Accelerator**

- Hardware acceleration for symmetric and asymmetric cryptographic methods and hash functions
- True random number generation (TRNG) function

**Packages**

- 100 TQFP, 68 QFN, 49 WLCSP

**Device Identification and Revisions**

- Product line ID (12-bit): 0x105
- Major/Minor die revision ID: 1/2
- Firmware revisions: ROM Boot: 7.1, Flash Boot: 3.1.0.378 (see [Boot Code](#) section)

This product line has a JTAG ID which is available through the SWJ interface. It is a 32-bit ID, where:

- The most significant digit is the device revision, based on the Major Die Revision
- The next four digits correspond to the part number, for example "E4B0" as a hexadecimal number
- The three least significant digits are the manufacturer ID, in this case "069" as a hexadecimal number

The Silicon ID system call can be used by firmware to get Silicon ID and ROM Boot data. For more information, see the [technical reference manual \(TRM\)](#).

The Flash Boot version can be read directly from designated addresses 0x1600 2004 and 0x1600 2018. For more information, see the [technical reference manual \(TRM\)](#).

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## Development Ecosystem

### PSoC 6 MCU Resources

Cypress provides a wealth of data at [www.cypress.com](http://www.cypress.com) to help you select the right PSoC device and quickly and effectively integrate it into your design. The following is an abbreviated list of resources for PSoC 6 MCU:

- **Overview:** [PSoC Portfolio](#), [PSoC Roadmap](#)
- **Product Selectors:** [PSoC 6 MCU](#)
- **Application Notes** cover a broad range of topics, from basic to advanced level, and include the following:
  - [AN221774](#): Getting Started with PSoC 6 MCU
  - [AN218241](#): PSoC 6 MCU Hardware Design Guide
  - [AN213924](#): PSoC 6 MCU Device Firmware Update Guide
  - [AN215656](#): PSoC 6 MCU Dual-CPU System Design
  - [AN219528](#): PSoC 6 MCU Power Reduction Techniques
  - [AN221111](#): PSoC 6 MCU Creating a Secure System
  - [AN85951](#): PSoC 4, PSoC 6 MCU CapSense Design Guide
- **Code Examples** demonstrate product features and usage, and are also available on [Cypress GitHub repositories](#).
- **Technical Reference Manuals (TRMs)** provide detailed descriptions of PSoC 6 MCU architecture and registers.
- **PSoC 6 MCU Programming Specification** provides the information necessary to program PSoC 6 MCU nonvolatile memory
- **Development Tools**
  - [ModusToolbox®](#) software enables cross platform code development with a robust suite of tools and software libraries
  - [CY8CPROTO-062S3-4343W](#) PSoC 6 Wi-Fi-BT Prototyping Kit : a low-cost hardware platform that enables design and debug of the PSoC 62 CY8C62x5 product line.
  - [PSoC 6 CAD libraries](#) provide footprint and schematic support for common tools. [BSDL files](#) and [IBIS models](#) are also available.
- **Training Videos** are available on a wide range of topics including the [PSoC 6 MCU 101 series](#)
- **Cypress Developer Community** enables connection with fellow PSoC developers around the world, 24 hours a day, 7 days a week, and hosts a dedicated [PSoC 6 MCU Community](#)

### ModusToolbox™ IDE and the PSoC 6 SDK

[ModusToolbox Software](#) is Cypress' comprehensive collection of multi-platform tools and software libraries that enable an immersive development experience for creating converged MCU and wireless systems. It is:

- Comprehensive - it has the resources you need
- Flexible - you can use the resources in your own workflow
- Atomic - you can get just the resources you want

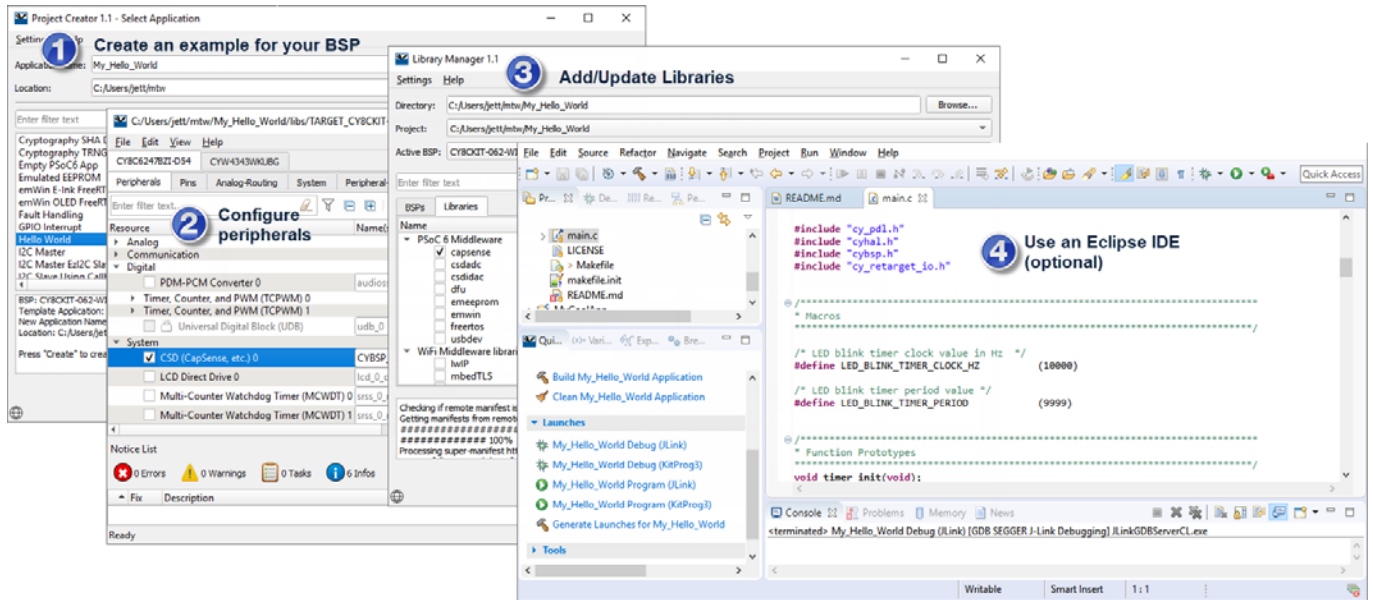
Cypress provides a large collection of code [repositories on GitHub](#). This includes:

- Board Support Packages (BSPs) aligned with Cypress kits
- Low-level resources, including a hardware abstraction layer (HAL) and peripheral driver library (PDL)
- Middleware enabling industry-leading features such as CapSense, Bluetooth Low Energy, and mesh networks
- An extensive set of thoroughly tested [code example applications](#)

**Note:** The HAL provides a high-level, simplified interface to configure and use the hardware blocks on Cypress MCUs. It is a generic interface that can be used across multiple product families. For example, it wraps the PSoC 6 PDL with a simplified API, but the PDL exposes all low-level peripheral functionality. You can leverage the HAL's simpler and more generic interface for most of an application, even if one portion requires finer-grained control.

ModusToolbox Software is IDE-neutral and easily adaptable to your workflow and preferred development environment. It includes a project creator, peripheral and library configurators, a library manager, as well as the optional Eclipse IDE for ModusToolbox. For information on using Cypress tools, refer to the documentation delivered with ModusToolbox software, and [AN228571: Getting Started with PSoC 6 MCU on ModusToolbox](#).

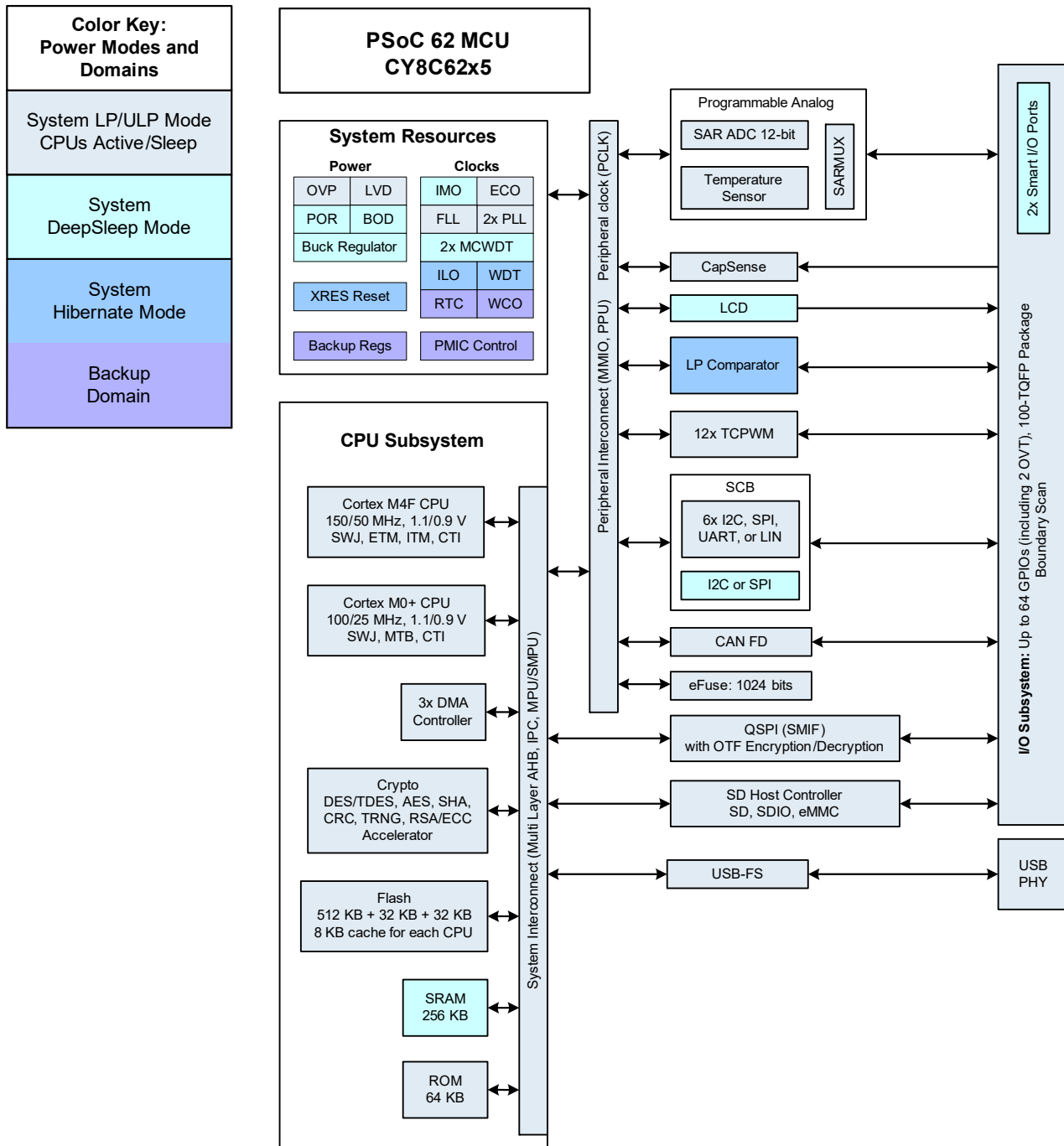
Figure 1. ModusToolbox Software Tools



### Blocks and Functionality

Figure 2 shows the major subsystems and a simplified view of their interconnections. The color coding shows the lowest power mode where the particular block is still functional (for example, the SRAM is functional down to system Deep Sleep mode).

Figure 2. Block Diagram



There are three debug access ports, one each for CM4 and CM0+, and a system port.

PSoC 6 MCU devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware. All device interfaces can be permanently disabled for applications concerned about a reprogrammed device or starting and interrupting flash programming sequences. All programming, debug, and test interfaces can be disabled.

Complete debug-on-chip functionality enables full device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The Eclipse IDE for ModusToolbox provides fully integrated programming and debug support for these devices. The SWJ (SWD and JTAG) interface is fully compatible with industry-standard third party probes. With the ability to disable debug features, with very robust flash protection, and by allowing customer-proprietary functionality to be implemented in on-chip programmable blocks, PSoC 6 provides multiple levels of device security.

## Functional Description

The following sections provide an overview of the features, capabilities and operation of each functional block identified in the block diagram in [Figure 2](#). For more detailed information, refer to the following documentation:

### ■ Board Support Package (BSP) Documentation

BSPs are available on [GitHub](#). They are aligned with Cypress kits and provide files for basic device functionality such as hardware configuration files, startup code, and linker files. The BSP also includes other libraries that are required to support a kit. Each BSP has its own documentation, but typically includes an API reference such as the example [here](#). This [search link](#) finds all currently available BSPs on the Cypress GitHub site.

### ■ Hardware Abstraction Layer API Reference Manual

The Cypress Hardware Abstraction Layer (HAL) provides a high-level interface to configure and use hardware blocks on Cypress MCUs. It is a generic interface that can be used across multiple product families. You can leverage the HAL's simpler and more generic interface for most of an application, even if one portion requires finer-grained control. The [HAL API Reference](#) provides complete details. Example applications that use the HAL download it automatically from the GitHub repository.

### ■ Peripheral Driver Library (PDL) Application Programming Interface (API) Reference Manual

The Peripheral Driver Library (PDL) integrates device header files and peripheral drivers into a single package and supports all PSoC 6 MCU product lines. The drivers abstract the hardware functions into a set of easy-to-use APIs. These are fully documented in the [PDL API Reference](#). Example applications that use the PSoC 6 PDL download it automatically from the GitHub repository.

### ■ Architecture Technical Reference Manual (TRM)

The architecture TRM provides a detailed description of each resource in the device. This is the next reference to use if it is necessary to understand the operation of the hardware below the software provided by PDL. It describes the architecture and functionality of each resource and explains the operation of each resource in all modes. It provides specific guidance regarding the use of associated registers.

### ■ Register Technical Reference Manual

The register TRM provides a complete list of all registers in the device. It includes the breakdown of all register fields, their possible settings, read/write accessibility, and default states. All registers that have a reasonable use in typical applications have functions to access them from within PDL. Note that ModusToolbox and PDL may provide software default conditions for some registers that are different from and override the hardware defaults.

## CPU and Memory Subsystem

PSoC 6 has multiple bus masters, as [Figure 2](#) shows. They are: CPUs, DMA controllers, QSPI, USB, SD Host controller, and a Crypto block. Generally, all memory and peripherals can be accessed and shared by all bus masters through multi-layer Arm AMBA high-performance bus (AHB) arbitration. Accesses between CPUs can be synchronized using an inter-processor communication (IPC) block.

### CPUs

There are two Arm Cortex CPUs:

The Cortex-M4 (CM4) has single-cycle multiply, a floating-point unit (FPU), and a memory protection unit (MPU). It can run at up to 150 MHz. This is the main CPU, designed for a short interrupt response time, high code density, and high throughput.

CM4 implements a version of the Thumb instruction set based on Thumb-2 technology (defined in the [Armv7-M Architecture Reference Manual](#)).

The Cortex-M0+ (CM0+) has single-cycle multiply, and an MPU. It can run at up to 100 MHz; however, for CM4 speeds above 100 MHz, CM0+ and bus peripherals are limited to half the speed of CM4. Thus, for CM4 running at 150 MHz, CM0+ and peripherals are limited to 75 MHz.

In PSoC 64, the initial CM0+ frequency is set according to a provisioned security policy (see PSoC 64 Security). The frequency ranges from 8 MHz to 50 MHz. For more information, see the Register and Architecture TRM.

CM0+ is the secondary CPU; it is used to implement system calls and device-level security, safety, and protection features. CM0+ provides a secured, uninterruptible boot function. This helps ensure that post boot, system integrity is checked and memory and peripheral access privileges are enforced.

CM0+ implements the Armv6-M Thumb instruction set (defined in the [Armv6-M Architecture Reference Manual](#)).

The CPUs have the following power draw, at  $V_{DD} = 3.3\text{ V}$  and using the internal buck regulator:

**Table 1. Active Current Slope at  $V_{DD} = 3.3\text{ V}$  Using the Internal Buck Regulator**

		System Power Mode	
		ULP	LP
CPU	Cortex-M0+	15 $\mu\text{A}/\text{MHz}$	20 $\mu\text{A}/\text{MHz}$
	Cortex-M4	22 $\mu\text{A}/\text{MHz}$	40 $\mu\text{A}/\text{MHz}$

The CPUs can be selectively placed in their Sleep and Deep Sleep power modes as defined by Arm.

Both CPUs have nested vectored interrupt controllers (NVIC) for rapid and deterministic interrupt response, and wakeup interrupt controllers (WIC) for CPU wakeup from Deep Sleep power mode.

The CPUs have extensive debug support. PSoC 6 has a debug access port (DAP) that acts as the interface for device programming and debug. An external programmer or debugger (the "host") communicates with the DAP through the device serial wire debug (SWD) or Joint Test Action Group (JTAG) interface pins. Through the DAP (and subject to device security

restrictions), the host can access the device memory and peripherals as well as the registers in both CPUs.

Each CPU offers debug and trace features as follows:

- CM4 supports six hardware breakpoints and four watchpoints, 4-bit embedded trace macrocell (ETM), serial wire viewer (SWV), and printf()-style debugging through the single wire output (SWO) pin.
- CM0+ supports four hardware breakpoints and two watchpoints, and a micro trace buffer (MTB) with 4-KB dedicated RAM.

PSoC 6 also has an Embedded Cross Trigger for synchronized debugging and tracing of both CPUs.

### Interrupts

This product line has 174 system and peripheral interrupt sources, and supports interrupts and system exceptions on both CPUs. CM4 has 174 interrupt request lines (IRQ), with the interrupt source 'n' directly connected to IRQn. CM0+ has eight interrupts IRQ[7:0] with configurable mapping of one or more interrupt sources to any of the IRQ[7:0]. CM0+ also supports eight internal (software only) interrupts.

Each interrupt supports configurable priority levels (eight levels for CM4 and four levels for CM0+). Up to four system interrupts can be mapped to each of the CPUs' non-maskable interrupts (NMI). Up to 39 interrupt sources are capable of waking the device from Deep Sleep power mode using the WIC. Refer to the [technical reference manual \(TRM\)](#).

### InterProcessor Communication (IPC)

In addition to the Arm SEV and WFE instructions, a hardware InterProcessor Communication (IPC) block is included. It includes 16 IPC channels and 16 IPC interrupt structures. The IPC channels can be used to implement data communication between the processors. Each IPC channel also implements a locking scheme which can be used to manage shared resources. The IPC interrupts let one processor interrupt the other, signaling an event. This is used to trigger events such as notify and release of the corresponding IPC channels. Some IPC channels and other resources are reserved, as [Table 2](#) shows:

**Table 2. Distribution of IPC Channels and Other Resources**

Resources Available	Resources Consumed
IPC channels, 16 available	8 reserved
IPC interrupts, 16 available	8 reserved
Other interrupts	1 reserved
CM0+ NMI	Reserved
Other resources: clock dividers, DMA channels, etc.	1 CM0+ interrupt mux

### Direct Memory Access (DMA) Controllers

This product line has three DMA controllers, with 32, 29, and 2 channels, which support CPU-independent accesses to memory and peripherals. The descriptors for DMA channels can be in SRAM or flash. Therefore, the number of descriptors is limited only by the size of the memory. Each descriptor can transfer data in two nested loops with configurable address increments to the source and destination. The size of data transfer per descriptor varies based on the type of DMA channel. Refer to the [technical reference manual \(TRM\)](#) for detail.

### Cryptography Accelerator (Crypto)

This subsystem consists of hardware implementation and acceleration of cryptographic functions and random number generators.

The Crypto subsystem supports the following:

- Encryption/Decryption Functions
  - Data Encryption Standard (DES)
  - Triple DES (3DES)
  - Advanced Encryption Standard (AES) (128-, 192-, 256-bit)
  - Elliptic Curve Cryptography (ECC)
  - RSA cryptography functions
- Hashing functions
  - Secure Hash Algorithm (SHA)
  - SHA-1
  - SHA-224/-256/-384/-512
- Message authentication functions (MAC)
  - Hashed message authentication code (HMAC)
  - Cipher-based message authentication code (CMAC)
- 32-bit cyclic redundancy code (CRC) generator
- Random number generators
  - Pseudo random number generator (PRNG)
  - True random number generator (TRNG)

### Protection Units

This product line has multiple types of protection units to control erroneous or unauthorized access to memory and peripheral registers. CM4 and CM0+ have Arm MPUs for protection at the bus master level. Other bus masters use additional MPUs. Shared memory protection units (SMPUs) help implement protection for memory resources that are shared among multiple bus masters. Peripheral protection units (PPU) are similar to SMPUs but are designed for protecting the peripheral register space.

Protection units support memory and peripheral access attributes including address range, read/write, code/data, privilege level, secured/non-secured, and protection context. Some protection unit resources are reserved for system usage; see the [technical reference manual](#) for details.

## Memory

PSoC 6 contains flash, SRAM, ROM, and eFuse memory blocks.

### ■ Flash

There is up to 512 KB of application flash, organized in 256-KB sectors.

There are also two 32-KB flash sectors:

- AUXflash, typically used for EEPROM emulation
- Supervisory flash (SFlash). Data stored in Sflash includes device trim values, [Flash Boot](#) code, and encryption keys. After the device transitions into the “Secure” lifecycle stage, SFlash can no longer be changed.

The flash uses 128-bit-wide accesses to reduce power. Write operations can be performed at the row level. A row is 512 bytes. Read operations are supported in both Low Power and Ultra-Low Power modes, however write operations may not be performed in Ultra-Low Power mode.

The flash controller has two caches, one for each CPU. Each cache is 8 KB, with 4-way set associativity.

### ■ SRAM

Up to 256 KB of SRAM is provided.. Power control and retention granularity is implemented in 32-KB blocks allowing the user to control the amount of memory retained in Deep Sleep. Memory is not retained in Hibernate mode.

### ■ ROM

The 64-KB ROM, also referred to as the supervisory ROM (SROM), provides code ([ROM Boot](#)) for several system functions. The ROM contains device initialization, flash write, security, eFuse programming, and other system-level routines. ROM code is executed only by the CM0+ CPU, in protection context 0. A system function can be initiated by either CPU, or through the DAP. This causes an NMI in CM0+, which causes CM0+ to execute the system function.

### ■ eFuse

A one-time-programmable (OTP) eFuse array consists of 1024 bits, of which 648 are reserved for system use such as die ID, device ID, initial trim settings, device life cycle, and security settings. The remaining bits are available for storing security key information, hash values, unique IDs or similar custom content.

Each fuse is individually programmed; once programmed (or “blown”), its state cannot be changed. Blowing a fuse transitions it from the default state of 0 to 1. To program an eFuse,  $V_{DDIO0}$  must be at 2.5 V  $\pm$ 5%, at 14 mA.

Because blowing an eFuse is an irreversible process, programming is recommended only in mass production under controlled factory conditions. For more information, see [PSoC 6 MCU Programming Specifications](#).

### Boot Code

Two blocks of code, [ROM Boot](#) and [Flash Boot](#), are pre-programmed into the device and work together to provide device startup and configuration, basic security features, life-cycle stage management and other system functions.

### ■ ROM Boot

On a device reset, the boot code in ROM is the first code to execute. This code performs the following:

- Integrity checks of flash boot code
  - Device trim setting (calibration)
  - Setting the device protection units
  - Setting device access restrictions for “Secure” lifecycle states
- ROM cannot be changed and acts as the root of trust in a secured system.

### ■ Flash Boot

Flash boot is firmware stored in SFlash that ensures that only a validated application may run on the device. It also ensures that the firmware image has not been modified, such as by a malicious third party.

Flash boot:

- Is validated by ROM Boot
- Runs after ROM Boot and before the user application
- Enables system calls
- Configures the Debug Access Port
- Launches the user application in the CM0+ (CM4 for single-CPU devices).

If the user application cannot be validated, then flash boot ensures that the device is transitioned into a safe state.

### Memory Map

Both CPUs have a fixed address map, with shared access to memory and peripherals. The 32-bit (4 GB) address space is divided into the Arm-defined regions shown in [Table 8](#). Note that code can be executed from the Code and External RAM regions.

**Table 3. Address Map for CM4 and CM0+**

Address Range	Name	Use
0x0000 0000 – 0x1FFF FFFF	Code	Program code region. Data can also be placed here. It includes the exception vector table, which starts at address 0.
0x2000 0000 – 0x3FFF FFFF	SRAM	Data region. This region is not supported in PSoC 6.
0x4000 0000 – 0x5FFF FFFF	Peripheral	All peripheral registers. Code cannot be executed from this region. CM4 bit-band in this region is not supported in PSoC 6.
0x6000 0000 – 0x9FFF FFFF	External RAM	SMIF or Quad SPI, (see the <a href="#">Quad-SPI (QSPI)/Serial Memory Interface (SMIF)</a> section). Code can be executed from this region.
0xA000 0000 – 0xDFFF FFFF	External Device	Not used.
0xE000 0000 – 0xE00F FFFF	Private Peripheral Bus	Provides access to peripheral registers within the CPU core.
0xE010 0A000 – 0xFFFF FFFF	Device	Device-specific system registers.

The device memory map shown in [Table 4](#) applies to both CPUs. That is, the CPUs share access to all PSoC 6 MCU memory and peripheral registers.

**Table 4. Internal Memory Address Map for CM4 and CM0+**

Address Range	Memory Type	Size
0x0000 0000 – 0x0000 FFFF	ROM	64 KB
0x0800 0000 – 0x0803 FFFF	SRAM	Up to 256 KB
0x1000 0000 – 0x1007 FFFF	Application flash	Up to 512 KB
0x1400 0000 – 0x1400 7FFF	Auxiliary flash, can be used for EEPROM emulation	32 KB
0x1600 0000 – 0x1600 7FFF	Supervisory flash	32 KB

Note that PSoC 6 SRAM is located in the Arm Code region for both CPUs (see [Table 8](#)). There is no physical memory located in the CPUs' Arm SRAM regions.

## System Resources

### Power System

The power system provides assurance that voltage levels are as required for each respective mode and will either delay mode entry (on power-on reset (POR), for example) until voltage levels are as required for proper function or generate resets (brown-out detect (BOD)) when the power supply drops below specified levels. The design guarantees safe chip operation between power supply voltage dropping below specified levels (for example, below 1.7 V) and the reset occurring. There are no voltage sequencing requirements.

The  $V_{DD}$  supply (1.7 to 3.6 V) powers an on-chip buck regulator or a low-dropout regulator (LDO), selectable by the user. In addition, both the buck and the LDO offer a selectable (0.9 or 1.1 V) core operating voltage ( $V_{CCD}$ ). The selection lets users choose between two system power modes:

- System Low Power (LP) operates  $V_{CCD}$  at 1.1 V and offers high performance, with no restrictions on device configuration.
- System Ultra Low Power (ULP) operates  $V_{CCD}$  at 0.9 V for exceptional low power, but imposes limitations on clock speeds.

In addition, a backup domain adds an “always on” functionality using a separate power domain supplied by a backup supply ( $V_{BACKUP}$ ) such as a battery or supercapacitor.

It includes a real-time clock (RTC) with alarm feature, supported by a 32.768-kHz watch crystal oscillator (WCO), and power-management IC (PMIC) control. Refer to [Power Supply Considerations](#) for more details.

### Power Modes

PSoC 6 MCU can operate in four system and three CPU power modes. These modes are intended to minimize the average power consumption in an application. For more details on power modes and other power-saving configuration options, see the application note, [AN219528: PSoC 6 MCU Low-Power Modes and Power Reduction Techniques](#) and the [Architecture TRM, Power Modes](#) chapter.

Power modes supported by PSoC 6 MCUs, in order of decreasing power consumption, are:

- System Low Power (LP) – All peripherals and CPU power modes are available at maximum speed
- System Ultra Low Power (ULP) – All peripherals and CPU power modes are available, but with limited speed
- CPU Active – CPU is executing code in system LP or ULP mode

- CPU Sleep – CPU code execution is halted in system LP or ULP mode
- CPU Deep Sleep – CPU code execution is halted and system Deep Sleep is requested in system LP or ULP mode
- System Deep Sleep – Only low-frequency peripherals are available after both CPUs enter CPU Deep Sleep mode
- System Hibernate – Device and I/O states are frozen and the device resets on wakeup

CPU Active, Sleep, and Deep Sleep are standard Arm-defined power modes supported by the Arm CPU instruction set architecture (ISA). System LP, ULP, Deep Sleep and Hibernate modes are additional low-power modes supported by PSoC 6 MCU.

### Clock System

[Figure 15](#) shows that the clock system of this product line consists of the following:

- Internal main oscillator (IMO)
- Internal low-speed oscillator (ILO)
- Watch crystal oscillator (WCO)
- External MHz crystal oscillator (ECO)
- External clock input
- One phase locked-loop (PLL)
- One frequency-locked loop (FLL)

Clocks may be buffered and brought out to a pin on a Smart I/O port.

The default clocking when the application starts is CLK\_HF[0] being driven by the IMO and the FLL. CLK\_HF[0], clk\_fast, clk\_peri, and clk\_slow are all either 50 MHz (LP mode) or 25 MHz (ULP mode). All other clocks, including all peripheral clocks, are off.

#### Internal Main Oscillator (IMO)

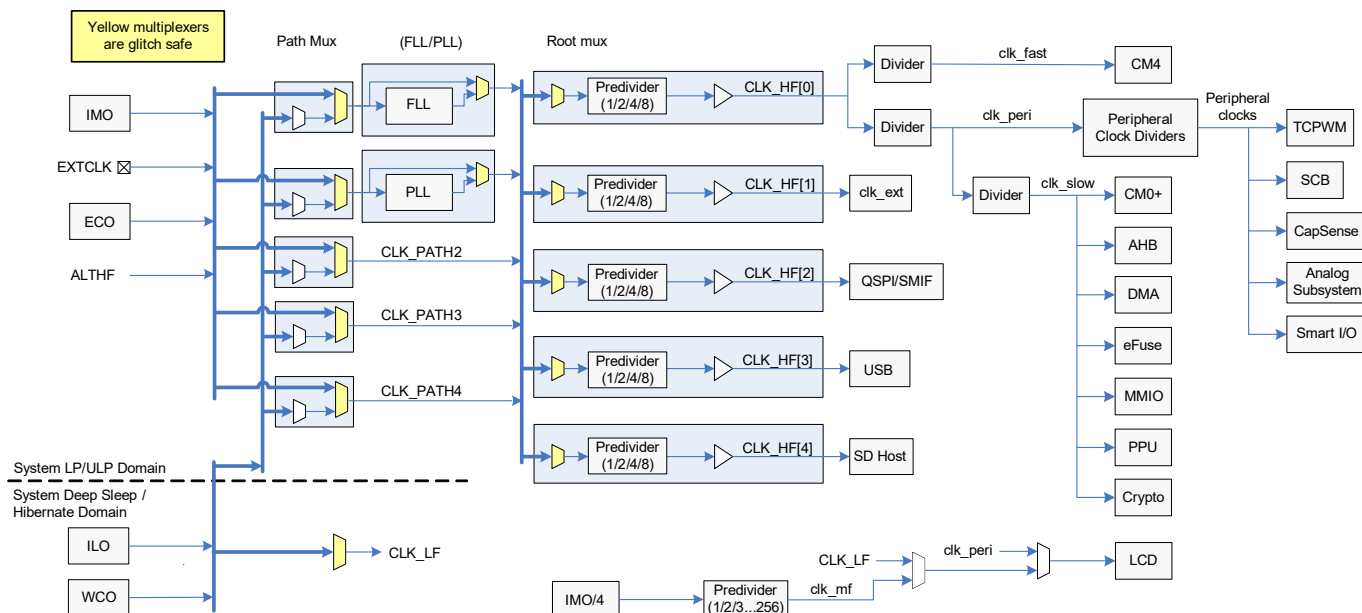
The IMO is the primary source of internal clocking. It is trimmed at the factory to achieve the specified accuracy. The IMO frequency is 8 MHz and tolerance is  $\pm 2\%$ .

The IMO can operate in system Deep Sleep mode to drive the LCD block for better contrast (and higher power) than is possible with the 32-kHz mode.

#### Internal Low-Speed Oscillator (ILO)

The ILO is a very low power oscillator, nominally 32 kHz, which operates in all power modes. The ILO can be calibrated against a higher accuracy clock for better accuracy.

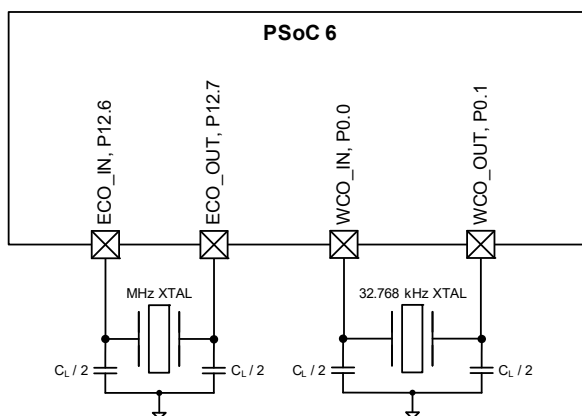
**Figure 3. Clocking Diagram**



### External Crystal Oscillators

Figure 4 shows all of the external crystal oscillator circuits for this product line. The component values shown are typical; check the [ECO Specifications](#) for the crystal values, and the crystal datasheet for the load capacitor values. The ECO and WCO require balanced external load capacitors. For more information, see the TRM and [AN218241, PSoC 6 MCU Hardware Design Considerations](#).

**Figure 4. Oscillator Circuits**



If the ECO is used, note that its performance is affected by GPIO switching noise. GPIO ports should be used as [Table 5](#) shows. See also [Table 6](#) for additional restrictions for general analog subsystem use.

**Table 5. ECO Usage Guidelines**

Ports	Max Frequency	Drive Strength for $V_{DD} \leq 2.7V$	Drive Strength for $V_{DD} \leq 2.7V$
Port 11	60 MHz for SMIF (QSPI)	DRIVE_SEL 2	DRIVE_SEL 3
Ports 12 and 13	Slow slew rate setting	No restrictions	No restrictions

### Watchdog Timers (WDT, MCWDT)

PSoC 6 MCU has one WDT and two multi-counter WDTs (MCWDT). The WDT has a 16-bit free-running counter. Each MCWDT has two 16-bit counters and one 32-bit counter, with multiple operating modes. All of the 16-bit counters can generate a watchdog device reset. All of the counters can generate an interrupt on a match event.

The WDT is clocked by the ILO. It can generate interrupt/wakeup in system LP/ULP, Deep Sleep, and Hibernate power modes. The MCWDTs are clocked by LFCLK (ILO or WCO). It can generate periodic interrupt/wakeup in system LP/ULP and Deep Sleep power modes.

### Clock Dividers

Integer and fractional clock dividers are provided for peripheral use and timing purposes. There are:

- Four 8-bit clock dividers
- Eight 16-bit integer clock dividers
- Two 16.5-bit fractional clock dividers
- One 24.5-bit fractional clock divider

### Trigger Routing

PSoC 6 MCU contains a trigger multiplexer block. This is a collection of digital multiplexers and switches that are used for routing trigger signals between peripheral blocks and between GPIOs and peripheral blocks.

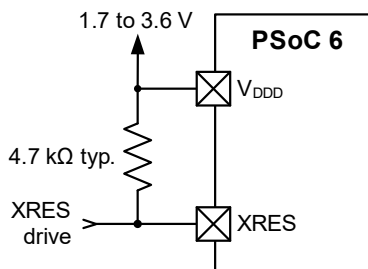
There are two types of trigger routing. Trigger multiplexers have reconfigurability in the source and destination. There are also hardwired switches called “one-to-one triggers”, which connect a specific source to a destination. The user can enable or disable the route.

### Reset

PSoC 6 MCU can be reset from a variety of sources:

- Power-on reset (POR) to hold the device in reset while the power supply ramps up to the level required for the device to function properly. POR activates automatically at power-up.
- Brown-out detect (BOD) reset to monitor the digital voltage supply  $V_{DD}$  and generate a reset if  $V_{DD}$  falls below the minimum required logic operating voltage.
- External reset dedicated pin (XRES) to reset the device using an external source. The XRES pin is active low. It can be connected either to a pull-up resistor to  $V_{DD}$ , or to an active drive circuit, as Figure 5 shows. If a pull-up resistor is used, select its value to minimize current draw when the pin is pulled low; 4.7 k $\Omega$  is typical.

**Figure 5. XRES Connection Diagram**



- Watchdog timer (WDT or MCWDT) to reset the device if firmware fails to service it within a specified timeout period.
- Software-initiated reset to reset the device on demand using firmware.
- Logic-protection fault can trigger an interrupt or reset the device if unauthorized operating conditions occur; for example, reaching a debug breakpoint while executing privileged code.
- Hibernate wakeup reset to bring the device out of the system Hibernate power mode.

Reset events are asynchronous and guarantee reversion to a known state. Some of the reset sources are recorded in a register, which is retained through reset and allows software to determine the cause of the reset.

### Programmable Analog Subsystems

#### 12-bit SAR ADC

The 12-bit, 2-Msps SAR ADC can operate at a maximum clock rate of 36 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion. One of three internal reference voltages may be used for the ADC reference voltage. The references are,  $V_{DD}$ ,  $V_{DD}/2$ , and  $V_{REF}$  (nominally 1.2 V and trimmed to  $\pm 1\%$ ). An external reference may also be used, by either driving the VREF pin or routing an external reference to GPIO pin P9.3. These reference options allow ratio-metric readings or absolute readings at the accuracy of the reference used. The input range of the ADC is the full supply voltage between  $V_{SS}$  and  $V_{DDA}/V_{DDIOA}$ . The SAR ADC may be configured with a mix of single-ended and differential signals in the same configuration.

The SAR ADC’s sample-and-hold (S/H) aperture is programmable to allow sufficient time for signals with a high impedance to settle sufficiently, if required. System performance is 65 dB for true 12-bit precision provided appropriate references are used and system noise levels permit it. To improve performance in noisy conditions, an external bypass capacitor for the internal reference amplifier (through the fixed “VREF” pin), may be added.

The SAR is connected to a fixed set of pins through an input multiplexer. The multiplexer cycles through the selected channels autonomously (sequencer scan) and does so with zero switching overhead (that is, the aggregate sampling bandwidth is equal to 2 Msps whether it is for a single channel or distributed over several channels). The result of each channel is buffered, so that an interrupt may be triggered only when a full scan of all channels is complete. Also, a pair of range registers can be set to detect and cause an interrupt if an input exceeds a minimum and/or maximum value. This allows fast detection of out-of-range values without having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software. The SAR can also be connected, under firmware control, to most other GPIO pins via the Analog Multiplexer Bus (AMUXBUS). The SAR is not available in system Deep Sleep and Hibernate modes as it requires a high-speed clock (up to 36 MHz). The SAR operating range is 1.71 to 3.6 V.

#### Temperature Sensor

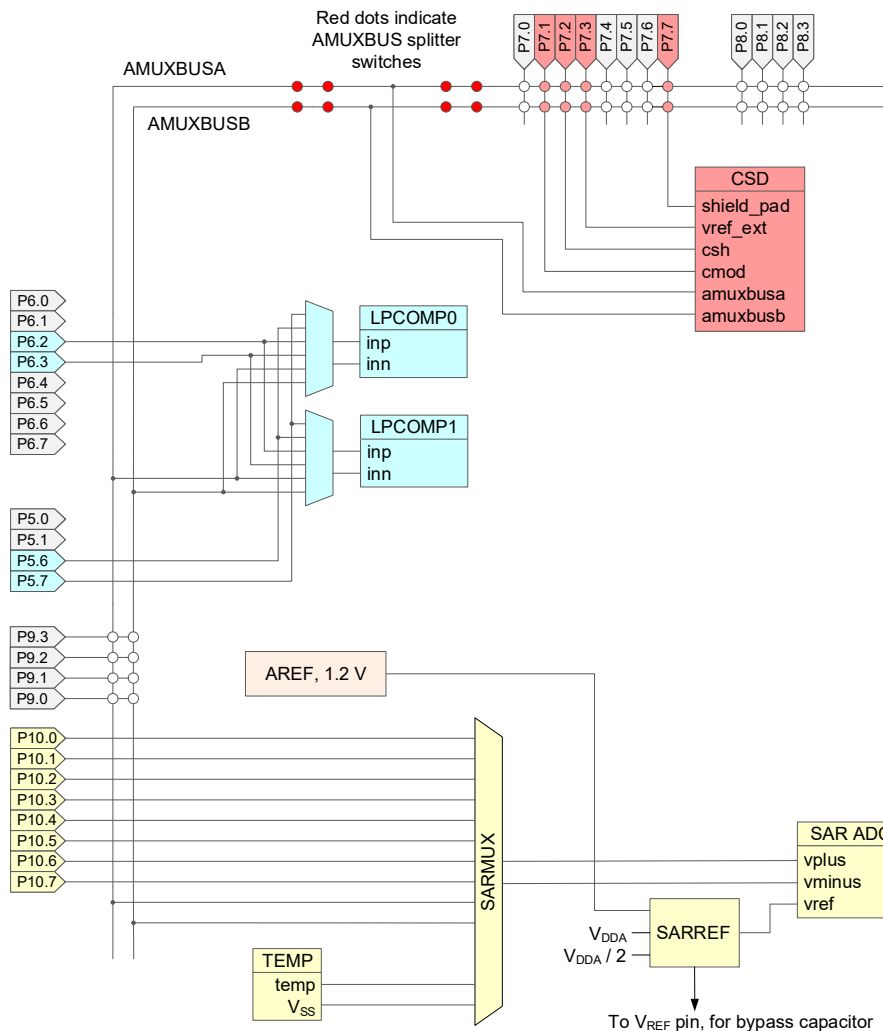
An on-chip temperature sensor is part of the SAR and may be scanned by the SAR ADC. It consists of a diode, which is biased by a current source that can be disabled to save power. The temperature sensor may be connected directly to the SAR ADC as one of the measurement channels. The ADC digitizes the temperature sensor’s output and a Cypress-supplied software function may be used to convert the reading to temperature which includes calibration and linearization.

#### Low-Power Comparators

Two low-power comparators are provided, which can operate in all power modes. This allows other analog system resources to be disabled while retaining the ability to monitor external voltage levels during system Deep Sleep and Hibernate modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode (Hibernate) where the system wake-up circuit is activated by a comparator-switch event.

Figure 6 shows an overview of the analog subsystem. This diagram is a high-level abstraction. See the TRM for detailed connectivity information.

**Figure 6. Analog Subsystem**



## Programmable Digital

### Smart I/O

Smart I/O is a programmable logic fabric that enables Boolean operations on signals traveling from device internal resources to the GPIO pins or on signals traveling into the device from external sources. A Smart I/O block sits between the GPIO pins and the high-speed I/O matrix (HSIOM) and is dedicated to a single port.

There are two Smart I/O blocks: one on Port 8 and one on Port 9. When Smart I/O is not enabled, all signals on Port 8 and Port 9 bypass the Smart I/O hardware.

Smart I/O supports:

- System Deep Sleep operation
- Boolean operations without CPU intervention
- Asynchronous or synchronous (clocked) operation

Each Smart I/O block contains a data unit (DU) and eight lookup tables (LUTs).

The DU:

- Performs unique functions based on a selectable opcode.
- Can source input signals from internal resources, the GPIO port, or a value in the DU register.

Each LUT:

- Has three selectable input sources. The input signals may be sourced from another LUT, an internal resource, an external signal from a GPIO pin, or from the DU.
- Acts as a programmable Boolean logic table.
- Can be synchronous or asynchronous.

## Fixed-Function Digital

### Timer/Counter/Pulse-width Modulator (TCPWM)

- The TCPWM supports the following operational modes:
  - Timer-counter with compare
  - Timer-counter with capture
  - Quadrature decoding
  - Pulse width modulation (PWM)
  - Pseudo-random PWM
  - PWM with dead time
- Up, down, and up/down counting modes.
- Clock prescaling (division by 1, 2, 4, ... 64, 128)
- Double buffering of compare/capture and period values
- Underflow, overflow, and capture/compare output signals
- Supports interrupt on:
  - Terminal count – Depends on the mode; typically occurs on overflow or underflow
  - Capture/compare – The count is captured to the capture register or the counter value equals the value in the compare register
- Complementary output for PWMs
- Selectable start, reload, stop, count, and capture event signals for each TCPWM; with rising edge, falling edge, both edges, and level trigger options. The TCPWM has a Kill input to force outputs to a predetermined state.

In this device there are:

- Four 32-bit TCPWMs
- Eight 16-bit TCPWMs

### Serial Communication Blocks (SCB)

This product line has seven SCBs:

- Six can implement either I<sup>2</sup>C, UART, or SPI.
- One SCB (SCB #6) can operate in system Deep Sleep mode with an external clock; this SCB can be either SPI slave or I<sup>2</sup>C slave.

**I<sup>2</sup>C Mode:** The SCB can implement a full multi-master and slave interface (it is capable of multimaster arbitration). This block can operate at speeds of up to 1 Mbps (Fast Mode Plus). It also supports EZI<sup>2</sup>C, which creates a mailbox address range and effectively reduces I<sup>2</sup>C communication to reading from and writing to an array in memory. The SCB supports a 256-byte FIFO for receive and transmit.

The I<sup>2</sup>C peripheral is compatible with I<sup>2</sup>C standard-mode, Fast Mode, and Fast Mode Plus devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual (UM10204). The I<sup>2</sup>C bus I/O is implemented with GPIO in open-drain modes.

**UART Mode:** This is a full-feature UART operating at up to 8 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows the addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. A 256-byte FIFO allows much greater CPU service latencies to be tolerated.

**SPI Mode:** The SPI mode supports full Motorola SPI, TI Secure Simple Pairing (SSP) (essentially adds a start pulse that is used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block supports an EZSPI mode in which the data interchange is reduced to reading and writing an array in memory. The SPI interface operates with a 25-MHz clock.

### USB Full-Speed Device Interface

This product line incorporates a full-speed USB device interface. The device can have up to eight endpoints. A 512-byte SRAM buffer is provided and DMA is supported.

**Note:** If the USB pins are not used, connect V<sub>DDUSB</sub> to ground and leave the P14.0/USBDP and P14.1/USBDM pins unconnected.

### Quad-SPI/Serial Memory Interface (SMIF)

A serial memory interface is provided, running at up to 80 MHz. It supports single, dual, and quad SPI configurations, and supports up to four external memory devices. It supports two modes of operation:

- Memory-mapped I/O (MMIO), a command mode interface that provides data access via registers and FIFOs
- Execute in Place (XIP), in which AHB reads and writes are directly translated to SPI read and write transfers.

In XIP mode, the external memory is mapped into the PSoc 6 MCU internal address space, enabling code execution directly from the external memory. To improve performance, a 4-KB cache is included. XIP mode also supports AES-128 on-the-fly encryption and decryption, enabling secured storage and access of code and data in the external memory.

### LCD

This block drives LCD commons and segments; routing is available to most of the GPIOs. One to eight of the GPIOs must be used for commons, the rest can be used for segments.

The LCD block has two modes of operation: high speed (8 MHz) and low speed (32 kHz). Both modes operate in system LP, ULP, and Deep Sleep modes, however the low-speed mode operates with reduced contrast in system Deep Sleep mode. The 8-MHz IMO is available in system Deep Sleep mode, and can be used to generate a clock for the LCD block. Review the number of common and segment lines, viewing angle requirements, and prototype performance, and then select the appropriate LCD clock frequency before using system Deep Sleep mode.

### SD Host Controller

This product line contains one Secure Digital (SD) host controller. It provides communication with IoT connectivity devices such as Bluetooth, Bluetooth Low-Energy and WiFi radios, as well as combination devices. The controller also supports embedded MultiMediaCards (eMMC) and Secure Digital (SD) cards.

Several bus speed modes under the SD specification are supported:

- DS (default speed)
- HS (high speed)
- SDR12 (single data rate)
- SDR25

- SDR50
- DDR50 (double data rate)

For eMMC, the supported modes are:

- BWC (backward compatibility)
- SDR

Maximum clock restrictions and capacitive loads apply to some modes, and are also dependent on system power mode (LP/ULP). Refer to the [SD Host Controller and eMMC Specifications](#) for details.

The SD Host Controller complies with the following standards. Refer to the specifications documents for more information on the protocol and operations.

- SD Specifications Part 1 Physical Layer Specification Version 6.00, supporting card capacities for SDSC (up to 2 GB), SDHC (up to 32 GB) and SDXC (up to 2 TB).
- SD Specifications Part A2 SD Host Controller Standard Specification Version 4.20
- SD Specifications Part E1 SDIO Specifications Version 4.10
- Embedded Multi-Media Card (eMMC) Electrical Standard 5.1

The SD host controller is configured as a master. To be fully compatible with features provided in the driver software for speed and efficiency, it supports advanced DMA version 3 (ADMA3), defined by the SDIO standard, and has a 1 KB RX/TX FIFO allowing double buffering of 512-byte blocks.

### CAN FD Block

This product line has one CAN FD block for industrial and automotive applications. The block includes Time-Stamp support and has a 4-KB message RAM. FD Data rates of up to 5 Mbps are supported. DMA transfers are supported.

### GPIO

This product line has up to 64 GPIOs, which implement the following:

- Eight drive strength modes:
  - Analog input mode (input and output buffers disabled)
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down

- Open drain with strong pull-down
- Open drain with strong pull-up
- Strong pull-up with strong pull-down
- Weak pull-up with weak pull-down

- Input threshold select (CMOS or LVTTL)
- Hold mode for latching previous state (used for retaining the I/O state in system Hibernate mode)
- Selectable slew rates for dV/dt-related noise control to improve EMI

The pins are organized in logical entities called ports, which are up to 8 pins in width. Data output and pin state registers store, respectively, the values to be driven on the pins and the input states of the pins.

Every pin can generate an interrupt if enabled; each port has an interrupt request (IRQ) associated with it.

The port 3 pins are capable of overvoltage-tolerant (OVT) operation, where the input voltage may be higher than  $V_{DD}$ . OVT pins are commonly used with I<sup>2</sup>C, to allow powering the chip OFF while maintaining a physical connection to an operating I<sup>2</sup>C bus without affecting its functionality.

GPIO pins can be ganged to source or sink higher values of current. GPIO pins, including OVT pins, may not be pulled up higher than the absolute maximum; see [Electrical Specifications](#).

During power-on and reset, the pins are forced to the analog input drive mode, with input and output buffers disabled, so as not to crowbar any inputs and/or cause excess turn-on current.

A multiplexing network known as the high-speed I/O matrix (HSIOM) is used to multiplex between various peripheral and analog signals that may connect to an I/O pin.

Analog performance is affected by GPIO switching noise. In order to get the best analog performance, the following frequency and drive mode constraints must be applied. The DRIVE\_SEL values (see [Table 6](#)) represent drive strengths (please see the [Architecture and Register TRMs](#) for further detail).

See also [Table 5](#) for additional restrictions for ECO use.

**Table 6. DRIVE\_SEL Values**

Ports	Max Frequency	Drive Strength for $V_{DD} \leq 2.7 V$	Drive Strength for $V_{DD} > 2.7 V$
Ports 0, 1	8 MHz	DRIVE_SEL 2	DRIVE_SEL 3
Port 2	50 MHz	DRIVE_SEL 1	DRIVE_SEL 2
Ports 3 to 10	16 MHz; 25 MHz for SPI	DRIVE_SEL 2	DRIVE_SEL 3
Ports 11 to 12	80 MHz for SMIF (QSPI).	DRIVE_SEL 1	DRIVE_SEL 2
Ports 9 and 10	Slow slew rate setting for TQFP Packages for ADC performance	No restrictions	No restrictions

## Special-Function Peripherals

### CapSense Subsystem

CapSense is supported in PSoC 6 MCU through a CapSense sigma-delta (CSD) hardware block. It is designed for high-sensitivity self-capacitance and mutual-capacitance measurements, and is specifically built for user interface solutions.

In addition to CapSense, the CSD hardware block supports three general-purpose functions. These are available when CapSense is not being used. Alternatively, two or more functions can be time-multiplexed in an application under firmware control. The four functions supported by the CSD hardware block are:

- CapSense
- 10-bit ADC
- Programmable current sources (IDAC)
- Comparator

### CapSense

Capacitive touch sensors are designed for user interfaces that rely on human body capacitance to detect the presence of a finger on or near a sensor. Cypress CapSense solutions bring elegant, reliable, and simple capacitive touch sensing functions to applications including IoT, industrial, automotive, and home appliances.

The Cypress-proprietary CapSense technology offers the following features:

- Best-in-class signal-to-noise ratio (SNR) and robust sensing under harsh and noisy conditions
- Self-capacitance (CSD) and mutual-capacitance (CSX) sensing methods
- Support for various widgets, including buttons, matrix buttons, sliders, touchpads, and proximity sensors
- High-performance sensing across a variety of materials
- Best-in-class liquid tolerance
- SmartSense™ auto-tuning technology that helps avoid complex manual tuning processes
- Superior immunity against external noise
- Spread-spectrum clocks for low radiated emissions
- Gesture and built-in self-test libraries
- Ultra-low power consumption
- An integrated graphical CapSense tuner for real-time tuning, testing, and debugging

### ADC

The CapSense subsystem slope ADC offers the following features:

- Selectable 8- or 10-bit resolution
- Selectable input range: GND to  $V_{REF}$  and GND to  $V_{DDA}$  on any GPIO input
- Measurement of  $V_{DDA}$  against an internal reference without the use of GPIO or external components

### IDAC

The CSD block has two programmable current sources, which offer the following features:

- 7-bit resolution
- Sink and source current modes
- A current source programmable from 37.5 nA to 609  $\mu$ A
- Two IDACs that can be used in parallel to form one 8-bit IDAC

### Comparator

The CapSense subsystem comparator operates in the system Low Power and Ultra-Low Power modes. The inverting input is connected to an internal programmable reference voltage and the non-inverting input can be connected to any GPIO via the AMUXBUS.

### CapSense Hardware Subsystem

Figure 7 shows the high-level hardware overview of the CapSense subsystem, which includes a delta sigma converter, internal clock dividers, a shield driver, and two programmable current sources.

The inputs are managed through analog multiplexed buses (AMUXBUS A/B). The input and output of all functions offered by the CSD block can be provided on any GPIO or on a group of GPIOs under software control, with the exception of the comparator output and external capacitors that use dedicated GPIOs.

Self-capacitance is supported by the CSD block using AMUXBUS A, an external modulator capacitor, and a GPIO for each sensor. There is a shield electrode (optional) for self-capacitance sensing. This is supported using AMUXBUS B and an optional external shield tank capacitor (to increase the drive capability of the shield driver) should this be required. Mutual-capacitance is supported by the CSD block using AMUXBUS A, two external integrated capacitors, and a GPIO for transmit and receive electrodes.

The ADC does not require an external component. Any GPIO that can be connected to AMUXBUS A can be an input to the ADC under software control. The ADC can accept  $V_{DDA}$  as an input without needing GPIOs (for applications such as battery voltage measurement).

The two programmable current sources (IDACs) in general-purpose mode can be connected to AMUXBUS A or B. They can therefore connect to any GPIO pin. The comparator resides in the delta-sigma converter. The comparator inverting input can be connected to the reference. Both comparator inputs can be connected to any GPIO using AMUXBUS B; see Figure 6. The reference has a direct connection to a dedicated GPIO; see Table 9.

The CSD block can operate in active and sleep CPU power modes, and seamlessly transition between system LP and ULP modes. It can be powered down in system Deep Sleep and Hibernate modes. Upon wakeup from Hibernate mode, the CSD block requires re-initialization. However, operation can be resumed without re-initialization upon exit from Deep Sleep mode, under firmware control.

Figure 7. CapSense Hardware Subsystem

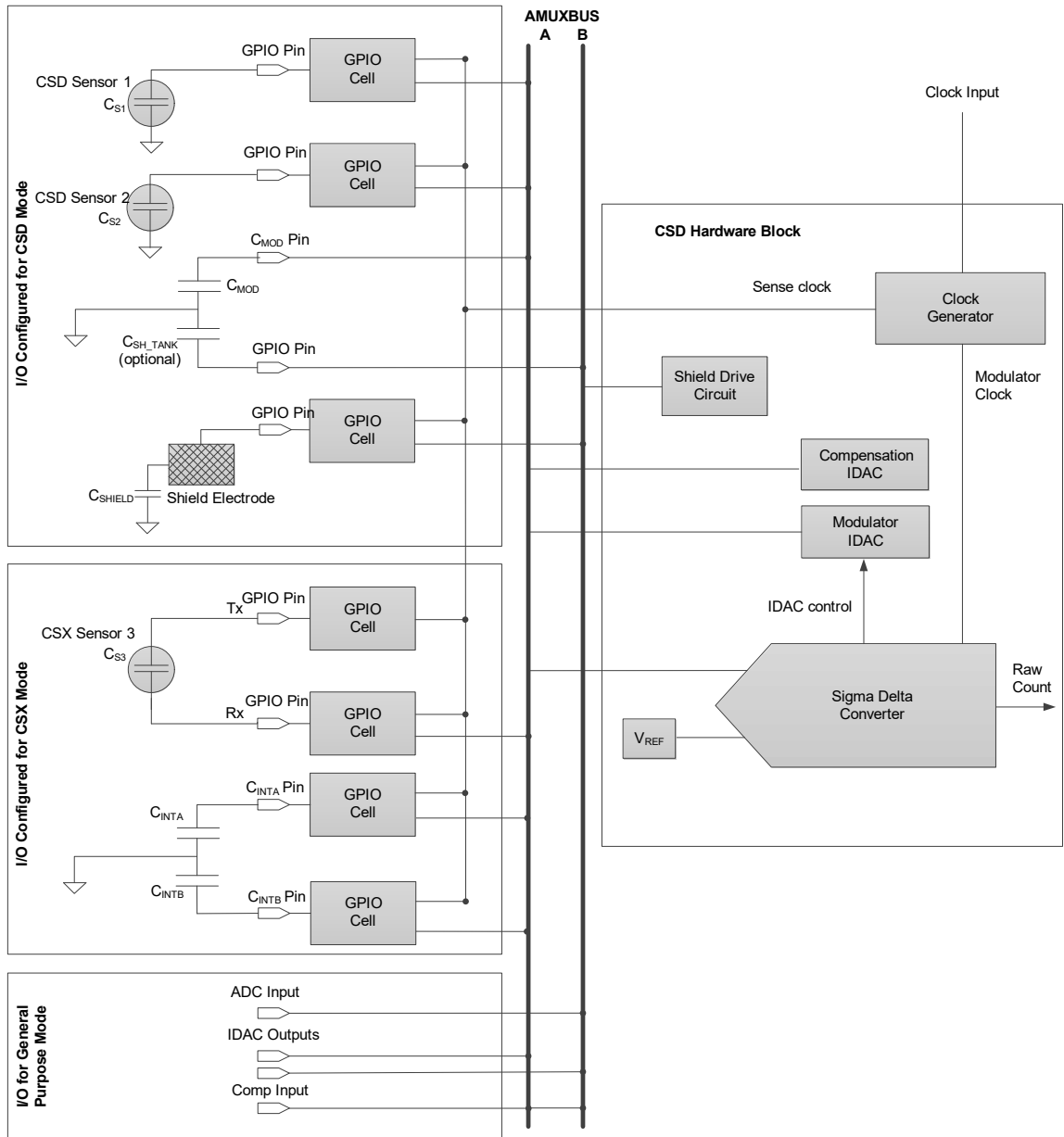


Figure 18 shows the high-level software overview. Cypress provides middleware libraries for [CapSense](#), [ADC](#), and [IDAC](#) on GitHub to enable quick integration. The Board Support Package for any kit with CapSense capabilities automatically includes the CapSense library in any application that uses the BSP.

User applications interact only with middleware to implement functions of the CSD block. The middleware interacts with underlying drivers to access hardware as necessary. The CSD driver facilitates time-multiplexing of the CSD hardware if more than one piece of CSD-related middleware is present in a project. It prevents access conflicts in this case.

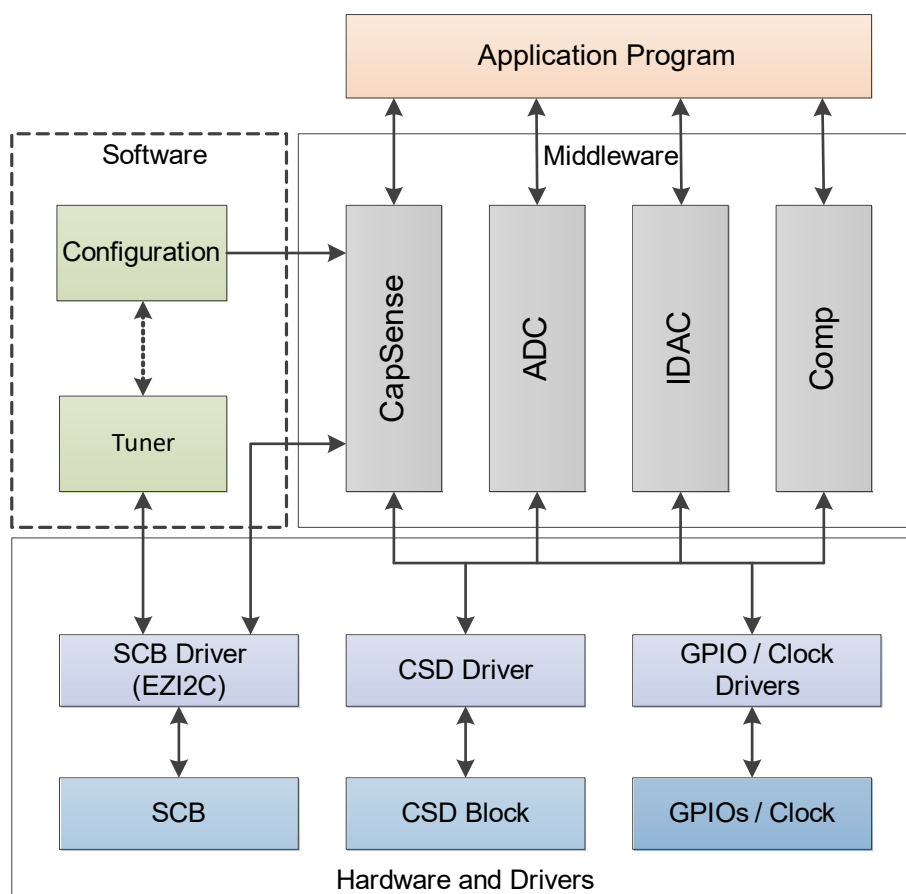
ModusToolbox Software provides a CapSense configurator to enable fast library configuration. It also provides a tuner for performance evaluation and real-time tuning of the system. The tuner requires an EZI2C communication interface in the application to enable real-time tuning capability. The tuner can update configuration parameters directly in the device as well as in the configurator.

CapSense and ADC middleware use the CSD interrupt to implement non-blocking sensing and A-to-D conversion. Therefore, interrupt service routines are a defined part of the middleware, which must be initialized by the application. Middleware and drivers can operate on either CPU. Cypress recommends using the middleware only in one CPU. If both CPUs must access the CSD driver, memory access should be managed in the application.

Refer to [AN85951: PSoC 4 and PSoC 6 MCU CapSense Design Guide](#) for more details on CSX sensing, CSD sensing, shield electrode usage and its benefits, and capacitive system design guidelines.

Refer to the API reference guides for [CapSense](#), [ADC](#), and [IDAC](#) available on GitHub.

**Figure 8. CapSense Software/Firmware Subsystem**



## Pinouts

**Note:** The CY8C62x5 [datasheet web page](#) contains a spreadsheet with a consolidated list of pinouts and pin alternate functions with HSIOM mapping.

GPIO ports are powered by  $V_{DDx}$  pins as follows:

- P0:  $V_{BACKUP}$
- P2, P3:  $V_{DDIO2}$
- P5, P6, P7, P8:  $V_{DDIO1}$
- P9, P10:  $V_{DDIOA}$ ,  $V_{DDA}$  ( $V_{DDIOA}$ , when present, and  $V_{DDA}$  must be connected together on the PCB)
- P11, P12:  $V_{DDIO0}$
- P14:  $V_{DDUSB}$

**Table 7. Packages and Pin Information**

Pin	Packages		
	100-TQFP	68-QFN	49-WLCSP
$V_{DDD}$	2	68	C11
$V_{CCD}$	1, 100	67	A11
$V_{DDA}$	73	48	B2
$V_{DDIOA}$	53	36	–
$V_{DDIO0}$	91, 92	64	A9
$V_{DDIO1}$	51	35	G1
$V_{DDIO2}$	31	22	J7
$V_{BACKUP}$	6	1	–
$V_{DDUSB}$	20	11	–
$V_{SS}$	3, 4, 5, 13, 15, 18, 19, 33, 38, 49, 50, 54, 71, 72, 93, 94	GND PAD	B6, H6
$V_{DD\_NS}$	16	9	F10
$V_{IND1}$	17	10	G11
XRES	14	8	E11
$V_{REF}$	74	49	C3
P0.0	7	2	E9
P0.1	8	3	D10
P0.2	9	4	–
P0.3	10	5	–
P0.4	11	6	–
P0.5	12	7	–
P2.0	23	14	H10
P2.1	24	15	F8
P2.2	25	16	H8
P2.3	26	17	G9
P2.4	27	18	J11
P2.5	28	19	J9
P2.6	29	20	–
P2.7	30	21	–
P3.0	34	23	–

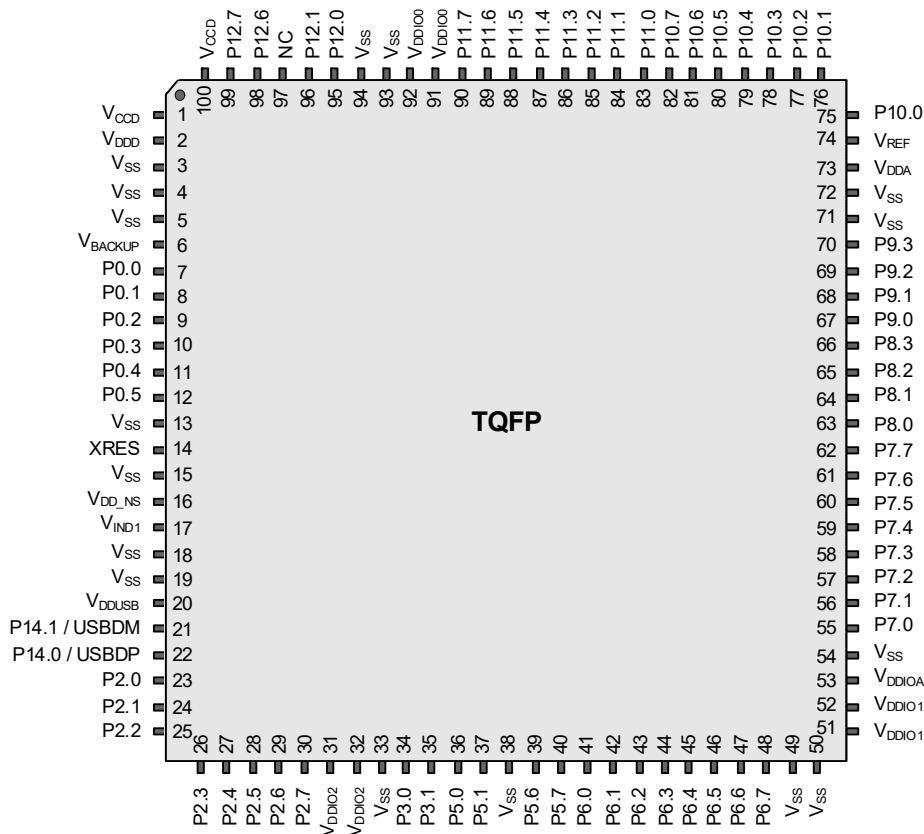
**Table 7. Packages and Pin Information** *(continued)*

Pin	Packages		
	100-TQFP	68-QFN	49-WLCSP
P3.1	35	24	–
P5.0	36	25	J5
P5.1	37	26	G7
P5.6	39	27	–
P5.7	40	28	–
P6.0	41	–	–
P6.1	42	–	–
P6.2	43	29	J3
P6.3	44	30	H4
P6.4	45	31	G5
P6.5	46	32	J1
P6.6	47	33	H2
P6.7	48	34	G3
P7.0	55	37	F6
P7.1	56	38	F4
P7.2	57	39	F2
P7.3	58	40	E3
P7.4	59	–	E1
P7.5	60	–	–
P7.6	61	–	–
P7.7	62	41	–
P8.0	63	42	–
P8.1	64	43	–
P8.2	65	–	–
P8.3	66	–	–
P9.0	67	44	D2
P9.1	68	45	E5
P9.2	69	46	E7
P9.3	70	47	C1
P10.0	75	50	D4
P10.1	76	51	A5
P10.2	77	52	B4
P10.3	78	53	A3
P10.4	79	54	C5
P10.5	80	55	D6
P10.6	81	–	–
P10.7	82	–	–
P11.0	83	56	–
P11.1	84	57	–
P11.2	85	58	C7
P11.3	86	59	A7
P11.4	87	60	D8

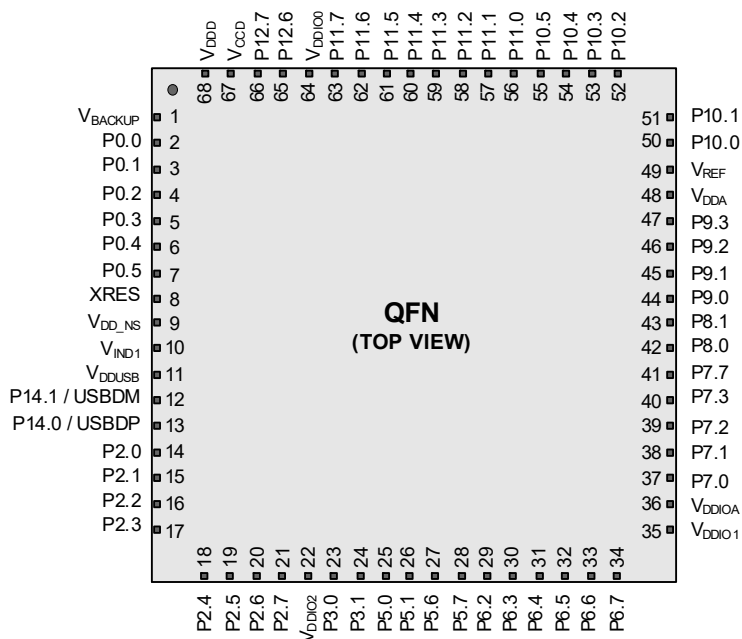
Table 7. Packages and Pin Information (continued)

Pin	Packages		
	100-TQFP	68-QFN	49-WLCSP
P11.5	88	61	B8
P11.6	89	62	C9
P11.7	90	63	B10
P12.0	95	-	-
P12.1	96	-	-
P12.6	98	65	-
P12.7	99	66	-
P14.0 / USBDP	22	13	-
P14.1 / USBDM	21	12	-
NC	97	-	-

Figure 9. Device Pinout for 100-TQFP Package



**Figure 10. Device Pinout for 68-QFN Package<sup>[1]</sup>**



**Note:** If the USB pins are not used, connect V<sub>DDUSB</sub> to ground and leave the P14.0/USB DP and P14.1/USB DM pins unconnected.

**Note**  
 1. The center pad on the QFN package should be connected to PCB ground relative to device VDDx for best mechanical, thermal, and electrical performance. For more information, see AN72845, Design Guidelines for QFN Devices.

Each port pin has multiple alternate functions. These are defined in Table 8. The columns ACT #x and DS #y denote active (System) and deactive (System) functions respectively.

The notation for a signal is of the form IPName[x].signal\_name[u].y.

IPName = Name of the block (such as tcpwm), x = Unique instance of the IP, Signal\_name = Name of the signal, u = Signal number of a particular signal name, y = Designates copies of the signal name.

For example, the name tcpwm[0].line\_comp[3]:4 indicates that this is instance 0 of a tcpwm block, the signal is line\_comp # 3 (copy) and the fourth occurrence (copy) of the signal. Signal copies are provided to allow flexibility in routing and to maximize use of on-chip resources.

**Table 8. Multiple Alternate Functions**

Port/Pin	ACT #0	ACT #1	ACT #2	ACT #3	DS #2	DS #3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #10	ACT #12	ACT #
P0.0	tcpwm[0].line[0]:0	tcpwm[1].line[0]:0	csd.csd_tx:0	csd.csd_tx_n:1			srss.ext_clk:0				scb[0].spi_select:0			peri.tr_io_input[0]:0	
P0.1	tcpwm[0].line_comp[0]:0	tcpwm[1].line_comp[0]:0	csd.csd_tx:1	csd.csd_tx_n:1							scb[0].spi_select:0			peri.tr_io_input[1]:0	
P0.2	tcpwm[0].line[1]:0	tcpwm[1].line[1]:0	csd.csd_tx:2	csd.csd_tx_n:2					scb[0].ua_rt_rx:0	scb[0].i2c_sci:0	scb[0].spi_mosi:0				
P0.3	tcpwm[0].line_comp[1]:0	tcpwm[1].line_comp[1]:0	csd.csd_tx:3	csd.csd_tx_n:3					scb[0].ua_rt_tx:0	scb[0].i2c_sda:0	scb[0].spi_miso:0				
P0.4	tcpwm[0].line[2]:0	tcpwm[1].line[2]:0	csd.csd_tx:4	csd.csd_tx_n:4					scb[0].ua_rt_rts:0		scb[0].spi_clk:0			peri.tr_io_input[2]:0	peri.tr_output:0:2
P0.5	tcpwm[0].line_comp[2]:0	tcpwm[1].line_comp[2]:0	csd.csd_tx:5	csd.csd_tx_n:5			srss.ext_clk:1		scb[0].ua_rt_cts:0		scb[0].spi_select:0			peri.tr_io_input[3]:0	peri.tr_output:1:2
P2.0	tcpwm[0].line[3]:0	tcpwm[1].line[3]:0	csd.csd_tx:6	csd.csd_tx_n:6					scb[1].ua_rt_rx:0	scb[1].i2c_sci:0	scb[1].spi_mosi:0			peri.tr_io_input[4]:0	
P2.1	tcpwm[0].line_comp[3]:0	tcpwm[1].line_comp[3]:0	csd.csd_tx:7	csd.csd_tx_n:7					scb[1].ua_rt_tx:0	scb[1].i2c_sda:0	scb[1].spi_miso:0			peri.tr_io_input[5]:0	
P2.2	tcpwm[0].line[4]:1	tcpwm[1].line[4]:0	csd.csd_tx:8	csd.csd_tx_n:8					scb[1].ua_rt_rts:0		scb[1].spi_clk:0				
P2.3	tcpwm[0].line_comp[4]:1	tcpwm[1].line_comp[4]:0	csd.csd_tx:9	csd.csd_tx_n:9					scb[1].ua_rt_cts:0		scb[1].spi_select:0				
P2.4	tcpwm[0].line[5]:1	tcpwm[1].line[5]:0	csd.csd_tx:10	csd.csd_tx_n:10							scb[1].spi_select:0				

Table 8. Multiple Alternate Functions (continued)

Port/Pin	ACT #0	ACT #1	ACT #2	ACT #3	DS #2	DS #3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #10	ACT #12	ACT #
P2.5	tcpwm[0].line_comp[1]:1	tcpwm[1].line_comp[5]:0	csd.csd_tx:11	csd.csd_tx_n:11							scb[1].spi_select:0				
P2.6	tcpwm[0].line[2]:1	tcpwm[1].line[6]:0	csd.csd_tx:12	csd.csd_tx_n:12							scb[1].spi_select:0			peri.tr_io_input[8]:0	
P2.7	tcpwm[0].line_comp[2]:1	tcpwm[1].line_comp[6]:0	csd.csd_tx:13	csd.csd_tx_n:13										peri.tr_io_input[9]:0	
P3.0	tcpwm[0].line[3]:1	tcpwm[1].line[7]:0	csd.csd_tx:14	csd.csd_tx_n:14					scb[2].uart_rx:1	scb[2].i2c_sci:1	scb[2].spi_mosi:1			peri.tr_io_input[6]:0	
P3.1	tcpwm[0].line_comp[3]:1	tcpwm[1].line_comp[7]:0	csd.csd_tx:15	csd.csd_tx_n:15					scb[2].uart_tx:1	scb[2].i2c_sda:1	scb[2].spi_miso:1			peri.tr_io_input[7]:0	
P5.0	tcpwm[0].line[0]:2	tcpwm[1].line[0]:1	csd.csd_tx:16	csd.csd_tx_n:16					scb[5].uart_rx:1	scb[5].i2c_sci:1	scb[5].spi_mosi:1			peri.tr_io_input[10]:0	
P5.1	tcpwm[0].line_comp[0]:2	tcpwm[1].line_comp[0]:1	csd.csd_tx:17	csd.csd_tx_n:17					scb[5].uart_tx:1	scb[5].i2c_sda:1	scb[5].spi_miso:1			peri.tr_io_input[11]:0	
P5.6	tcpwm[0].line[1]:2	tcpwm[1].line[1]:1	csd.csd_tx:18	csd.csd_tx_n:18											cpuss.uit_out_j
P5.7	tcpwm[0].line_comp[1]:2	tcpwm[1].line_comp[1]:1	csd.csd_tx:19	csd.csd_tx_n:19											cpuss.uit_out_j
P6.0	tcpwm[0].line[2]:2	tcpwm[1].line[2]:1	csd.csd_tx:20	csd.csd_tx_n:20					scb[3].uart_rx:0	scb[3].i2c_sci:0	scb[3].spi_mosi:0				
P6.1	tcpwm[0].line_comp[2]:2	tcpwm[1].line_comp[2]:1	csd.csd_tx:21	csd.csd_tx_n:21					scb[3].uart_tx:0	scb[3].i2c_sda:0	scb[3].spi_miso:0				
P6.2	tcpwm[0].line[3]:2	tcpwm[1].line[3]:1	csd.csd_tx:22	csd.csd_tx_n:22					scb[3].uart_rts:0		scb[3].spi_clk:0				
P6.3	tcpwm[0].line_comp[3]:2	tcpwm[1].line_comp[3]:1	csd.csd_tx:23	csd.csd_tx_n:23					scb[3].uart_cis:0		scb[3].spi_select:0				
P6.4	tcpwm[0].line[0]:3	tcpwm[1].line[4]:1	csd.csd_tx:24	csd.csd_tx_n:24	scb[6].i2c_sci:0									peri.tr_io_input[12]:0	peri.tr_io_output_1:1
P6.5	tcpwm[0].line_comp[0]:3	tcpwm[1].line_comp[4]:1	csd.csd_tx:25	csd.csd_tx_n:25	scb[6].i2c_sda:0									peri.tr_io_input[13]:0	peri.tr_io_output_1:1

Table 8. Multiple Alternate Functions (continued)

Port/Pin	ACT #0	ACT #1	ACT #2	ACT #3	DS #2	DS #3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #10	ACT #12	ACT #	
P6.6	tcpwm[0].line[1]:3	tcpwm[1].line[5]:1	csd.csd_tx:26	csd.csd_tx_n:26												
P6.7	tcpwm[0].line.comp[1]:3	tcpwm[1].line.comp[5]:1	csd.csd_tx:27	csd.csd_tx_n:27												
P7.0	tcpwm[0].line[2]:3	tcpwm[1].line[6]:1	csd.csd_tx:28	csd.csd_tx_n:28					scb[4].ua_rt_rx:1	scb[4].i2_c_sci:1	scb[4].spi_mosi:1			peri.tr_io_input[1-4]:0		
P7.1	tcpwm[0].line.comp[2]:3	tcpwm[1].line.comp[6]:1	csd.csd_tx:29	csd.csd_tx_n:29					scb[4].ua_rt_tx:1	scb[4].i2_c_sda:1	scb[4].spi_miso:1			peri.tr_io_input[1-5]:0		
P7.2	tcpwm[0].line[3]:3	tcpwm[1].line[7]:1	csd.csd_tx:30	csd.csd_tx_n:30					scb[4].ua_rt_rts:1		scb[4].spi_clk:1					
P7.3	tcpwm[0].line.comp[3]:3	tcpwm[1].line.comp[7]:1	csd.csd_tx:31	csd.csd_tx_n:31					scb[4].ua_rt_cts:1		scb[4].spi_select0:1					
P7.4	tcpwm[0].line[0]:4	tcpwm[1].line[0]:2	csd.csd_tx:32	csd.csd_tx_n:32							scb[4].spi_select1:1					
P7.5	tcpwm[0].line.comp[0]:4	tcpwm[1].line.comp[0]:2	csd.csd_tx:33	csd.csd_tx_n:33							scb[4].spi_select2:1					
P7.6	tcpwm[0].line[1]:4	tcpwm[1].line[1]:2	csd.csd_tx:34	csd.csd_tx_n:34							scb[4].spi_select3:1					
P7.7	tcpwm[0].line.comp[1]:4	tcpwm[1].line.comp[1]:2	csd.csd_tx:35	csd.csd_tx_n:35								cpuss.clk_fm_pump				
P8.0	tcpwm[0].line[2]:4	tcpwm[1].line[2]:2	csd.csd_tx:36	csd.csd_tx_n:36					scb[4].ua_rt_rx:0	scb[4].i2_c_sci:0	scb[4].spi_mosi:0			peri.tr_io_input[1-6]:0		
P8.1	tcpwm[0].line.comp[2]:4	tcpwm[1].line.comp[2]:2	csd.csd_tx:37	csd.csd_tx_n:37					scb[4].ua_rt_tx:0	scb[4].i2_c_sda:0	scb[4].spi_miso:0			peri.tr_io_input[1-7]:0		
P8.2	tcpwm[0].line[3]:4	tcpwm[1].line[3]:2	csd.csd_tx:38	csd.csd_tx_n:38				lpcomp.dsi_comp:0:0	scb[4].ua_rt_rts:0		scb[4].spi_clk:0					
P8.3	tcpwm[0].line.comp[3]:4	tcpwm[1].line.comp[3]:2	csd.csd_tx:39	csd.csd_tx_n:39			lpcomp.dsi_comp:1:0		scb[4].ua_rt_cts:0		scb[4].spi_select0:0					
P9.0	tcpwm[0].line[0]:5	tcpwm[1].line[4]:2	csd.csd_tx:40	csd.csd_tx_n:40					scb[2].ua_rt_rx:0	scb[2].i2_c_sci:0	scb[2].spi_mosi:0			peri.tr_io_input[1-8]:0		

Table 8. Multiple Alternate Functions (continued)

Port/Pin	ACT #0	ACT #1	ACT #2	ACT #3	DS #2	DS #3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #10	ACT #12	ACT #
P9.1	tcpwm[0].line_comp[0]:5	tcpwm[1].line_comp[4]:2	csd.csd_tx:41	csd.csd_tx_n:41					scb[2].uar_tx:0	scb[2].i2c_sda:0	scb[2].spi_miso:0			peri.tr_io_input[1-9]:0	
P9.2	tcpwm[0].line[1]:5	tcpwm[1].line[5]:2	csd.csd_tx:42	csd.csd_tx_n:42					scb[2].uar_rts:0		scb[2].spi_clk:0				
P9.3	tcpwm[0].line_comp[1]:5	tcpwm[1].line_comp[5]:2	csd.csd_tx:43	csd.csd_tx_n:43					scb[2].uar_rts_dis:0		scb[2].spi_select0:0				
P10.0	tcpwm[0].line[2]:5	tcpwm[1].line[6]:2	csd.csd_tx:44	csd.csd_tx_n:44					scb[1].uar_tx_rx:1	scb[1].i2c_sci:1	scb[1].spi_mosi:1			peri.tr_io_input[2-0]:0	
P10.1	tcpwm[0].line_comp[2]:5	tcpwm[1].line_comp[6]:2	csd.csd_tx:45	csd.csd_tx_n:45					scb[1].uar_tx:1	scb[1].i2c_sda:1	scb[1].spi_miso:1			peri.tr_io_input[2-1]:0	
P10.2	tcpwm[0].line[3]:5	tcpwm[1].line[7]:2	csd.csd_tx:46	csd.csd_tx_n:46					scb[1].uar_rts:1		scb[1].spi_clk:1				
P10.3	tcpwm[0].line_comp[3]:5	tcpwm[1].line_comp[7]:2	csd.csd_tx:47	csd.csd_tx_n:47					scb[1].uar_rts_dis:1		scb[1].spi_select0:1				
P10.4	tcpwm[0].line[0]:6	tcpwm[1].line[0]:3	csd.csd_tx:48	csd.csd_tx_n:48							scb[1].spi_select1:1				
P10.5	tcpwm[0].line_comp[0]:6	tcpwm[1].line_comp[0]:3	csd.csd_tx:49	csd.csd_tx_n:49							scb[1].spi_select2:1				
P10.6	tcpwm[0].line[1]:6	tcpwm[1].line[1]:3	csd.csd_tx:50	csd.csd_tx_n:50							scb[1].spi_select3:1				
P10.7	tcpwm[0].line_comp[1]:6	tcpwm[1].line_comp[1]:3	csd.csd_tx:51	csd.csd_tx_n:51											
P11.0	tcpwm[0].line[2]:6	tcpwm[1].line[2]:3	csd.csd_tx:52	csd.csd_tx_n:52				smif.spi_select2	scb[5].uar_tx:0	scb[5].i2c_sci:0	scb[5].spi_mosi:0			peri.tr_io_input[2-2]:0	
P11.1	tcpwm[0].line_comp[2]:6	tcpwm[1].line_comp[2]:3	csd.csd_tx:53	csd.csd_tx_n:53				smif.spi_select1	scb[5].uar_tx:0	scb[5].i2c_sda:0	scb[5].spi_miso:0			peri.tr_io_input[2-3]:0	
P11.2	tcpwm[0].line[3]:6	tcpwm[1].line[3]:3	csd.csd_tx:54	csd.csd_tx_n:54				smif.spi_select0	scb[5].uar_rts:0		scb[5].spi_clk:0				

Table 8. Multiple Alternate Functions (continued)

Port/Pin	ACT #0	ACT #1	ACT #2	ACT #3	DS #2	DS #3	ACT #4	ACT #5	ACT #6	ACT #7	ACT #8	ACT #9	ACT #10	ACT #12	ACT #n
P11.3	tcpwm[0].line_comp[3]:6	tcpwm[1].line_comp[3]:3	csd.csd_tx:55	csd.csd_tx_n:55				smif.spi_data3	sch[5].ua_r[_cls:0		sch[5].spi_select0:0				peri.tr_output_0]:0
P11.4	tcpwm[0].line[0]:7	tcpwm[1].line[4]:3	csd.csd_tx:56	csd.csd_tx_n:56				smif.spi_data2			sch[5].spi_select1:0				peri.tr_output_1]:0
P11.5	tcpwm[0].line_comp[0]:7	tcpwm[1].line_comp[4]:3	csd.csd_tx:57	csd.csd_tx_n:57				smif.spi_data1			sch[5].spi_select2:0				
P11.6	tcpwm[0].line[1]:7	tcpwm[1].line[5]:3	csd.csd_tx:58	csd.csd_tx_n:58				smif.spi_data0			sch[5].spi_select3:0				
P11.7	tcpwm[0].line_comp[1]:7	tcpwm[1].line_comp[5]:3	csd.csd_tx:59	csd.csd_tx_n:59				smif.spi_clk							
P12.0	tcpwm[0].line[2]:7	tcpwm[1].line[6]:3	csd.csd_tx:60	csd.csd_tx_n:60	scb[6].i2_c_scl:1									peri.tr.io_input[2_4]:0	
P12.1	tcpwm[0].line_comp[2]:7	tcpwm[1].line_comp[6]:3	csd.csd_tx:61	csd.csd_tx_n:61	scb[6].i2_c_sdat:1									peri.tr.io_input[2_5]:0	
P12.6	tcpwm[0].line[3]:7	tcpwm[1].line[7]:3	csd.csd_tx:62	csd.csd_tx_n:62											
P12.7	tcpwm[0].line_comp[3]:7	tcpwm[1].line_comp[7]:3	csd.csd_tx:63	csd.csd_tx_n:63											

Analog and Smart I/O alternate port pin functionality is provided in [Table 9](#).

**Table 9. Port Pin Analog, and Smart I/O Functions**

Name	Analog	Digital HV	AMUXA	AMUXB	SMARTIO
P0.0	wco_in				
P0.1	wco_out				
P0.2					
P0.3					
P0.4		pmic_wakeup_in hibernate_wakeup[1]			
P0.5		pmic_wakeup_out			
P5.6	lpcomp.inp_comp0				
P5.7	lpcomp.inn_comp0				
P6.2	lpcomp.inp_comp1				
P6.3	lpcomp.inn_comp1				
P6.6		swd_data			
P6.7		swd_clk			
P7.0			amuxbus_a_csd0	amuxbus_b_csd0	
P7.1	csd.cmodpadd csd.cmodpads		amuxbus_a_csd0	amuxbus_b_csd0	
P7.2	csd.csh_tankpadd csd.csh_tankpads		amuxbus_a_csd0	amuxbus_b_csd0	
P7.3	csd.vref_ext		amuxbus_a_csd0	amuxbus_b_csd0	
P7.4		hibernate_wakeup[0]	amuxbus_a_csd0	amuxbus_b_csd0	
P7.5			amuxbus_a_csd0	amuxbus_b_csd0	
P7.6			amuxbus_a_csd0	amuxbus_b_csd0	
P7.7	csd.cshieldpads		amuxbus_a_csd0	amuxbus_b_csd0	
P8.0			amuxbus_a_csd0	amuxbus_b_csd0	smartio[8].io[0]
P8.1			amuxbus_a_csd0	amuxbus_b_csd0	smartio[8].io[1]
P8.2			amuxbus_a_csd0	amuxbus_b_csd0	smartio[8].io[2]
P8.3			amuxbus_a_csd0	amuxbus_b_csd0	smartio[8].io[3]
P9.0			amuxbus_a_sar	amuxbus_b_sar	smartio[9].io[0]
P9.1			amuxbus_a_sar	amuxbus_b_sar	smartio[9].io[1]
P9.2			amuxbus_a_sar	amuxbus_b_sar	smartio[9].io[2]
P9.3	aref_ext_vref		amuxbus_a_sar	amuxbus_b_sar	smartio[9].io[3]
P10.0	sarmux_pads[0]				
P10.1	sarmux_pads[1]				
P10.2	sarmux_pads[2]				
P10.3	sarmux_pads[3]				
P10.4	sarmux_pads[4]				
P10.5	sarmux_pads[5]				
P10.6	sarmux_pads[6]				
P10.7	sarmux_pads[7]				
P12.6	eco_in				
P12.7	eco_out				

### Power Supply Considerations

The following power system diagrams show typical connections for power pins for all supported packages, and with and without usage of the buck regulator.

In these diagrams, the package pin is shown with the pin name, for example "V<sub>DDA</sub>, 53". For V<sub>DDX</sub> pins, the I/O port that is powered by that pin is also shown, for example "V<sub>BACKUP</sub>, 6; I/O port P0".

Figure 11. 100-TQFP Power Connection Diagram

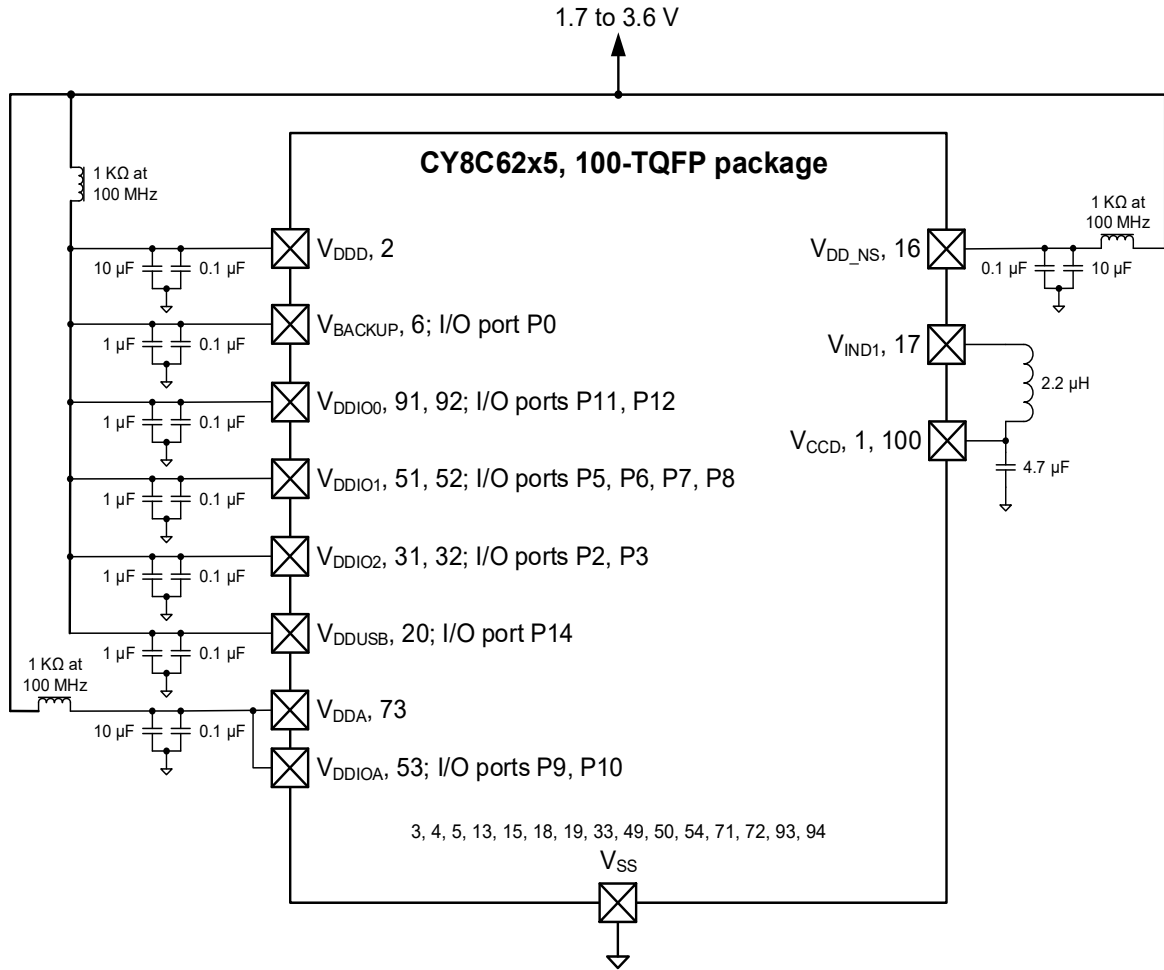
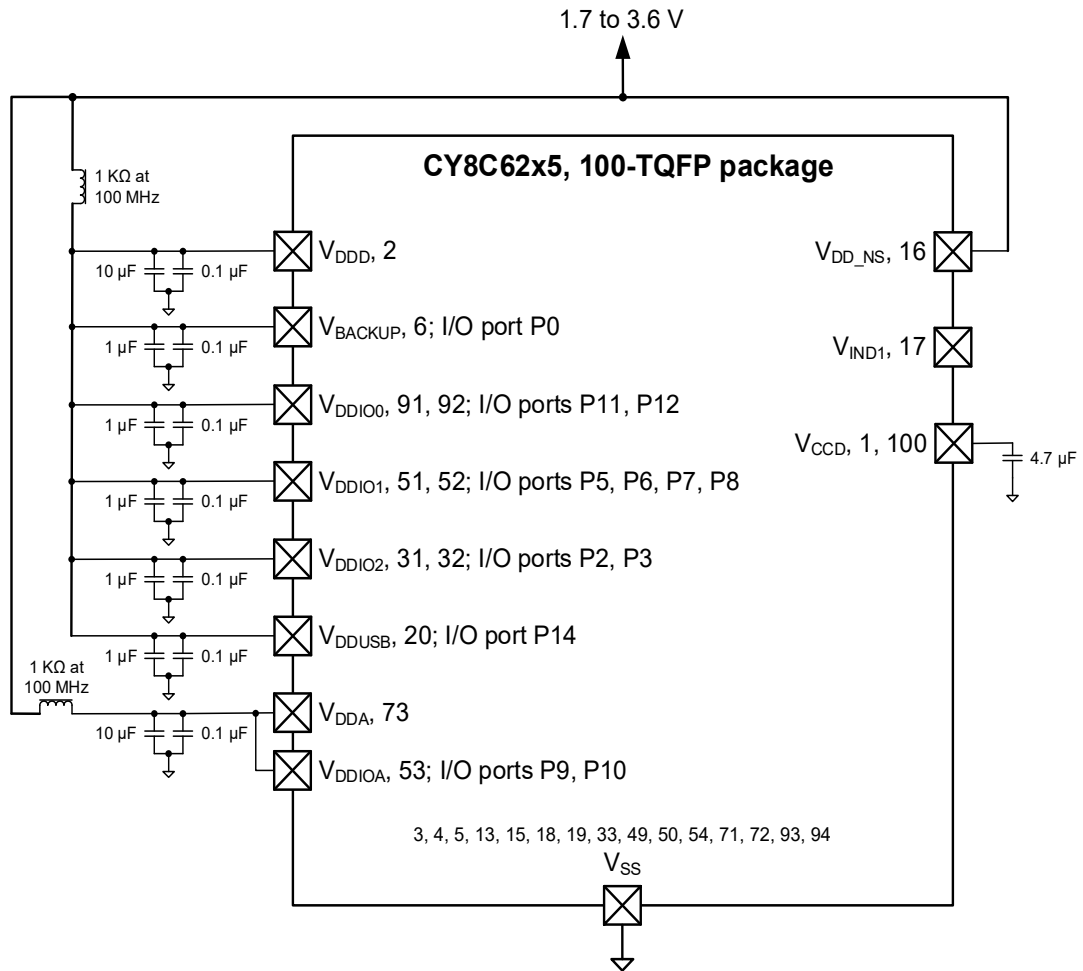


Figure 12. 100-TQFP (No Buck) Power Connection Diagram



In the QFN package, all internal grounds are routed to the metal pad (epad) in the package. This pad must be grounded on the PCB.

Figure 13. 68-QFN Power Connection Diagram

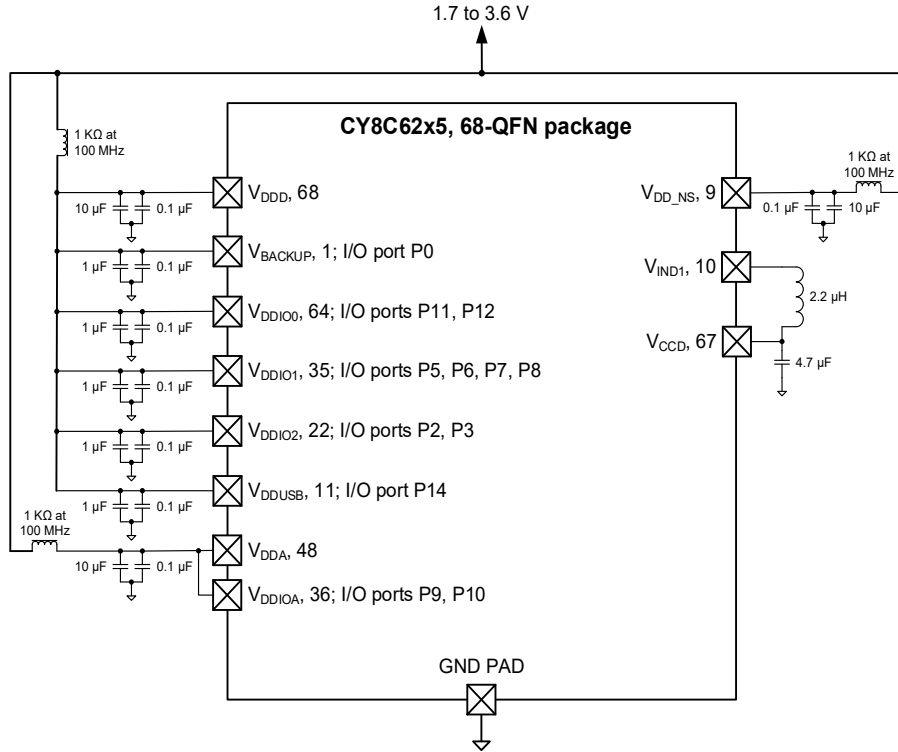
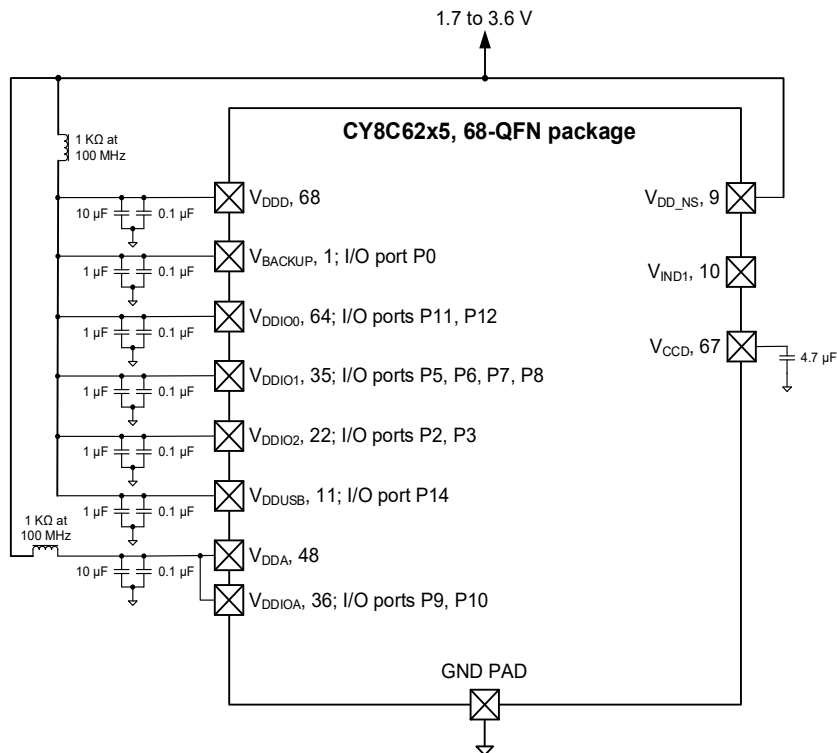
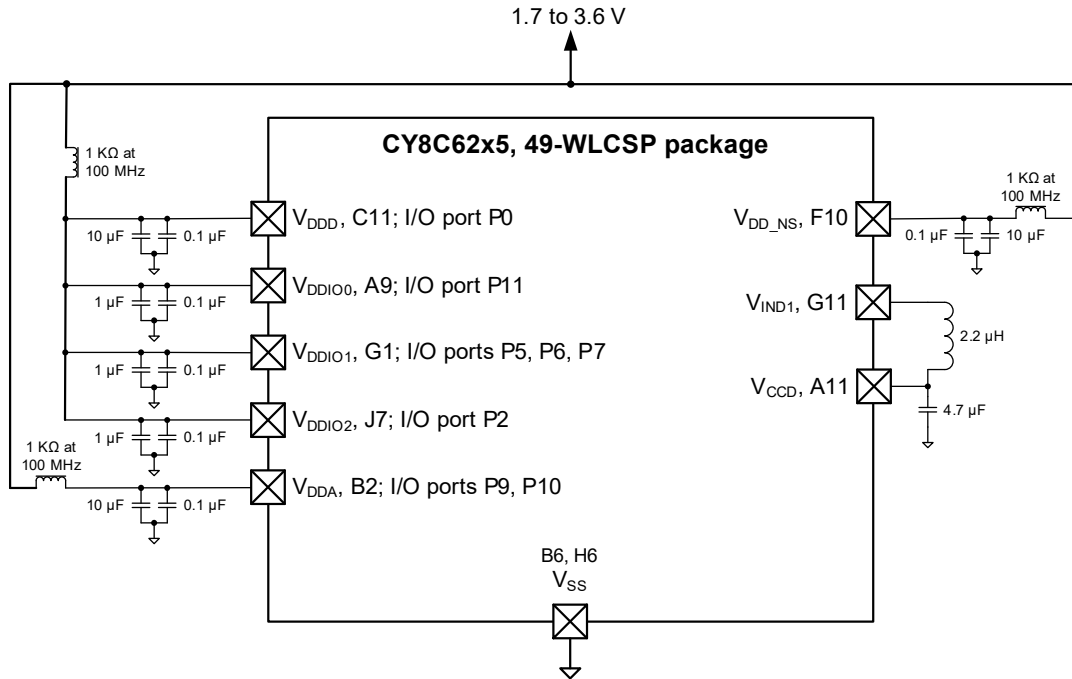


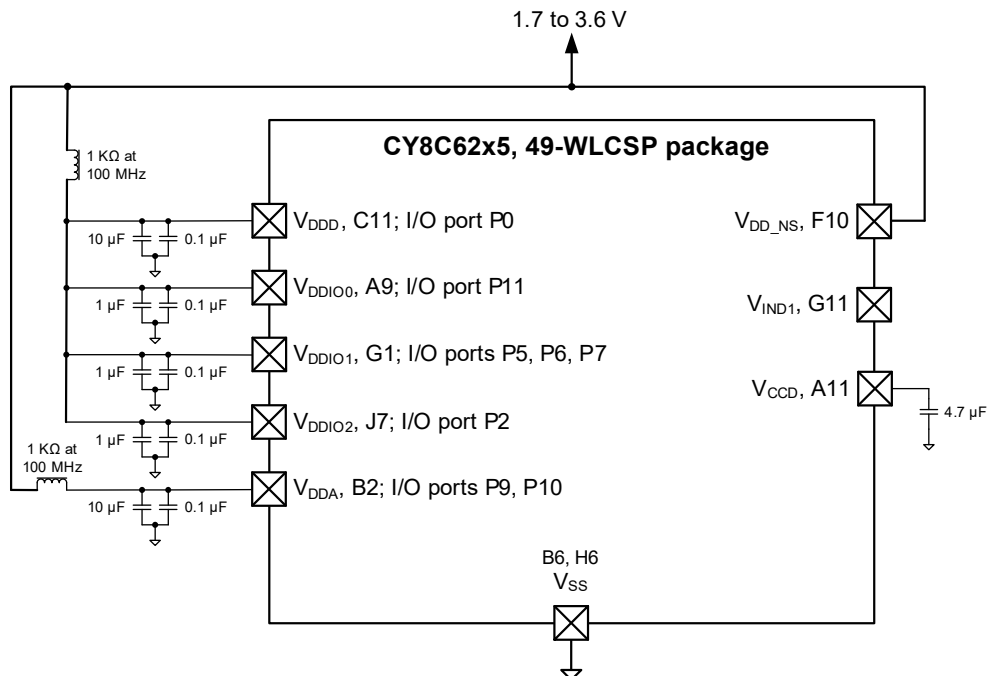
Figure 14. 68-QFN (No Buck) Power Connection Diagram



**Figure 15. 49-WLCSP Power Connection Diagram**



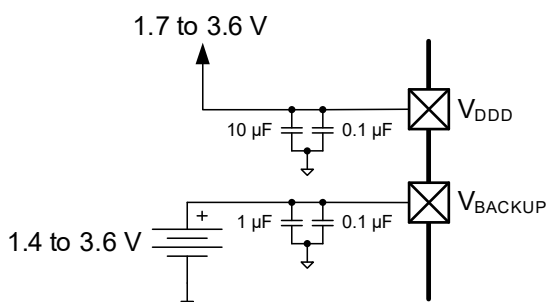
**Figure 16. 49-WLCSP (No Buck) Power Connection Diagram**



There are as many as eight  $V_{DDx}$  supply pins, depending on the package, and multiple  $V_{SS}$  ground pins. The power pins are:

- $V_{DDD}$ : the main digital supply. It powers the LDO and switching regulators. It also powers I/O port 0 on packages where  $V_{BACKUP}$  is not available.
- $V_{CCD}$ : the main LDO output. It requires a 4.7- $\mu$ F capacitor for regulation. The LDO can be turned off when  $V_{CCD}$  is driven from the switching regulator (see below). For more information, see the power system block diagram in the device [technical reference manual \(TRM\)](#).
- $V_{DDA}$ : the supply for the analog peripherals. Voltage must be applied to this pin for correct device initialization and boot up.
- $V_{DDIOA}$ : the supply for I/O ports 9 and 10. If it is present in the device package, it must be connected to  $V_{DDA}$ .
- $V_{DDIO0}$ : the supply for I/O ports 11 and 12.
- $V_{DDIO1}$ : the supply for I/O ports 5, 6, 7, and 8. Some of the ports are not available depending on package.
- $V_{DDIO2}$ : the supply for I/O ports 2 and 3.
- $V_{BACKUP}$ : the supply for the backup domain, which includes the 32-kHz WCO and the RTC. It can be a separate supply as low as 1.4 V, for battery or supercapacitor backup, as [Figure 17](#) shows, otherwise it is connected to  $V_{DDD}$ . It powers I/O port 0<sup>[2]</sup>.

**Figure 17. Separate Battery Connection to  $V_{BACKUP}$**



- $V_{DDUSB}$ : the supply for the USB peripheral and the USBDP and USBDM pins. It must be 2.85 V to 3.6 V for USB operation. If USB is not used, it can be 1.7 V to 3.6 V, and the USB pins can be used as limited-capability GPIOs on I/O port 14.

[Table 10](#) shows a summary of the I/O port supplies:

**Table 10. I/O Power Supplies**

Port	Supply	Alternate Supply
0	$V_{BACKUP}$	$V_{DDD}$
2, 3	$V_{DDIO2}$	—
5, 6, 7, 8	$V_{DDIO1}$	—
9, 10	$V_{DDIOA}$	$V_{DDA}$
11, 12	$V_{DDIO0}$	—
14	$V_{DDUSB}$	—

**Note**

2. It is not available in the 49-WLCSP package.  $V_{DDD}$  powers port 0.

**Note:** If the USB pins are not used, connect  $V_{DDUSB}$  to ground and leave the P14.0/USB DP and P14.1/USB DM pins unconnected.

Voltage must be applied to the  $V_{DDD}$  pin, and the  $V_{DDA}$  pin as noted above, for correct device initialization and operation. If an I/O port is not being used, applying voltage to the corresponding  $V_{DDx}$  pin is optional.

- $V_{SS}$ : ground pins for the above supplies. All ground pins should be connected together to a common ground.

In addition to the LDO regulator, a switching regulator is included. The regulator pins are:

- $V_{DD\_NS}$ : the regulator supply.
- $V_{IND1}$ : the regulator output. It is typically used to drive  $V_{CCD}$  through an inductor.

The  $V_{DD}$  power pins are not connected on chip. They can be connected off chip, in one or more separate nets. If separate power nets are used, they can be isolated from noise from the other nets using optional ferrite beads, as indicated in the diagrams.

No external load should be placed on  $V_{CCD}$ , or  $V_{IND1}$ , whether or not these pins are used.

There are no power pin sequencing requirements; power supplies may be brought up in any order. The power management system holds the device in reset until all power pins are at the voltage levels required for proper operation.

**Note:** If a battery is installed on the PCB first,  $V_{DDD}$  must be cycled for at least 50  $\mu$ s. This prevents premature drain of the battery during product manufacture and storage.

Bypass capacitors must be connected to a common ground from the  $V_{DDx}$  and other pins, as indicated in the diagrams. Typical practice for systems in this frequency range is to use a 10- $\mu$ F or 1- $\mu$ F capacitor in parallel with a smaller capacitor (0.1  $\mu$ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and bypass capacitor parasitic should be simulated for optimal bypassing.

All capacitors and inductors should be  $\pm 20\%$  or better. The recommended inductor value is 2.2  $\mu$ H  $\pm 20\%$  (for example, TDK MLP2012H2R2MT0S1).

It is good practice to check the datasheets for your bypass capacitors, specifically the working voltage and the DC bias specifications. With some capacitors, the actual capacitance can decrease considerably when the applied voltage is a significant percentage of the rated working voltage.

For more information on pad layout, refer to [PSoC 6 CAD libraries](#).

## Electrical Specifications

All specifications are valid for  $-40\text{ }^{\circ}\text{C} \leq T_A \leq 85\text{ }^{\circ}\text{C}$  and for 1.71 V to 3.6 V except where noted.

### Absolute Maximum Ratings

**Table 11. Absolute Maximum Ratings<sup>[3]</sup>**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID1	V <sub>DD_ABS</sub>	Analog or digital supply relative to V <sub>SS</sub> (V <sub>SSD</sub> = V <sub>SSA</sub> )	-0.5	-	4	V	
SID2	V <sub>CCD_ABS</sub>	Direct digital core voltage input relative to V <sub>SSD</sub>	-0.5	-	1.2	V	
SID3	V <sub>GPIO_ABS</sub>	GPIO voltage; V <sub>DDD</sub> or V <sub>DDA</sub>	-0.5	-	V <sub>DD</sub> + 0.5	V	
SID4	I <sub>GPIO_ABS</sub>	Current per GPIO	-25	-	25	mA	
SID5	I <sub>GPIO_injection</sub>	GPIO injection current per pin	-0.5	-	0.5	mA	
SID3A	ESD_HBM	Electrostatic discharge Human Body Model	2200	-	-	V	
SID4A	ESD_CDM	Electrostatic discharge Charged Device Model	500	-	-	V	
SID5A	LU	Pin current for latchup-free operation	-100	-	100	mA	

### Device-Level Specifications

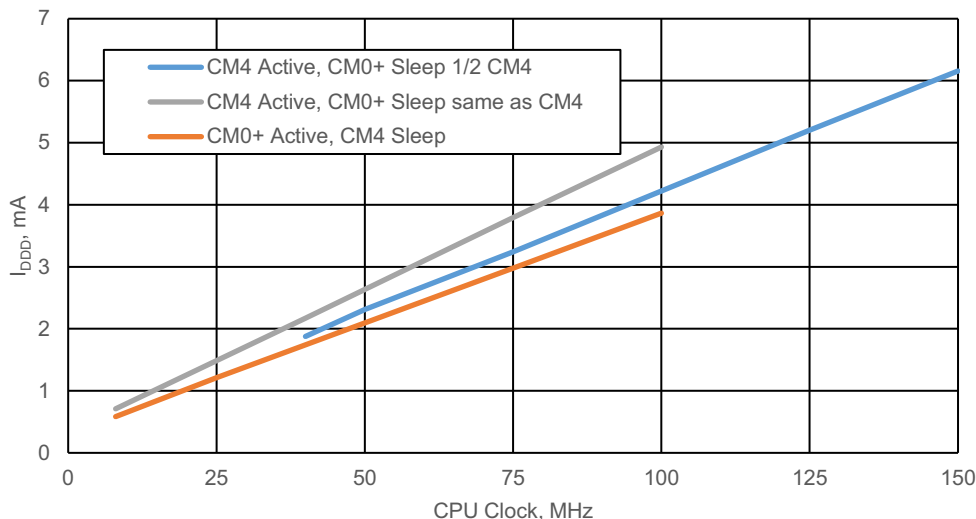
Table 14 provides detailed specifications of CPU current. Table 12 summarizes these specifications, for rapid review of CPU currents under common conditions. Note that the max frequency for CM4 is 150 MHz, and for CM0+ is 100 MHz. IMO and FLL are used to generate the CPU clocks; FLL is not used when the CPU clock frequency is 8 MHz.

**Table 12. CPU Current Specifications Summary**

Condition	Range	Typ Range	Max Range
LP Mode, V <sub>DDD</sub> = 3.3 V, V <sub>CCD</sub> = 1.1 V, with buck regulator			
CM4 active, CM0+ sleep	Across CPUs clock ranges: 8–150/100 MHz; Dhrystone with flash cache enabled	0.9–6.3 mA	1.5–7 mA
CM0+ active, CM4 sleep		0.8–3.8 mA	1.3–4.5 mA
CM4 sleep, CM0+ sleep		0.7–1.5 mA	1.3–2.2 mA
CM0+ sleep, CM4 off		0.7–1.3 mA	1.3–2 mA
Minimum regulator current mode	Across CM4/CM0+ CPU active/sleep modes	0.6–0.7 mA	1.1–1.1 mA
ULP Mode, V <sub>DDD</sub> = 3.3 V, V <sub>CCD</sub> = 0.9 V, with buck regulator			
CM4 active, CM0+ sleep	Across CPUs clock ranges: 8 – 50/25 MHz; Dhrystone with flash cache enabled	0.65–1.6 mA	0.8–2.2mA
CM0+ active, CM4 sleep		0.51–0.91 mA	0.72–1.25 mA
CM4 sleep, CM0+ sleep		0.42–0.76 mA	0.65–1.1 mA
CM0+ sleep, CM4 off		0.41–0.62 mA	0.6–0.9 mA
Minimum regulator current mode	Across CM4/CM0+ CPU active/sleep modes	0.39–0.54 mA	0.6–0.76 mA
Deep Sleep	Across SRAM retention	7–9 $\mu$ A	-
Hibernate	Across V <sub>DDD</sub>	300–800 nA	-

#### Note

- Usage above the absolute maximum conditions listed in Table 11 may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

**Figure 18. Typical Device Currents vs. CPU Frequency; System Low Power (LP) Mode**

*Power Supplies*
**Table 13. Power Supply DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID6	V <sub>DDD</sub>	Internal regulator	1.7	–	3.6	V	–
SID7	V <sub>DDA</sub>	Analog power supply voltage. Shorted to V <sub>DDIOA</sub> on PCB.	1.7	–	3.6	V	Internally unregulated supply
SID7A	V <sub>DDIO1</sub>	GPIO supply for Ports 5 to 8 when present	1.7	–	3.6	V	Must be ≥ V <sub>DDA</sub> if the CapSense (CSD) block is used in the application
SID7B	V <sub>DDIO0</sub>	GPIO supply for Ports 11 and 12	1.7	–	3.6	V	–
SID7E	V <sub>DDIO0</sub>	Supply for eFuse programming	2.38	2.5	2.62	V	–
SID7C	V <sub>DDIO2</sub>	GPIO supply for Ports 2 and 3 when present	1.7	–	3.6	V	–
SID7D	V <sub>DDIOA</sub>	GPIO supply for Ports 9 and 10 when present. Must be connected to V <sub>DDA</sub> on PCB.	1.7	–	3.6	V	–
SID7F	V <sub>DDUSB</sub>	Supply for Port 14 (USB or GPIO) when present	1.7	–	3.6	V	Min supply is 2.85 V for USB
SID6B	V <sub>BACKUP</sub>	Backup power and GPIO Port 0 supply when present	1.7	–	3.6	V	Min. is 1.4 V when V <sub>DDD</sub> is removed
SID8	V <sub>CCD1</sub>	Output voltage (for core logic bypass)	–	1.1	–	V	System LP mode
SID9	V <sub>CCD2</sub>	Output voltage (for core logic bypass)	–	0.9	–		ULP mode. Valid for –20 to 85 °C.
SID10	C <sub>EFC</sub>	External regulator voltage (V <sub>CCD</sub> ) bypass	3.8	4.7	5.6	μF	X5R ceramic or better. Value for 0.8 to 1.2 V
SID11	C <sub>EXC</sub>	Power supply decoupling capacitor	–	10	–	μF	X5R ceramic or better

*CPU Current and Transition Times*
**Table 14. CPU Current and Transition Times**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>LP Range Power Specifications (for <math>V_{CCD} = 1.1</math> V with Buck and LDO)</b>							
<b>Cortex-M4. Active Mode</b>							
<b>Execute with Cache Disabled (Flash)</b>							
SIDF1	$I_{DD1}$	Execute from flash; CM4 Active 50 MHz, CM0+ Sleep 25 MHz. With IMO and FLL. While(1).	–	2.3	3.2	mA	$V_{DDD} = 3.3$ V, Buck ON, Max at 60 °C.
			–	3.1	3.6	mA	$V_{DDD} = 1.8$ V, Buck ON, Max at 60 °C.
			–	5.7	6.5	mA	$V_{DDD} = 1.8$ to 3.3 V, LDO, max at 85 °C.
SIDF2	$I_{DD2}$	Execute from flash; CM4 Active 8 MHz, CM0+ Sleep 8 MHz. With IMO. While(1).	–	0.9	1.5	mA	$V_{DDD} = 3.3$ V, Buck ON, Max at 60 °C.
			–	1.2	1.6	mA	$V_{DDD} = 1.8$ V, Buck ON, Max at 60 °C.
			–	2.8	3.5	mA	$V_{DDD} = 1.8$ to 3.3 V, LDO, Max at 85 °C.
<b>Execute with Cache Enabled</b>							
SIDC1	$I_{DD3}$	Execute from cache; CM4 Active 150 MHz, CM0+ Sleep 75 MHz. IMO and PLL. Dhrystone.	–	6.3	7	mA	$V_{DDD} = 3.3$ V, Buck ON, Max at 60 °C.
			–	9.7	11.2	mA	$V_{DDD} = 1.8$ V, Buck ON, Max at 60 °C.
			–	14.4	15.1	mA	$V_{DDD} = 1.8$ to 3.3 V, LDO, max at 85 °C.
SIDC2	$I_{DD4}$	Execute from cache; CM4 Active 100 MHz, CM0+ Sleep 100MHz. IMO and FLL. Dhrystone.	–	4.8	5.8	mA	$V_{DDD} = 3.3$ V, Buck ON, Max at 60 °C.
			–	7.4	8.4	mA	$V_{DDD} = 1.8$ V, Buck ON, Max at 60 °C.
			–	11.3	12	mA	$V_{DDD} = 1.8$ to 3.3 V, LDO, Max at 85 °C.
SIDC3	$I_{DD5}$	Execute from cache; CM4 Active 50 MHz, CM0+ Sleep 25MHz. IMO and FLL. Dhrystone.	–	2.4	3.4	mA	$V_{DDD} = 3.3$ V, Buck ON, Max at 60 °C.
			–	3.7	4.1	mA	$V_{DDD} = 1.8$ V, Buck ON, Max at 60 °C.
			–	6.3	7.2	mA	$V_{DDD} = 1.8$ to 3.3 V, LDO, Max at 85 °C.
SIDC4	$I_{DD6}$	Execute from cache; CM4 Active 8 MHz, CM0+ Sleep 8 MHz. IMO. Dhrystone.	–	0.90	1.5	mA	$V_{DDD} = 3.3$ V, Buck ON, Max at 60 °C.
			–	1.3	1.8	mA	$V_{DDD} = 1.8$ V, Buck ON, Max at 60 °C.
			–	3	3.8	mA	$V_{DDD} = 1.8$ to 3.3 V, LDO, Max at 85 °C.

**Table 14. CPU Current and Transition Times (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>Cortex-M0+. Active Mode</b>							
<b>Execute with Cache Disabled (Flash)</b>							
SIDF3	I <sub>DD7</sub>	Execute from flash;CM4 OFF, CM0+ Active 50 MHz. With IMO and FLL. While (1).	–	2.4	3.3	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	3.2	3.7	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	5.6	6.3	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
SIDF4	I <sub>DD8</sub>	Execute from flash;CM4 OFF, CM0+ Active 8 MHz. With IMO. While (1).	–	0.8	1.5	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.1	1.6	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.6	3.4	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
<b>Execute with Cache Enabled</b>							
SIDC5	I <sub>DD9</sub>	Execute from cache;CM4 OFF, CM0+ Active 100 MHz. With IMO and FLL. Dhrystone.	–	3.8	4.5	mA	V <sub>DDD</sub> = 3.3V, Buck ON, Max at 60 °C.
			–	5.9	6.5	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	9	9.7	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
SIDC6	I <sub>DD10</sub>	Execute from cache;CM4 OFF, CM0+ Active 8 MHz. With IMO. Dhrystone.	–	0.8	1.3	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.2	1.7	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.6	3.4	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
<b>Cortex-M4. Sleep Mode</b>							
SIDS1	I <sub>DD11</sub>	CM4 Sleep 100 MHz, CM0+ Sleep 25 MHz. With IMO and FLL.	–	1.5	2.2	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	2.2	2.7	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	4	4.6	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, max at 85 °C.
SIDS2	I <sub>DD12</sub>	CM4 Sleep 50 MHz, CM0+ Sleep 25 MHz. With IMO & FLL.	–	1.2	1.9	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.7	2.2	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	3.4	4.3	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
SIDS3	I <sub>DD13</sub>	CM4 Sleep 8 MHz, CM0+ Sleep 8 MHz. With IMO.	–	0.7	1.3	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1	1.5	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.4	3.3	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.

**Table 14. CPU Current and Transition Times (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>Cortex-M0+. Sleep Mode</b>							
SIDS4	I <sub>DD14</sub>	CM4 Off, CM0+ Sleep 50 MHz. With IMO and FLL.	–	1.3	2	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.9	2.4	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	3.8	4.6	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
SIDS5	I <sub>DD15</sub>	CM4 Off, CM0+ Sleep 8 MHz. With IMO.	–	0.7	1.3	mA	V <sub>DDD</sub> = 3.3V, Buck ON, Max at 60 °C.
			–	1	1.5	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.4	3.3	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
<b>Cortex-M4. Minimum Regular Current Mode</b>							
SIDLPA1	I <sub>DD16</sub>	Execute from flash; CM4 Active 8 MHz, CM0+ Sleep 8 MHz. With IMO. While (1).	–	0.9	1.5	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.2	1.7	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.8	3.5	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, max at 85 °C.
SIDLPA2	I <sub>DD17</sub>	Execute from cache; CM4 Active 8 MHz, CM0+ Sleep 8 MHz. With IMO. Dhrystone.	–	0.9	1.5	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.3	1.8	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.9	3.7	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
<b>Cortex-M0+. Minimum Regulator Current Mode</b>							
SIDLPA3	I <sub>DD18</sub>	Execute from flash; CM4 OFF, CM0+ Active 8 MHz. With IMO. While (1).	–	0.8	1.4	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.1	1.6	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.7	3.6	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
SIDLPA4	I <sub>DD19</sub>	Execute from cache; CM4 Off, CM0+ Active 8 MHz. With IMO. Dhrystone	–	0.8	1.4	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.2	1.7	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.7	3.6	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
<b>Cortex-M4. Minimum Regulator Current Mode</b>							
SIDLPS1	I <sub>DD20</sub>	CM4 Sleep 8 MHz, CM0+ Sleep 8 MHz. With IMO.	–	0.7	1.1	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1	1.5	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.4	3.3	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.

**Table 14. CPU Current and Transition Times (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>Cortex-M0+. Minimum Regulator Current Mode</b>							
SIDLPS3	I <sub>DD22</sub>	CM4 Off, CM0+ Sleep 8 MHz. With IMO.	–	0.6	1.1	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	0.9	1.5	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
			–	2.4	3.3	mA	V <sub>DDD</sub> = 1.8 to 3.3 V, LDO, Max at 85 °C.
<b>ULP RANGE POWER SPECIFICATIONS (for V<sub>CCD</sub> = 0.9 V using the Buck). ULP mode is valid from –20 to +85 °C.</b>							
<b>Cortex-M4. Active Mode</b>							
<b>Execute with Cache Disabled (Flash)</b>							
SIDF5	I <sub>DD3</sub>	Execute from flash; CM4 Active 50 MHz, CM0+ Sleep 25 MHz. With IMO and FLL. While(1).	–	1.7	2.2	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	2.1	2.4	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
SIDF6	I <sub>DD4</sub>	Execute from flash; CM4 Active 8 MHz, CM0+ Sleep 8 MHz. With IMO. While (1).	–	0.56	0.8	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	0.75	1	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Execute with Cache Enabled</b>							
SIDC8	I <sub>DD10</sub>	Execute from cache; CM4 Active 50 MHz, CM0+ Sleep 25 MHz. With IMO and FLL. Dhrystone.	–	1.6	2.2	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	2.4	2.7	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
SIDC9	I <sub>DD11</sub>	Execute from cache; CM4 Active 8 MHz, CM0+ Sleep 8 MHz. With IMO. Dhrystone.	–	0.65	0.8	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	0.8	1.1	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Cortex-M0+. Active Mode</b>							
<b>Execute with Cache Disabled (Flash)</b>							
SIDF7	I <sub>DD16</sub>	Execute from flash; CM4 OFF, CM0+ Active 25 MHz. With IMO and FLL. Write(1).	–	1	1.4	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.34	1.6	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
SIDF8	I <sub>DD17</sub>	Execute from flash; CM4 OFF, CM0+ Active 8 MHz. With IMO. While(1).	–	0.54	0.75	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	0.73	1	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Execute with Cache Enabled</b>							
SIDC10	I <sub>DD18</sub>	Execute from cache; CM4 OFF, CM0+ Active 25 MHz. With IMO and FLL. Dhrystone.	–	0.91	1.25	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.34	1.6	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
SIDC11	I <sub>DD19</sub>	Execute from cache; CM4 OFF, CM0+ Active 8 MHz. With IMO. Dhrystone.	–	0.51	0.72	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	0.73	0.95	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Cortex-M4. Sleep Mode</b>							
SIDS7	I <sub>DD21</sub>	CM4 Sleep 50 MHz, CM0+ Sleep 25 MHz. With IMO and FLL.	–	0.76	1.1	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			–	1.1	1.4	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.

**Table 14. CPU Current and Transition Times (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SIDS8	I <sub>DD22</sub>	CM4 Sleep 8 MHz, CM0+ Sleep 8 MHz. With IMO.	-	0.42	0.65	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.59	0.8	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Cortex-M0+. Sleep Mode</b>							
SIDS9	I <sub>DD23</sub>	CM4 Off, CM0+ Sleep 25 MHz. With IMO and FLL.	-	0.62	0.9	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.88	1.1	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
SIDS10	I <sub>DD24</sub>	CM4 Off, CM0+ Sleep 8 MHz. With IMO.	-	0.41	0.6	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.58	0.8	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Cortex-M4. Minimum Regulator Current Mode</b>							
SIDLPA5	I <sub>DD25</sub>	Execute from flash. CM4 Active 8 MHz, CM0+ Sleep 8 MHz. With IMO. While(1).	-	0.52	0.75	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.76	1	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
SIDLPA6	I <sub>DD26</sub>	Execute from cache. CM4 Active 8 MHz, CM0+ Sleep 8 MHz. With IMO. Dhystone.	-	0.54	0.76	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.78	1	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Cortex-M0+. Minimum Regulator Current Mode</b>							
SIDLPA7	I <sub>DD27</sub>	Execute from flash. CM4 OFF, CM0+ Active 8 Hz. With IMO. While (1).	-	0.51	0.75	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.75	1	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
SIDLPA8	I <sub>DD28</sub>	Execute from cache. CM4 OFF, CM0+ Active 8 MHz. With IMO. Dhystone.	-	0.48	0.7	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.7	0.95	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Cortex-M4. Minimum Regulator Current Mode</b>							
SIDLPS5	I <sub>DD29</sub>	CM4 Sleep 8 MHz, CM0+ Sleep 8 MHz. With IMO.	-	0.4	0.6	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.57	0.8	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Cortex-M0+. Minimum Regulator Current Mode</b>							
SIDLPS7	I <sub>DD31</sub>	CM4 Off, CM0+ Sleep 8 MHz. With IMO.	-	0.39	0.6	mA	V <sub>DDD</sub> = 3.3 V, Buck ON, Max at 60 °C.
			-	0.56	0.8	mA	V <sub>DDD</sub> = 1.8 V, Buck ON, Max at 60 °C.
<b>Deep Sleep Mode</b>							
SIDDS1	I <sub>DD33A</sub>	With internal Buck enabled and 64-KB SRAM retention	-	7	-	μA	Max value is at 85 °C
SIDDS1_B	I <sub>DD33A_B</sub>	With internal Buck enabled and 64-KB SRAM retention	-	7	-	μA	Max value is at 60 °C.
SIDDS2	I <sub>DD33B</sub>	With internal Buck enabled and 256-KB SRAM retention	-	9	-	μA	Max value is at 85 °C
SIDDS2_B	I <sub>DD33B_B</sub>	With internal Buck enabled and 256-KB SRAM retention	-	9	-	μA	Max value is at 60 °C.

**Table 14. CPU Current and Transition Times (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>Hibernate Mode</b>							
SIDHIB1	$I_{DD34}$	$V_{DDD} = 1.8\text{ V}$	–	300	–	nA	No clocks running
SIDHIB2	$I_{DD34A}$	$V_{DDD} = 3.3\text{ V}$	–	800	–	nA	No clocks running
<b>Power Mode Transition Times</b>							
SID12	$T_{LPACT\_ACT}$	Minimum regulator current to LP transition time	–	–	35	$\mu\text{s}$	Including PLL lock time
SID13	$T_{DS\_LPACT}$	Deep Sleep to LP transition time	–	–	15	$\mu\text{s}$	Guaranteed by design
SID14	$T_{HIB\_ACT}$	Hibernate to LP transition time	–	2000	–	$\mu\text{s}$	Including PLL lock time

**XRES**
**Table 15. XRES DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID17	$T_{XRES\_IDD}$	$I_{DD}$ when XRES asserted	–	300	–	nA	$V_{DDD} = 1.8\text{ V}$
SID17A	$T_{XRES\_IDD\_1}$	$I_{DD}$ when XRES asserted	–	800	–	nA	$V_{DDD} = 3.3\text{ V}$
SID77	$V_{IH}$	Input voltage HIGH threshold	$0.7 * V_{DD}$	–	–	V	CMOS input
SID78	$V_{IL}$	Input voltage LOW threshold	–	–	$0.3 * V_{DD}$	V	CMOS input
SID80	$C_{IN}$	Input capacitance	–	3	–	pF	–
SID81	$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	–
SID82	$I_{DIODE}$	Current through protection diode to $V_{DD}/V_{SS}$	–	–	100	$\mu\text{A}$	–

**Table 16. XRES AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID15	$T_{XRES\_ACT}$	POR or XRES release to Active transition time	–	2000	–	$\mu\text{s}$	Normal mode, 50-MHz CM0+
SID16	$T_{XRES\_PW}$	XRES pulse width	5	–	–	$\mu\text{s}$	–

**GPIO**
**Table 17. GPIO DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID57	$V_{IH}$	Input voltage HIGH threshold	$0.7 * V_{DD}$	–	–	V	CMOS Input
SID57A	$I_{IHS}$	Input current when Pad > $V_{DDIO}$ for OVT inputs	–	–	10	$\mu\text{A}$	Per I <sup>2</sup> C Spec
SID58	$V_{IL}$	Input voltage LOW threshold	–	–	$0.3 * V_{DD}$	V	CMOS Input
SID241	$V_{IH}$	LVTTL input, $V_{DD} < 2.7\text{ V}$	$0.7 * V_{DD}$	–	–	V	–
SID242	$V_{IL}$	LVTTL input, $V_{DD} < 2.7\text{ V}$	–	–	$0.3 * V_{DD}$	V	–
SID243	$V_{IH}$	LVTTL input, $V_{DD} \geq 2.7\text{ V}$	2.0	–	–	V	–
SID244	$V_{IL}$	LVTTL input, $V_{DD} \geq 2.7\text{ V}$	–	–	0.8	V	–
SID59	$V_{OH}$	Output voltage HIGH level	$V_{DD} - 0.5$	–	–	V	$I_{OH} = 8\text{ mA}$
SID62A	$V_{OL}$	Output voltage LOW level	–	–	0.4	V	$I_{OL} = 8\text{ mA}$
SID63	$R_{PULLUP}$	Pull-up resistor	3.5	5.6	8.5	k $\Omega$	–
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5	k $\Omega$	–

**Table 17. GPIO DC Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID65	$I_{IL}$	Input leakage current (absolute value)	–	–	2	nA	25 °C, $V_{DD} = 3.0\text{ V}$
SID66	$C_{IN}$	Input capacitance	–	–	5	pF	–
SID67	$V_{HYSTTL}$	Input hysteresis LVTTL $V_{DD} > 2.7\text{ V}$	100	0	–	mV	–
SID68	$V_{HYSCMOS}$	Input hysteresis CMOS	$0.05 * V_{DD}$	–	–	mV	–
SID69	$I_{DIODE}$	Current through protection diode to $V_{DD}/V_{SS}$	–	–	100	$\mu\text{A}$	–
SID69A	$I_{TOT\_GPIO}$	Maximum total source or sink chip current	–	–	200	mA	–

**Table 18. GPIO AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID70	$T_{RISEF}$	Rise time in Fast Strong Mode. 10% to 90% of $V_{DD}$ .	–	–	2.5	ns	Load = 15 pF, 8-mA drive strength
SID71	$T_{FALLF}$	Fall time in Fast Strong Mode. 10% to 90% of $V_{DD}$ .	–	–	2.5	ns	Load = 15 pF, 8-mA drive strength
SID72	$T_{RISES\_1}$	Rise time in Slow Strong Mode. 10% to 90% of $V_{DD}$ .	52	–	142	ns	Load = 15 pF, 8-mA drive strength, $V_{DD} \leq 2.7\text{ V}$
SID72A	$T_{RISES\_2}$	Rise time in Slow Strong Mode. 10% to 90% of $V_{DD}$ .	48	–	102	ns	Load = 15 pF, 8-mA drive strength, $2.7\text{ V} < V_{DD} \leq 3.6\text{ V}$
SID73	$T_{FALLS\_1}$	Fall time in Slow Strong Mode. 10% to 90% of $V_{DD}$ .	44	–	211	ns	Load = 15 pF, 8 mA drive strength, $V_{DD} \leq 2.7\text{ V}$
SID73A	$T_{FALLS\_2}$	Fall time in Slow Strong Mode. 10% to 90% of $V_{DD}$ .	42	–	93	ns	Load = 15 pF, 8-mA drive strength, $2.7\text{ V} < V_{DD} \leq 3.6\text{ V}$
SID73G	$T_{FALL\_I2C}$	Fall time (30% to 70% of $V_{DD}$ ) in Slow Strong mode.	$20 * V_{DDIO} / 5.5$	–	250	ns	Load = 10 pF to 400 pF, 8-mA drive strength
SID74	$F_{GPIOOUT1}$	GPIO Fout. Fast Strong mode.	–	–	100	MHz	90/10%, 15-pF load, 60/40 duty cycle
SID75	$F_{GPIOOUT2}$	GPIO Fout; Slow Strong mode.	–	–	1.5	MHz	90/10%, 15-pF load, 60/40 duty cycle
SID76	$F_{GPIOOUT3}$	GPIO Fout; Fast Strong mode.	–	–	100	MHz	90/10%, 25-pF load, 60/40 duty cycle
SID245	$F_{GPIOOUT4}$	GPIO Fout; Slow Strong mode.	–	–	1.3	MHz	90/10%, 25-pF load, 60/40 duty cycle
SID246	$F_{GPIOIN}$	GPIO input operating frequency; $1.71\text{ V} \leq V_{DD} \leq 3.6\text{ V}$	–	–	100	MHz	90/10% $V_{IO}$

**Analog Peripherals**
*Low-Power (LP) Comparator*
**Table 19. LP Comparator DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID84	V <sub>OFFSET1</sub>	Input offset voltage. Normal power mode.	-10	-	10	mV	-
SID85A	V <sub>OFFSET2</sub>	Input offset voltage. Low-power mode.	-25	±12	25	mV	-
SID85B	V <sub>OFFSET3</sub>	Input offset voltage. Ultra low-power mode.	-25	±12	25	mV	-
SID86	V <sub>HYST1</sub>	Hysteresis when enabled in Normal mode	-	-	60	mV	-
SID86A	V <sub>HYST2</sub>	Hysteresis when enabled in Low-power mode	-	-	80	mV	-
SID87	V <sub>ICM1</sub>	Input common mode voltage in Normal mode	0	-	V <sub>DDIO1</sub> - 0.1	V	-
SID247	V <sub>ICM2</sub>	Input common mode voltage in Low power mode	0	-	V <sub>DDIO1</sub> - 0.1	V	-
SID247A	V <sub>ICM3</sub>	Input common mode voltage in Ultra low power mode	0	-	V <sub>DDIO1</sub> - 0.1	V	-
SID88	CMRR	Common mode rejection ratio in Normal power mode	50	-	-	dB	-
SID89	I <sub>CMP1</sub>	Block current, Normal mode	-	-	150	µA	-
SID248	I <sub>CMP2</sub>	Block current, Low-power mode	-	-	10	µA	-
SID259	I <sub>CMP3</sub>	Block current in Ultra low-power mode	-	0.3	0.85	µA	-
SID90	ZCMP	DC input impedance of comparator	35	-	-	MΩ	-

**Table 20. LP Comparator AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
<b>LP Comparator AC Specifications</b>							
SID91	T <sub>RESP1</sub>	Response time, Normal mode, 100 mV overdrive	-	-	100	ns	-
SID258	T <sub>RESP2</sub>	Response time, Low power mode, 100 mV overdrive	-	-	1000	ns	-
SID92	T <sub>RESP3</sub>	Response time, Ultra-low power mode, 100 mV overdrive	-	-	20	µs	-
SID92E	T <sub>CMP_EN1</sub>	Time from Enabling to operation	-	-	10	µs	Normal and low-power modes
SID92F	T <sub>CMP_EN2</sub>	Time from Enabling to operation	-	-	50	µs	Ultra-low-power mode

*Temperature Sensor*
**Table 21. Temperature Sensor Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID93	T <sub>SENSACC</sub>	Temperature sensor accuracy	-5	±1	5	°C	-40 to +85 °C

*Internal Reference*
**Table 22. Internal Reference Specification**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID93R	V <sub>REFBG</sub>	-	1.188	1.2	1.212	V	-

*SAR ADC*
**Table 23. 12-bit SAR ADC DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID94	A_RES	SAR ADC Resolution	-	-	12	bits	
SID95	A_CHNLS_S	Number of channels - single-ended	-	-	16		8 full speed.
SID96	A-CHNKS_D	Number of channels - differential	-	-	8		Diff inputs use neighboring I/O
SID97	A-MONO	Monotonicity	-	-	-		Yes.
SID98	A_GAINERR	Gain error	-	-	±0.2	%	With external reference.
SID99	A_OFFSET	Input offset voltage	-	-	2	mV	Measured with 1-V reference
SID100	A_ISAR_1	Current consumption at 1 Msps	-	-	1.05	mA	At 1 Msps. External reference mode
SID100A	A_ISAR_2	Current consumption at 1 Msps	-	-	1.3	mA	At 1 Msps. Internal reference mode
SID1002	A_ISAR_3	Current consumption at 2 Msps	-	-	1.65	mA	At 2 Msps. External reference mode
SID1003	A_ISAR_4	Current consumption at 2 Msps	-	-	2.15	mA	At 2 Msps. Internal reference mode
SID101	A_VINS	Input voltage range - single-ended	V <sub>SS</sub>	-	V <sub>DDA</sub>	V	
SID102	A_VIND	Input voltage range - differential	V <sub>SS</sub>	-	V <sub>DDA</sub>	V	
SID103	A_INRES	Input resistance	-	1	-	kΩ	
SID104	A_INCAP	Input capacitance	-	5	-	pF	

**Table 24. 12-bit SAR ADC AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID106	A_PSRR	Power supply rejection ratio	70	-	-	dB	
SID107	A_CMRR	Common mode rejection ratio	66	-	-	dB	Measured at 1 V
SID1081	A_SAMP_1	Sample rate with external reference With bypass cap	-	-	2	Msps	V <sub>DDA</sub> 2.7 - 3.6
SID1082	A_SAMP_1	Sample rate with external reference With bypass cap	-	-	1	Msps	V <sub>DDA</sub> 1.7 - 3.6
SID108A1	A_SAMP_2	Sample rate with V <sub>DD</sub> reference; No bypass cap	-	-	2	Msps	V <sub>DDA</sub> 2.7 - 3.6
SID108A2	A_SAMP_2	Sample rate with V <sub>DD</sub> reference; No bypass cap	-	-	1	Msps	V <sub>DDA</sub> 1.7 - 3.6
SID108B	A_SAMP_3	Sample rate with internal reference; With bypass cap	-	-	1	Msps	-

**Table 24. 12-bit SAR ADC AC Specifications (continued)**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID108C	A_SAMP_4	Sample rate with Internal Reference. No bypass cap	–	–	200	ksps	–
SID109	A_SINAD	Signal-to-noise and distortion ratio (SINAD).	64	–	–	dB	Fin = 10 kHz
SID111A	A_INL	Integral non-linearity. Up to 1 Msps	–2	–	2	LSB	All Reference Mode
SID111B	A_INL	Integral non-linearity. 2 Msps.	–2.5	–	2.5	LSB	External Reference or V <sub>DDA</sub> Reference Mode, V <sub>REF</sub> ≥ 2 V. V <sub>DDA</sub> = 2.7 V to 3.6 V
SID112A	A_DNL	Differential non-linearity. Up to 1Msps	–1	–	1.5	LSB	All Reference Modes
SID112B	A_DNL	Differential non-linearity. 2Msps.	–1	–	1.6	LSB	External Reference or V <sub>DDA</sub> Reference Mode, V <sub>REF</sub> ≥ 2V. V <sub>DDA</sub> = 2.7 to 3.6 V
SID113	A_THD	Total harmonic distortion. 1 Msps.	–	–	–65	dB	Fin = 10 kHz. V <sub>DDA</sub> = 2.7 to 3.6 V.

**CSD**
**Table 25. CapSense Sigma-Delta (CSD) Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>CSD V2 Specifications</b>							
SYS.PER#3	V <sub>DD_RIPPLE</sub>	Max allowed ripple on power supply, DC to 10 MHz	–	–	±50	mV	V <sub>DDA</sub> > 2 V (with ripple), 25 °C T <sub>A</sub> , Sensitivity = 0.1 pF
SYS.PER#16	V <sub>DD_RIPPLE_1.8</sub>	Max allowed ripple on power supply, DC to 10 MHz	–	–	±25	mV	V <sub>DDA</sub> > 1.75 V (with ripple), 25 °C T <sub>A</sub> , Parasitic Capacitance (C <sub>P</sub> ) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	I <sub>CSD</sub>	Maximum block current	–	–	4500	µA	–
SID.CSD#15	V <sub>REF</sub>	Voltage reference for CSD and Comparator	0.6	1.2	V <sub>DDA</sub> – 0.6	V	V <sub>DDA</sub> – V <sub>REF</sub> ≥ 0.6 V
SID.CSD#15A	V <sub>REF_EXT</sub>	External Voltage reference for CSD and Comparator	0.6	–	V <sub>DDA</sub> – 0.6	V	V <sub>DDA</sub> – V <sub>REF</sub> ≥ 0.6 V
SID.CSD#16	I <sub>DAC1IDD</sub>	IDAC1 (7-bits) block current	–	–	1900	µA	–
SID.CSD#17	I <sub>DAC2IDD</sub>	IDAC2 (7-bits) block current	–	–	1900	µA	–
SID308	V <sub>CSD</sub>	Voltage range of operation	1.7	–	3.6	V	1.71 to 3.6 V
SID308A	V <sub>COMPIDAC</sub>	Voltage compliance range of IDAC	0.6	–	V <sub>DDA</sub> – 0.6	V	V <sub>DDA</sub> – V <sub>REF</sub> ≥ 0.6 V
SID309	I <sub>DAC1DNL</sub>	DNL	–1	–	1	LSB	–
SID310	I <sub>DAC1INL</sub>	INL	–3	–	3	LSB	If V <sub>DDA</sub> < 2 V then for LSB of 2.4 µA or less
SID311	I <sub>DAC2DNL</sub>	DNL	–1	–	1	LSB	–
SID312	I <sub>DAC2INL</sub>	INL	–3	–	3	LSB	If V <sub>DDA</sub> < 2 V then for LSB of 2.4 µA or less
SNRC of the following is Ratio of counts of finger to noise. Guaranteed by characterization.							
SID313_1A	SNRC_1	SRSS reference. IMO + FLL clock source. 0.1-pF sensitivity.	5	–	–	Ratio	9.5-pF max. capacitance

**Table 25. CapSense Sigma-Delta (CSD) Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID313_1B	SNRC_2	SRSS reference. IMO + FLL clock source. 0.3-pF sensitivity.	5	–	–	Ratio	31-pF max. capacitance
SID313_1C	SNRC_3	SRSS reference. IMO + FLL clock source. 0.6-pF sensitivity.	5	–	–	Ratio	61-pF max. capacitance
SID313_2A	SNRC_4	PASS reference. IMO + FLL clock source. 0.1-pF sensitivity.	5	–	–	Ratio	12-pF max. capacitance
SID313_2B	SNRC_5	PASS reference. IMO + FLL clock source. 0.3-pF sensitivity.	5	–	–	Ratio	47-pF max. capacitance
SID313_2C	SNRC_6	PASS reference. IMO + FLL clock source. 0.6-pF sensitivity.	5	–	–	Ratio	86-pF max. capacitance
SID313_3A	SNRC_7	PASS reference. IMO + PLL clock source. 0.1-pF sensitivity.	5	–	–	Ratio	27-pF max. capacitance
SID313_3B	SNRC_8	PASS reference. IMO + PLL clock source. 0.3-pF sensitivity.	5	–	–	Ratio	86-pF max. capacitance
SID313_3C	SNRC_9	PASS reference. IMO + PLL clock source. 0.6-pF sensitivity.	5	–	–	Ratio	168 pF Max. capacitance
SID314	IDAC <sub>1</sub> CRT1	Output current of IDAC1 (7 bits) in low range	4.2		5.7	μA	LSB = 37.5-nA typ.
SID314A	IDAC <sub>1</sub> CRT2	Output current of IDAC1 (7 bits) in medium range	33.7		45.6	μA	LSB = 300-nA typ.
SID314B	IDAC <sub>1</sub> CRT3	Output current of IDAC1 (7 bits) in high range	270		365	μA	LSB = 2.4-μA typ.
SID314C	IDAC <sub>1</sub> CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8		11.4	μA	LSB = 37.5-nA typ. 2X output stage
SID314D	IDAC <sub>1</sub> CRT22	Output current of IDAC1 (7 bits) in medium range, 2X mode	67		91	μA	LSB = 300-nA typ. 2X output stage
SID314E	IDAC <sub>1</sub> CRT32	Output current of IDAC1 (7 bits) in high range, 2X mode. V <sub>DDA</sub> > 2 V	540		730	μA	LSB = 2.4-μA typ. 2X output stage
SID315	IDAC <sub>2</sub> CRT1	Output current of IDAC2 (7 bits) in low range	4.2		5.7	μA	LSB = 37.5-nA typ.
SID315A	IDAC <sub>2</sub> CRT2	Output current of IDAC2 (7 bits) in medium range	33.7		45.6	μA	LSB = 300-nA typ.
SID315B	IDAC <sub>2</sub> CRT3	Output current of IDAC2 (7 bits) in high range	270		365	μA	LSB = 2.4-μA typ.
SID315C	IDAC <sub>2</sub> CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8		11.4	μA	LSB = 37.5-nA typ. 2X output stage
SID315D	IDAC <sub>2</sub> CRT22	Output current of IDAC2 (7 bits) in medium range, 2X mode	67		91	μA	LSB = 300-nA typ. 2X output stage
SID315E	IDAC <sub>2</sub> CRT32	Output current of IDAC2 (7 bits) in high range, 2X mode. V <sub>DDA</sub> > 2V	540		730	μA	LSB = 2.4-μA typ. 2X output stage
SID315F	IDAC <sub>3</sub> CRT13	Output current of IDAC in 8-bit mode in low range	8		11.4	μA	LSB = 37.5-nA typ.
SID315G	IDAC <sub>3</sub> CRT23	Output current of IDAC in 8-bit mode in medium range	67		91	μA	LSB = 300-nA typ.
SID315H	IDAC <sub>3</sub> CRT33	Output current of IDAC in 8-bit mode in high range. V <sub>DDA</sub> > 2V	540		730	μA	LSB = 2.4-μA typ.
SID320	IDAC <sub>OFFSET</sub>	All zeroes input	–	–	1	LSB	Polarity set by Source or Sink

**Table 25. CapSense Sigma-Delta (CSD) Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID321	IDAC <sub>GAIN</sub>	Full-scale error less offset	–	–	±15	%	LSB = 2.4-µA typ.
SID322	IDAC <sub>MISMATCH1</sub>	Mismatch between IDAC1 and IDAC2 in Low mode	–	–	9.2	LSB	LSB = 37.5-nA typ.
SID322A	IDAC <sub>MISMATCH2</sub>	Mismatch between IDAC1 and IDAC2 in Medium mode	–	–	6	LSB	LSB = 300-nA typ.
SID322B	IDAC <sub>MISMATCH3</sub>	Mismatch between IDAC1 and IDAC2 in High mode	–	–	5.8	LSB	LSB = 2.4-µA typ.
SID323	IDAC <sub>SET8</sub>	Settling time to 0.5 LSB for 8-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID324	IDAC <sub>SET7</sub>	Settling time to 0.5 LSB for 7-bit IDAC	–	–	10	µs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor.	–	2.2	–	nF	5-V rating, X7R or NP0 cap.

**Table 26. CSD ADC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
CSDv2 ADC Specifications							
SIDA94	A_RES	Resolution	–	–	10	bits	Auto-zeroing is required every milli-second
SID95	A_CHNLS_S	Number of channels - single ended	–	–	–	16	–
SIDA97	A-MONO	Monotonicity	–	–	Yes	–	V <sub>REF</sub> mode
SIDA98	A_GAINERR_VREF	Gain error	–	0.6	–	%	Reference Source: SRSS (V <sub>REF</sub> = 1.20 V, V <sub>DDA</sub> < 2.2 V), (V <sub>REF</sub> = 1.6 V, 2.2 V < V <sub>DDA</sub> < 2.7 V), (V <sub>REF</sub> = 2.13 V, V <sub>DDA</sub> > 2.7 V)
SIDA98A	A_GAINERR_VDDA	Gain error	–	0.2	–	%	Reference Source: SRSS (V <sub>REF</sub> =1.20 V, V <sub>DDA</sub> < 2.2V), (V <sub>REF</sub> =1.6 V, 2.2 V < V <sub>DDA</sub> < 2.7 V), (V <sub>REF</sub> = 2.13 V, V <sub>DDA</sub> > 2.7 V)
SIDA99	A_OFFSET_VREF	Input offset voltage	–	0.5	–	LSB	After ADC calibration, Ref. Src = SRSS, (V <sub>REF</sub> = 1.20 V, V <sub>DDA</sub> < 2.2 V), (V <sub>REF</sub> = 1.6 V, 2.2 V < V <sub>DDA</sub> < 2.7 V), (V <sub>REF</sub> = 2.13 V, V <sub>DDA</sub> > 2.7 V)
SIDA99A	A_OFFSET_VDDA	Input offset voltage	–	0.5	–	LSB	After ADC calibration, Ref. Src = SRSS, (V <sub>REF</sub> = 1.20 V, V <sub>DDA</sub> < 2.2 V), (V <sub>REF</sub> = 1.6 V, 2.2 V < V <sub>DDA</sub> < 2.7 V), (V <sub>REF</sub> = 2.13 V, V <sub>DDA</sub> > 2.7 V)
SIDA100	A_ISAR_VREF	Current consumption	–	0.3	–	mA	CSD ADC Block current
SIDA100A	A_ISAR_VDDA	Current consumption	–	0.3	–	mA	CSD ADC Block current

**Table 26. CSD ADC Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SIDA101	A_VINS_VREF	Input voltage range - single ended	V <sub>SSA</sub>	–	V <sub>REF</sub>	V	(V <sub>REF</sub> = 1.20 V, V <sub>D<sub>DDA</sub></sub> < 2.2 V), (V <sub>REF</sub> = 1.6 V, 2.2 V < V <sub>D<sub>DDA</sub></sub> < 2.7 V), (V <sub>REF</sub> = 2.13 V, V <sub>D<sub>DDA</sub></sub> > 2.7 V)
SIDA101A	A_VINS_VDDA	Input voltage range - single ended	V <sub>SSA</sub>	–	V <sub>D<sub>DDA</sub></sub>	V	(V <sub>REF</sub> = 1.20 V, V <sub>D<sub>DDA</sub></sub> < 2.2 V), (V <sub>REF</sub> = 1.6 V, 2.2 V < V <sub>D<sub>DDA</sub></sub> < 2.7 V), (V <sub>REF</sub> = 2.13 V, V <sub>D<sub>DDA</sub></sub> > 2.7 V)
SIDA103	A_INRES	Input charging resistance	–	15	–	kΩ	–
SIDA104	A_INCAP	Input capacitance	–	41	–	pF	–
SIDA106	A_PSRR	Power supply rejection ratio (DC)	–	60	–	dB	–
SIDA107	A_TACQ	Sample acquisition time	–	10	–	μs	Measured with 50-Ω source impedance. 10 μs is default software driver acquisition time setting. Settling to within 0.05%.
SIDA108	A_CONV8	Conversion time for 8-bit resolution at conversion rate = F <sub>hclk</sub> / (2 <sup>N</sup> (N + 2)). Clock frequency = 50 MHz.	–	25	–	μs	Does not include acquisition time.
SIDA108A	A_CONV10	Conversion time for 10-bit resolution at conversion rate = F <sub>hclk</sub> / (2 <sup>N</sup> (N + 2)). Clock frequency = 50 MHz.	–	60	–	μs	Does not include acquisition time.
SIDA109	A_SND_VRE	Signal-to-noise and distortion ratio (SINAD)	–	57	–	dB	Measured with 50-Ω source impedance
SIDA109A	A_SND_VDDA	Signal-to-noise and distortion ratio (SINAD)	–	52	–	dB	Measured with 50-Ω source impedance
SIDA111	A_INL_VREF	Integral non-linearity. 11.6 ksps	–	–	2	LSB	Measured with 50-Ω source impedance
SIDA111A	A_INL_VDDA	Integral non-linearity. 11.6 ksps	–	–	2	LSB	Measured with 50-Ω source impedance
SIDA112	A_DNL_VREF	Differential non-linearity. 11.6 ksps	–	–	1	LSB	Measured with 50-Ω source impedance
SIDA112A	A_DNL_VDDA	Differential non-linearity. 11.6 ksps	–	–	1	LSB	Measured with 50-Ω source impedance

**Digital Peripherals**
*Timer/Counter/PWM*
**Table 27. Timer/Counter/PWM (TCPWM) Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.TCPWM.1	$I_{TCPWM1}$	Block current consumption at 8 MHz	–	–	70	$\mu\text{A}$	All modes (TCPWM)
SID.TCPWM.2	$I_{TCPWM2}$	Block current consumption at 24 MHz	–	–	180	$\mu\text{A}$	All modes (TCPWM)
SID.TCPWM.2A	$I_{TCPWM3}$	Block current consumption at 50 MHz	–	–	270	$\mu\text{A}$	All modes (TCPWM)
SID.TCPWM.2B	$I_{TCPWM4}$	Block current consumption at 100 MHz	–	–	540	$\mu\text{A}$	All modes (TCPWM)
SID.TCPWM.3	$TCPWM_{FREQ}$	Operating frequency	–	–	100	MHz	Maximum = 100 MHz
SID.TCPWM.4	$TPWM_{ENEXT}$	Input trigger pulse width for all trigger events	$2/F_c$	–	–	ns	Trigger events can be Stop, Start, Reload, Count, Capture, or Kill depending on which mode of operation is selected. $F_c$ is counter operating frequency.
SID.TCPWM.5	$TPWM_{EXT}$	Output trigger pulse widths	$1.5/F_c$	–	–	ns	Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) trigger outputs
SID.TCPWM.5A	$TC_{RES}$	Resolution of counter	$1/F_c$	–	–	ns	Minimum time between successive counts
SID.TCPWM.5B	$PWM_{RES}$	PWM resolution	$1/F_c$	–	–	ns	Minimum pulse width of PWM output
SID.TCPWM.5C	$Q_{RES}$	Quadrature inputs resolution	$2/F_c$	–	–	ns	Minimum pulse width between Quadrature phase inputs. Delays from pins should be similar.

*Serial Communication Block (SCB)*
**Table 28. Serial Communication Block (SCB) Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>Fixed I<sup>2</sup>C DC Specifications</b>							
SID149	$I_{I2C1}$	Block current consumption at 100 kHz	–	–	30	$\mu\text{A}$	–
SID150	$I_{I2C2}$	Block current consumption at 400 kHz	–	–	80	$\mu\text{A}$	–
SID151	$I_{I2C3}$	Block current consumption at 1 Mbps	–	–	180	$\mu\text{A}$	–
SID152	$I_{I2C4}$	I <sup>2</sup> C enabled in Deep Sleep mode	–	–	1.7	$\mu\text{A}$	At 60°C.
<b>Fixed I<sup>2</sup>C AC Specifications</b>							
SID153	$F_{I2C1}$	Bit Rate	–	–	1	Mbps	–
<b>Fixed UART DC Specifications</b>							
SID160	$I_{UART1}$	Block current consumption at 100 kbps	–	–	30	$\mu\text{A}$	–
SID161	$I_{UART2}$	Block current consumption at 1000 kbps	–	–	180	$\mu\text{A}$	–
<b>Fixed UART AC Specifications</b>							
SID162A	$F_{UART1}$	Bit Rate	–	–	3	Mbps	ULP Mode
SID162B	$F_{UART2}$		–	–	8		LP Mode
<b>Fixed SPI DC Specifications</b>							
SID163	$I_{SPI1}$	Block current consumption at 1 Mbps	–	–	220	$\mu\text{A}$	–

**Table 28. Serial Communication Block (SCB) Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID164	I <sub>SPI2</sub>	Block current consumption at 4 Mbps	–	–	340	μA	–
SID165	I <sub>SPI3</sub>	Block current consumption at 8 Mbps	–	–	360	μA	–
SID165A	I <sub>SPI4</sub>	Block current consumption at 25 Mbps	–	–	800	μA	–
<b>Fixed SPI AC Specifications for LP Mode (1.1 V) unless noted otherwise.</b>							
SID166	F <sub>SPI</sub>	SPI Operating frequency externally clocked slave	–	–	25	MHz	12-MHz max for ULP (0.9 V) mode
SID166B	F <sub>SPI_EXT</sub>	SPI operating frequency master (F <sub>scb</sub> is SPI clock).	–	–	F <sub>scb</sub> /4	MHz	F <sub>scb</sub> max is 100 MHz in LP (1.1 V) mode, 25 MHz in ULP mode.
SID166A	F <sub>SPI_IC</sub>	SPI slave internally clocked	–	–	15	MHz	5 MHz max for ULP (0.9 V) mode
<b>Fixed SPI Master mode AC Specifications for LP Mode (1.1 V) unless noted otherwise.</b>							
SID167	T <sub>DMO</sub>	MOSI valid after SClk driving edge	–	–	12	ns	20 ns max for ULP (0.9 V) mode
SID168	T <sub>DSI</sub>	MISO valid before SClk capturing edge	5	–	–	ns	Full clock, late MISO sampling
SID169	T <sub>HMO</sub>	MOSI data hold time	0	–	–	ns	Referred to Slave capturing edge
<b>Fixed SPI Slave mode AC Specifications for LP Mode (1.1 V) unless noted otherwise.</b>							
SID170	T <sub>DMI</sub>	MOSI valid before Sclck capturing edge	5	–	–	ns	–
SID171A	T <sub>D<sub>SO</sub>_EXT</sub>	MISO valid after Sclck driving edge in Ext. Clk. mode	–	–	20	ns	35 ns max. for ULP (0.9 V) mode
SID171	T <sub>D<sub>SO</sub></sub>	MISO valid after Sclck driving edge in Internally Clk. mode	–	–	T <sub>D<sub>SO</sub>_EXT</sub> + 3 * T <sub>scb</sub>	ns	T <sub>scb</sub> is Serial Comm. Block clock period.
SID171B	T <sub>D<sub>SO</sub></sub>	MISO Valid after Sclck driving edge in Internally Clk. Mode with median filter enabled.	–	–	T <sub>D<sub>SO</sub>_EXT</sub> + 4 * T <sub>scb</sub>	ns	T <sub>scb</sub> is Serial Comm. Block clock period.
SID172	T <sub>H<sub>SO</sub></sub>	Previous MISO data hold time	5	–	–	ns	–
SID172A	TSSEL <sub>SCK1</sub>	SSEL Valid to first SCK valid edge	65	–	–	ns	–
SID172B	TSSEL <sub>SCK2</sub>	SSEL Hold after Last SCK valid edge	65	–	–	ns	–

*LCD Specifications*
**Table 29. LCD Direct Drive DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID154	I <sub>LCDLOW1</sub>	Operating current with 100-kHz LCD block clock in ULP mode in Deep Sleep	–	90	–	μA	32×4 small display. 30-Hz. PWM mode. Slow slew rate. 460-kΩ series resistors
SID154A	I <sub>LCDLOW2</sub>	Operating current with 32- kHz LCD block clock in ULP mode in Deep Sleep	–	50	–	μA	32×4 small display. 30-Hz. PWM mode. Slow slew rate. 460-kΩ series resistors
SID155	C <sub>LDCAP</sub>	LCD capacitance per segment/common driver	–	500	5000	pF	–
SID156	LCD <sub>OFFSET</sub>	Long-term segment offset	–	20	–	mV	–
SID157	I <sub>LCDOP1</sub>	PWM Mode current. 3.3 V bias. 8 MHz IMO. 25 °C.	–	0.6	–	mA	32 × 4 segments 50 Hz
SID158	I <sub>LCDOP2</sub>	PWM Mode current. 3.3 V bias. 8 MHz IMO. 25 °C.	–	0.5	–	mA	32 × 4 segments 50 Hz

**Table 30. LCD Direct Drive AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F <sub>LCD</sub>	LCD frame rate	10	50	150	Hz	–

**Memory**
**Table 31. Flash Specifications<sup>[6]</sup>**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
<b>Flash DC Specifications</b>							
SID173A	IPE	Erase and Program current	–	–	6	mA	
<b>Flash AC Specifications</b>							
SID174	T <sub>ROWWRITE</sub>	Row write time (erase and program)	–	–	16	ms	Row = 512 bytes
SID175	T <sub>ROWERASE</sub>	Row erase time	–	–	11	ms	–
SID176	T <sub>ROWPROGRAM</sub>	Row program time after erase	–	–	5	ms	–
SID178	T <sub>BULKERASE</sub>	Bulk erase time (512 KB)	–	–	11	ms	–
SID179	T <sub>SECTORERASE</sub>	Sector erase time (256 KB)	–	–	11	ms	512 rows per sector
SID178S	T <sub>SSERIAE</sub>	Subsector erase time	–	–	11	ms	8 rows per subsector
SID179S	T <sub>SSWRITE</sub>	Subsector write time; 1 erase plus 8 program times	–	–	51	ms	–
SID180S	T <sub>SWRITE</sub>	Sector write time; 1 erase plus 512 program times	–	–	2.6	seconds	–
SID180	T <sub>DEVPROG</sub>	Total device write time	–	–	7.5	seconds	–
SID181	F <sub>END</sub>	Flash endurance	100K	–	–	cycles	–
SID182	F <sub>RET1</sub>	Flash retention. Ta ≤ 25 °C, 100K P/E cycles	10	–	–	years	–
SID182A	F <sub>RET2</sub>	Flash retention. Ta ≤ 85 °C, 10K P/E cycles	10	–	–	years	–
SID182B	F <sub>RET3</sub>	Flash retention. Ta ≤ 55 °C, 20K P/E cycles	20	–	–	years	–
SID256	T <sub>WS100</sub>	Number of Wait states at 100 MHz	3	–	–		–
SID257	T <sub>WS50</sub>	Number of Wait states at 50 MHz	2	–	–		–

**Note**

4. It can take as much as 16 milliseconds to write to flash. During this time, the device should not be reset, or flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.

**System Resources**
**Table 32. System Resources**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
<b>Power-On-Reset with Brown-out DC Specifications</b>							
<b>Precise POR (PPOR)</b>							
SID190	V <sub>FALLPPOR</sub>	BOD trip voltage in Active and Sleep modes. V <sub>DDD</sub> .	1.54	–	–	V	BOD reset guaranteed for levels below 1.54 V
SID192	V <sub>FALLDPSLP</sub>	BOD trip voltage in Deep Sleep. V <sub>DDD</sub> .	1.54	–	–	V	–
SID192A	V <sub>DDRAMP</sub>	Maximum power supply ramp rate (any supply)	–	–	100	mV/μs	Active mode
<b>POR with Brown-out AC Specification</b>							
SID194A	V <sub>DDRAMP_DS</sub>	Maximum power supply ramp rate (any supply) in Deep Sleep	–	–	10	mV/μs	BOD operation guaranteed
<b>Voltage Monitors DC Specifications</b>							
SID195	V <sub>HVDI1</sub>	–	1.38	1.43	1.47	V	–
SID196	V <sub>HVDI2</sub>	–	1.57	1.63	1.68	V	–
SID197	V <sub>HVDI3</sub>	–	1.76	1.83	1.89	V	–
SID198	V <sub>HVDI4</sub>	–	1.95	2.03	2.1	V	–
SID199	V <sub>HVDI5</sub>	–	2.05	2.13	2.2	V	–
SID200	V <sub>HVDI6</sub>	–	2.15	2.23	2.3	V	–
SID201	V <sub>HVDI7</sub>	–	2.24	2.33	2.41	V	–
SID202	V <sub>HVDI8</sub>	–	2.34	2.43	2.51	V	–
SID203	V <sub>HVDI9</sub>	–	2.44	2.53	2.61	V	–
SID204	V <sub>HVDI10</sub>	–	2.53	2.63	2.72	V	–
SID205	V <sub>HVDI11</sub>	–	2.63	2.73	2.82	V	–
SID206	V <sub>HVDI12</sub>	–	2.73	2.83	2.92	V	–
SID207	V <sub>HVDI13</sub>	–	2.82	2.93	3.03	V	–
SID208	V <sub>HVDI14</sub>	–	2.92	3.03	3.13	V	–
SID209	V <sub>HVDI15</sub>	–	3.02	3.13	3.23	V	–
SID211	LVI_IDD	Block current	–	5	15	μA	–
<b>Voltage Monitors AC Specification</b>							
SID212	T <sub>MONTRIP</sub>	Voltage monitor trip time	–	–	170	ns	–

*SWD Interface*
**Table 33. SWD and Trace Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>SWD and Trace Interface</b>							
SID214	F_SWDCCLK2	$1.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$	–	–	25	MHz	LP Mode. $V_{CCD} = 1.1\text{ V}$ .
SID214L	F_SWDCCLK2L	$1.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$	–	–	12	MHz	ULP Mode. $V_{CCD} = 0.9\text{ V}$ .
SID215	T_SWDI_SETUP	$T = 1/f\text{ SWDCCLK}$	$0.25 * T$	–	–	ns	–
SID216	T_SWDI_HOLD	$T = 1/f\text{ SWDCCLK}$	$0.25 * T$	–	–	ns	–
SID217	T_SWDO_VALID	$T = 1/f\text{ SWDCCLK}$	–	–	$0.5 * T$	ns	–
SID217A	T_SWDO_HOLD	$T = 1/f\text{ SWDCCLK}$	1	–	–	ns	–
SID214T	F_TRCLK_LP1	With Trace Data setup/hold times of 2/1 ns respectively	–	–	50	MHz	LP Mode. $V_{DD} = 1.1\text{ V}$ .
SID215T	F_TRCLK_LP2	With Trace Data setup/hold times of 3/2 ns respectively	–	–	50	MHz	LP Mode. $V_{DD} = 1.1\text{ V}$ .
SID216T	F_TRCLK_ULP	With Trace Data setup/hold times of 3/2 ns respectively	–	–	20	MHz	ULP Mode. $V_{DD} = 0.9\text{ V}$ .

*Internal Main Oscillator*
**Table 34. IMO DC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I <sub>IMO1</sub>	IMO operating current at 8 MHz	–	9	15	μA	–

**Table 35. IMO AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	F <sub>IMOTOL1</sub>	Frequency variation centered on 8 MHz	–	–	±2	%	–
SID227	T <sub>JITR</sub>	Cycle-to-Cycle and Period jitter	–	250	–	ps	–

*Internal Low-Speed Oscillator*
**Table 36. ILO DC Specification**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231	I <sub>ILO2</sub>	ILO operating current at 32 kHz	–	0.3	0.7	μA	–

**Table 37. ILO AC Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234	T <sub>STARTILO1</sub>	ILO startup time	–	–	7	μs	Startup time to 95% of final frequency
SID236	TLIODUTY	ILO Duty cycle	45	50	55	%	–
SID237	F <sub>ILOTRIM1</sub>	32 kHz trimmed frequency	28.8	32	35.2	kHz	±10% variation

*Crystal Oscillator Specifications*
**Table 38. ECO Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
<b>MHz ECO DC Specification</b>							
SID316	I <sub>DD_MHz</sub>	Block operating current with Clload up to 18 pF	–	800	1600	μA	Max = 35 MHz, Typ = 16 MHz
<b>MHz ECO AC Specification</b>							
SID317	F_MHz	Crystal frequency range	16	–	35	MHz	Some restrictions apply. Refer to the <a href="#">device TRM</a> .
<b>kHz ECO DC Specification</b>							
SID318	I <sub>DD_kHz</sub>	Block operating current with 32-kHz crystal	–	0.38	1	μA	–
SID321E	ESR32K	Equivalent series resistance	–	80	–	kΩ	–
SID322E	PD32K	Drive level	–	–	1	μW	–
<b>kHz ECO AC Specification</b>							
SID319	F_kHz	32 kHz frequency	–	32.768	–	kHz	–
SID320	Ton_kHz	Startup time	–	–	500	ms	–
SID320E	F <sub>TOL32K</sub>	Frequency tolerance	–	50	250	ppm	–

*External Clock Specifications*
**Table 39. External Clock Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID305	EXTCLK <sub>FREQ</sub>	External clock input frequency	0	–	100	MHz	–
SID306	EXTCLK <sub>DUTY</sub>	Duty cycle; measured at V <sub>DD</sub> /2	45	–	55	%	–

*PLL Specifications*
**Table 40. PLL Specifications**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID304P	PLL_IN	Input frequency to PLL block	4	–	64	MHz	
SID305P	PLL_LOCK	Time to achieve PLL lock	–	16	35	μs	–
SID306P	PLL_OUT	Output frequency from PLL block	10.625	–	150	MHz	–
SID307P	PLL_IDD	PLL current	–	0.55	1.1	mA	Typ. at 100 MHz out.
SID308P	PLL_JTR	Period jitter	–	–	150	ps	100-MHz output frequency

**Table 41. Clock Source Switching Time**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID262	TCLK <sub>SWITCH</sub>	Clock switching from clk1 to clk2 in clock periods; for example, from IMO (clk1) to FLL (clk2). <sup>[5]</sup>	–	–	4 clk1 + 3 clk2	periods	–

**Note**

5. As an example, if the clk\_path[1] source is changed from the IMO to the FLL (see [Figure 3](#)) then clk1 is the IMO and clk2 is the FLL.

*FLL Specifications*
**Table 42. Frequency Locked Loop (FLL) Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
Frequency Locked Loop (FLL) Specifications							
SID450	FLL_RANGE	Input frequency range.	0.001	–	100	MHz	Lower limit allows lock to USB SOF signal (1 kHz). Upper limit is for External input.
SID451	FLL_OUT_DIV2	Output frequency range. $V_{CCD} = 1.1\text{ V}$	24.00	–	100.00	MHz	Output range of FLL divided-by-2 output
SID451A	FLL_OUT_DIV2	Output frequency range. $V_{CCD} = 0.9\text{ V}$	24.00	–	50.00	MHz	Output range of FLL divided-by-2 output
SID452	FLL_DUTY_DIV2	Divided-by-2 output; High or Low	47.00	–	53.00	%	–
SID454	FLL_WAKEUP	Time from stable input clock to 1% of final value on Deep Sleep wakeup	–	–	7.50	$\mu\text{s}$	With IMO input, less than 10 °C change in temperature while in Deep Sleep, and $F_{out} \geq 50\text{ MHz}$ .
SID455	FLL_JITTER	Period jitter (1 sigma) at 100 MHz	–	–	35.00	ps	50 ps at 48 MHz, 35 ps at 100 MHz
SID456	FLL_CURRENT	CCO + Logic current	–	–	5.50	$\mu\text{A}/\text{MHz}$	–

*USB*
**Table 43. USB Specifications (USB requires LP Mode 1.1-V internal supply)**

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
USB Block Specifications							
SID322U	$V_{USB\_3.3}$	Device supply for USB operation	3.15	–	3.6	V	USB Configured
SID323U	$V_{USB\_3}$	Device supply for USB operation (functional operation only)	2.85	–	3.6	V	USB Configured
SID325U	iusb_config	Block supply current in Active mode	–	8	–	mA	$V_{DDD} = 3.3\text{ V}$
SID328	iusb_suspend	Block supply current in suspend mode	–	0.5	–	mA	$V_{DDD} = 3.3\text{ V}$ , Device connected
SID329	iusb_suspend	Block supply current in suspend mode	–	0.3	–	mA	$V_{DDD} = 3.3\text{ V}$ , Device disconnected
SID330U	USB_Drive_Res	USB driver impedance	28	–	44	$\Omega$	Series resistors are on chip
SID332U	USB_Pullup_Idle	Idle mode range	900	–	1575	$\Omega$	Bus idle
SID333U	USB_Pullup	Active mode	1425	–	3090	$\Omega$	Upstream device transmitting

**Table 44. QSPI Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>SMIF QSPI Specifications. All specs with 15-pF load. Measured from 50% to 50% waveform transitions.</b>							
SID390Q	Fsmifclock	SMIF QSPI output clock frequency	–	–	80	MHz	LP mode (1.1 V)
SID390QU	Fsmifclocku	SMIF QSPI output clock frequency	–	–	50	MHz	ULP mode (0.9 V). Guaranteed by Char.
SID399Q	Clk_dutycycle	Clock duty cycle (high or low time)	45	–	55	%	
SID397Q	Idd_qspi	Block current in LP mode (1.1 V)	–	–	1900	μA	LP mode (1.1 V)
SID398Q	Idd_qspi_u	Block current in ULP mode (0.9 V)	–	–	590	μA	ULP mode (0.9 V)
SID391Q	Tsetup	Input data set-up time with respect to clock capturing falling edge	4.5	–	–	ns	–
SID392Q	Tdatahold	Input data hold time with respect to clock capturing falling edge	1	–	–	ns	–
SID393Q	Tdataoutvalid	Output data valid time with respect to clock falling edge	–	–	3.7	ns	7.5-ns max for ULP mode (0.9 V)
SID394Q	Tholdtime	Output data hold time with respect to clock rising edge	3	–	–	ns	–
SID395Q	Tseloutvalid	Output Select valid time with respect to clock rising edge	–	–	7.5	ns	15-ns max for ULP mode (0.9 V)
SID396Q	Tselouthold	Output Select hold time with respect to clock rising edge	Tsclk/2	–	–	ns	Tsclk = Fsmifclk cycle time

*Smart I/O*
**Table 45. Smart I/O Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID420	SMIO_BYP	Smart I/O bypass delay	–	–	2	ns	–
SID421	SMIO_LUT	Smart I/O LUT prop delay	–	8	–	ns	–

*SD Host Controller and eMMC*
**Table 46. SD Host Controller and eMMC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>SD Host Controller and eMMC Specifications (SD Host clock (see the <a href="#">Clocking Diagram</a>) must be divided by 2 or more when used as source in DDR modes. Specs are Guaranteed by Design.)</b>							
SID_SD390	SD_DS	I/O drive select	4	–	4	mA	drive_sel = '01' for all modes
SID_SD391	SD_TR	Input transition time	0.7	–	3	ns	–
<b>SD:DS Timing</b>							
SID_SD392	SD_CLK	Interface clock period (LP mode)	–	–	25	MHz	(40-ns period)
SID_SD393	SD_CLK	Interface clock period (ULP mode)	–	–	8	MHz	(125-ns period)
SID_SD394	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	30	–	pF	–
SID_SD395	SD_CLK_CL	I/O loading at CLK pins	–	30	–	pF	–
SID_SD396	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	5.1	–	–	ns	–

**Table 46. SD Host Controller and eMMC Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID_SD397	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	5.1	–	–	ns	–
SID_SD398	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	24	–	–	ns	–
SID_SD399	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	109	–	–	ns	–
SID_SD400	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	0	–	–	ns	–
<b>SD:HS Timing</b>							
SID_SD401	SD_CLK	Interface clock period (LP mode)	–	–	45	MHz	(22.5-ns period)
SID_SD402	SD_CLK	Interface clock period (ULP mode)	–	–	16	MHz	(62.5-ns period)
SID_SD403	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	30	–	pF	–
SID_SD404	SD_CLK_CL	I/O loading at CLK pins	–	30	–	pF	–
SID_SD405	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	6.1	–	–	ns	–
SID_SD406	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	2.1	–	–	ns	–
SID_SD407	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	8	–	–	ns	–
SID_SD408	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	48.3	–	–	ns	–
SID_SD409	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	2.5	–	–	ns	–
<b>SD:SDR-12 Timing</b>							
SID_SD410	SD_CLK	Interface clock period (LP mode)	–	–	25	MHz	(40-ns period)
SID_SD411	SD_CLK	Interface clock period (ULP mode)	–	–	8	MHz	(125-ns period)
SID_SD412	SD_CLK_DC	Duty cycle of output CLK	30	–	70	%	–
SID_SD413	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	30	–	pF	–
SID_SD414	SD_CLK_CL	I/O loading at CLK pins	–	30	–	pF	–
SID_SD415	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	3.1	–	–	ns	–
SID_SD416	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	0.9	–	–	ns	–
SID_SD417	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	24	–	–	ns	–
SID_SD418	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	109	–	–	ns	–
SID_SD419	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	1.5	–	–	ns	–
<b>SD:SDR-25 Timing</b>							
SID_SD420	SD_CLK	Interface clock period (LP mode)	–	–	50	MHz	(20-ns period)
SID_SD421	SD_CLK	Interface clock period (ULP mode)	–	–	16	MHz	(62.5-ns period)
SID_SD422	SD_CLK_DC	Duty cycle of output CLK	30	–	70	%	–
SID_SD423	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	30	–	pF	–
SID_SD424	SD_CLK_CL	I/O loading at CLK pins	–	30	–	pF	–

**Table 46. SD Host Controller and eMMC Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID_SD425	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	3.1	–	–	ns	–
SID_SD426	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	0.9	–	–	ns	–
SID_SD427	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	5.8	–	–	ns	–
SID_SD428	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	48.3	–	–	ns	–
SID_SD429	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	1.5	–	–	ns	–
<b>SD:SDR-50 Timing</b>							
SID_SD430	SD_CLK	Interface clock period (LP mode)	–	–	80	MHz	(12.5-ns period)
SID_SD431	SD_CLK	Interface clock period (ULP mode)	–	–	32	MHz	(31.25-ns period)
SID_SD432	SD_CLK_DC	Duty cycle of output CLK	30	–	70	%	–
SID_SD433	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	20	–	pF	–
SID_SD434	SD_CLK_CL	I/O loading at CLK pins	–	20	–	pF	–
SID_SD435	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	3.1	–	–	ns	–
SID_SD436	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	0.9	–	–	ns	–
SID_SD437	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	5	–	–	ns	–
SID_SD438	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	23.6	–	–	ns	–
SID_SD439	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	1.5	–	–	ns	–
<b>SD:DDR-50 Timing</b>							
SID_SD440	SD_CLK	Interface clock period (LP mode)	–	–	40	MHz	(25-ns period).
SID_SD441	SD_CLK	Interface clock period (ULP mode)	–	–	16	MHz	(62.5-ns period)
SID_SD442	SD_CLK_DC	Duty cycle of output CLK	45	–	55	%	–
SID_SD443	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	30	–	pF	–
SID_SD444	SD_CLK_CL	I/O loading at CLK pins	–	30	–	pF	–
SID_SD445	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	3.1	–	–	ns	–
SID_SD446	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	0.9	–	–	ns	–
SID_SD447	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	5.7	–	–	ns	–
SID_SD448	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	24	–	–	ns	–
SID_SD449	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	1.5	–	–	ns	–
<b>eMMC:BWC Timing</b>							
SID_SD450	SD_CLK	Interface clock period (LP mode)	–	–	26	MHz	(38.4-ns period)
SID_SD451	SD_CLK	Interface clock period (ULP mode)	–	–	8	MHz	(125-ns period)
SID_SD452	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	30	–	pF	–

**Table 46. SD Host Controller and eMMC Specifications (continued)**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID_SD453	SD_CLK_CL	I/O loading at CLK pins	–	30	–	pF	–
SID_SD454	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	3.1	–	–	ns	–
SID_SD455	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	3.1	–	–	ns	–
SID_SD456	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	9.7	–	–	ns	–
SID_SD457	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	96.3	–	–	ns	–
SID_SD458	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	8.3	–	–	ns	–
<b>eMMC:SDR Timing</b>							
SID_SD459	SD_CLK	Interface clock period (LP mode)	–	–	52	MHz	(19.2-ns period)
SID_SD460	SD_CLK	Interface clock period (ULP mode)	–	–	16	MHz	(62.5-ns period)
SID_SD461	SD_DCMD_CL	I/O loading at DATA/CMD pins	–	30	–	pF	–
SID_SD462	SD_CLK_CL	I/O loading at CLK pins	–	30	–	pF	–
SID_SD463	SD_TS_OUT	Output: Setup time of CMD/DAT prior to CLK	3.1	–	–	ns	–
SID_SD464	SD_HLD_OUT	Output: Hold time of CMD/DAT after CLK	3.1	–	–	ns	–
SID_SD465	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (LP mode)	5.3	–	–	ns	–
SID_SD466	SD_TS_IN	Input: Setup time of CMD/DAT prior to CLK (ULP mode)	48.6	–	–	ns	–
SID_SD467	SD_HLD_IN	Input: Hold time of CMD/DAT after CLK	2.5	–	–	ns	–
<b>SD Host Block Current Specs</b>							
SID400SD	IDD_SD_1	SD Host block current consumption at 100 MHz	–	4.65	5	mA	SDR-50
SID401SD	IDD_SD_2	SD Host block current consumption at 50 MHz	–	3.75	4.3	mA	SDR-25

**JTAG Boundary Scan**
**Table 47. JTAG Boundary Scan**

Spec ID#	Parameter	Min	Typ	Max	Units	Details / Conditions
<b>JTAG Boundary Scan Parameters</b>						
<b>JTAG Boundary Scan Parameters for 1.1 V (LP) Mode Operation:</b>						
SID468	TCKLOW	TCK LOW	52	–	–	ns
SID469	TCKHIGH	TCK HIGH	10	–	–	ns
SID470	TCK_TDO	TCK falling edge to output valid	–	–	40	ns
SID471	TSU_TCK	Input valid to TCK rising edge	12	–	–	ns
SID472	Tck_THD	Input hold time to TCK rising edge	10	–	–	ns
SID473	TCK_TDOV	TCK falling edge to output valid (High-Z to Active).	40	–	–	ns
SID474	TCK_TDOZ	TCK falling edge to output valid (Active to High-Z).	40	–	–	ns

**Table 47. JTAG Boundary Scan** *(continued)*

Spec ID#	Parameter	Min	Typ	Max	Units	Details / Conditions
<b>JTAG Boundary Scan Parameters for 0.9 V (ULP) Mode Operation:</b>						
SID468A	TCKLOW	TCK low	102	–	–	ns –
SID469A	TCKHIGH	TCK high	20	–	–	ns –
SID470A	TCK_TDO	TCK falling edge to output valid		–	80	ns –
SID471A	TSU_TCK	Input valid to TCK rising edge	22	–	–	ns –
SID472A	Tck_THD	Input hold time to TCK rising edge	20	–	–	ns –
SID473A	TCK_TDOV	TCK falling edge to output valid (high-Z to active).	80	–	–	ns –
SID474A	TCK_TDOZ	TCK falling edge to output valid (active to high-Z).	80	–	–	ns –

## Ordering Information

Table 49 lists the CY8C62x5 part numbers and features. See also the [product selector guide](#).

**Table 48. Ordering Information**

Family	Base Features	Marketing Part Number	Flash (KB)	SRAM (KB)	CapSense	CAN FD	Crypto	USB	GPIO	Package
Performance Line	Arm CM4 and CM0+, DC-DC converter, 12-bit SAR ADC, 2 LPCOMPs, 7 SCBs, 12 TCPWMs, SD Host Controller	CY8C6245AZI-S3D72	512	256	Y	1	Y	Y	64	100-TQFP
		CY8C6245LQI-S3D72	512	256	Y	1	Y	Y	53	68-QFN
		CY8C6245FNI-S3D71	512	256	Y	1	Y	–	37	49-WLCSP
		CY8C6245AZI-S3D62	512	256	–	1	–	Y	64	100-TQFP
		CY8C6245LQI-S3D62	512	256	–	1	–	Y	53	68-QFN
		CY8C6245AZI-S3D42	512	256	Y	–	Y	Y	64	100-TQFP
		CY8C6245LQI-S3D42	512	256	Y	–	Y	Y	53	68-QFN
		CY8C6245FNI-S3D41	512	256	Y	–	Y	–	37	49-WLCSP
		CY8C6245AZI-S3D12	512	256	Y	–	–	Y	64	100-TQFP
		CY8C6245LQI-S3D12	512	256	Y	–	–	Y	53	68-QFN
		CY8C6245FNI-S3D11	512	256	Y	–	–	–	37	49-WLCSP
		CY8C6245AZI-S3D02	512	256	–	–	–	Y	64	100-TQFP
CY8C6245LQI-S3D02	512	256	–	–	–	Y	53	68-QFN		

**PSoC 6 MPN Decoder**
**CY XX 6 A B C DD E - FF G H I JJ K L**

Field	Description	Values	Meaning
CY	Cypress	CY	Cypress
XX	Firmware	8C	Standard
		B0	“Secure Boot” v1
		S0	“Standard Secure” - AWS
6	Architecture	6	PSoC 6
A	Line	0	Value
		1	Programmable
		2	Performance
		3	Connectivity
		4	Secured
B	Speed	2	100 MHz
		3	150 MHz
		4	150/50 MHz
C	Memory Size (Flash/SRAM)	0-3	Reserved
		4	256K/128K
		5	512K/256K
		6	512K/128K
		7	1024K/288K
		8	1024K/512K
		9	Reserved
A	2048K/1024K		
DD	Package	AZ, AX	TQFP
		LQ	QFN
		BZ	BGA
		FM	M-CSP
		FN, FD, FT	WLCSP

Field	Description	Values	Meaning
E	Temperature Range	C	Consumer
		I	Industrial
		Q	Extended Industrial
FF	Feature Code		Cypress internal
		S2-S6	
		BL	Integrated Bluetooth LE
G	CPU Core	F	Single Core
		D	Dual Core
H	Attributes Code	0–9	Feature set
I	GPIO count	1	31-50
		2	51-70
		3	71-90
		4	91-110
JJ	Engineering sample (optional)	ES	Engineering samples or not
K	Die Revision (optional)		Base
		A1-A9	Die revision
L	Tape/Reel Shipment (optional)	T	Tape and Reel shipment

## Packaging

This product line is offered in 100 TQFP, 68 QFN, and 49 WLCSP packages.

**Table 49. Package Dimensions**

Spec ID#	Package	Description	Package Dwg #
PKG_1	100-TQFP	100 TQFP package	51-85048
PKG_2	68 QFN	68 QFN package	001-96836
PKG_3	49 WLCSP	49 WLCSP package	002-26627

**Table 50. Package Characteristics**

Parameter	Description	Conditions	Min	Typ	Max	Units
T <sub>A</sub>	Operating ambient temperature	–	–40	25	85	°C
T <sub>J</sub>	Operating junction temperature	–	–40	–	100	°C
T <sub>JA</sub>	Package $\theta_{JA}$ (100 TQFP)	–	–	37.2	–	°C/watt
T <sub>JC</sub>	Package $\theta_{JC}$ (100 TQFP)	–	–	20.7	–	°C/watt
T <sub>JA</sub>	Package $\theta_{JA}$ (68 QFN)	–	–	15.4	–	°C/watt
T <sub>JC</sub>	Package $\theta_{JC}$ (68 QFN)	–	–	2	–	°C/watt
T <sub>JA</sub>	Package $\theta_{JA}$ (49 WLCSP)	–	–	21.5	–	°C/watt
T <sub>JC</sub>	Package $\theta_{JC}$ (49 WLCSP)	–	–	0.21	–	°C/watt

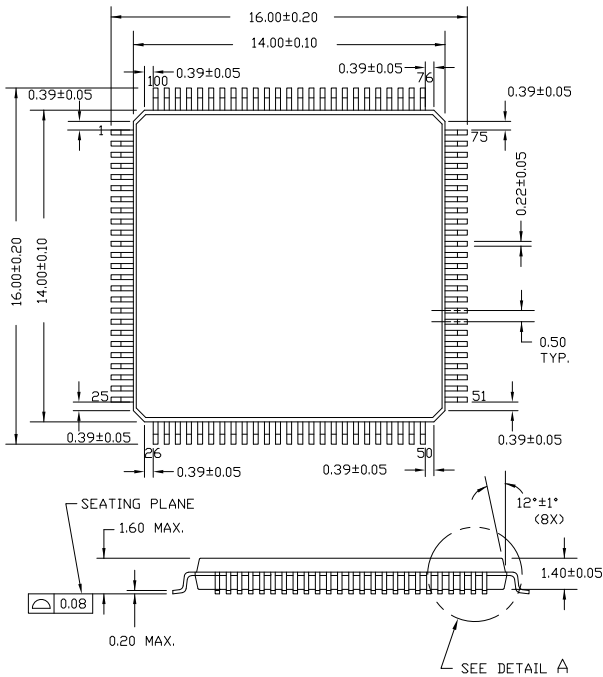
**Table 51. Solder Reflow Peak Temperature**

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
All packages	260 °C	30 seconds

**Table 52. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-2**

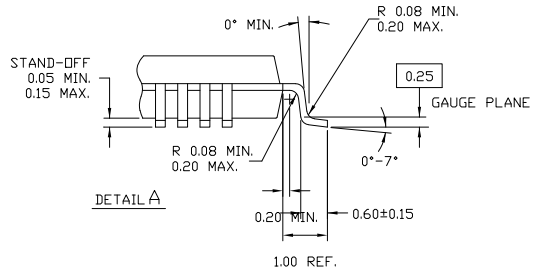
Package	MSL
100 TQFP and 68 QFN	MSL 3
49 WLCSP	MSL 1

Figure 19. 100-TQFP 14.0 × 14.0 × 1.4 mm

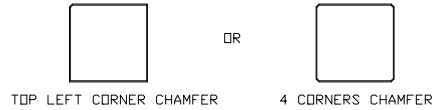


NOTE:

1. JEDEC STD REF MS-026
2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH  
MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.0098 in (0.25 mm) PER SIDE  
BODY LENGTH DIMENSIONS ARE MAX PLASTIC BODY SIZE INCLUDING MOLD MISMATCH
3. DIMENSIONS IN MILLIMETERS

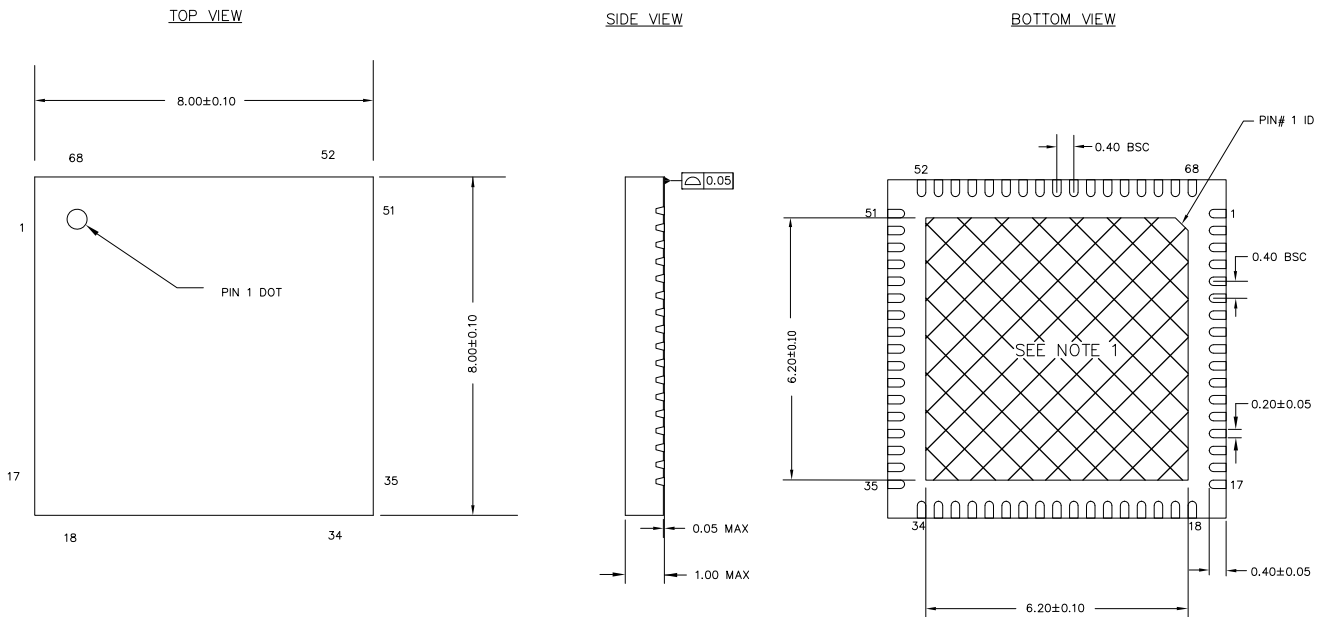


NOTE: PKG. CAN HAVE



51-85048 \*K

Figure 20. 68-QFN Package Diagram

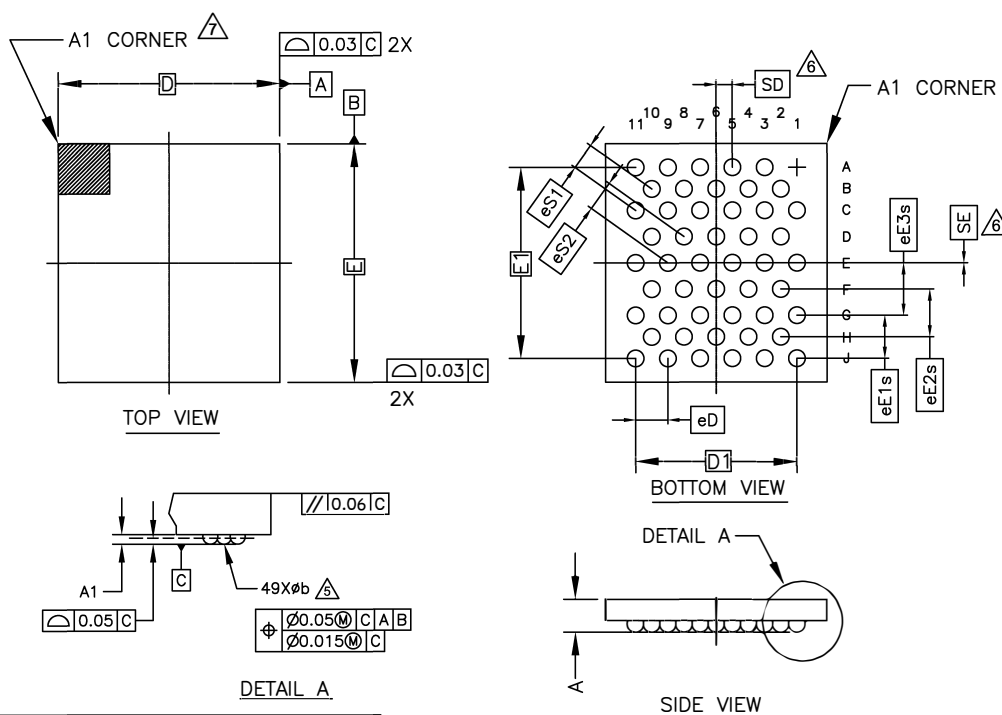


NOTES:

1. HATCH AREA IS SOLDERABLE EXPOSED METAL.
2. REFERENCE JEDEC#: MO-220
3. ALL DIMENSIONS ARE IN MILLIMETERS

001-96836 \*A

Figure 21. 49-Ball WLCSP Package Diagram



SYMBOL	DIMENSIONS		
	MIN	NOM	MAX
A	-	-	0.467
A1	0.122	-	-
D	2.8819 BSC		
E	3.1024 BSC		
D1	2.100 BSC		
E1	2.484 BSC		
MD	11		
ME	9		
N	49		
Øb	0.188	0.218	0.248
eD	0.42 BSC		
eE1s	0.56 BSC		
eE2s	0.621 BSC		
eE3s	0.682 BSC		
eS1	0.35 BSC		
eS2	0.40 BSC		
SD	0.21 BSC		
SE	0.00 BSC		

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
  - SOLDER BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-020.
  - "e" REPRESENTS THE SOLDER BALL GRID PITCH.
  - SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION. N IS THE NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
- ⚠️ DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- ⚠️ "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW. WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW. "SD" OR "SE" = 0. WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW. "SD" = eD/2 AND "SE" = eE/2.
- ⚠️ A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK, METALIZED MARK, INDENTATION OR OTHER MEANS.
- "\*" INDICATES THE THEORETICAL CENTER OF DEPOPULATED SOLDER BALLS.
  - JEDEC SPECIFICATION NO. REF. : N/A.

002-26627 \*A

## Acronyms

Acronym	Description
3DES	triple DES (data encryption standard)
ADC	analog-to-digital converter
ADMA3	advanced DMA version 3, a Secure Digital data transfer mode
AES	advanced encryption standard
AHB	AMBA (advanced microcontroller bus architecture) high-performance bus, an Arm data transfer bus
AMUX	analog multiplexer
AMUXBUS	analog multiplexer bus
API	application programming interface
Arm®	advanced RISC machine, a CPU architecture
BGA	ball grid array
BOD	brown-out detect
BREG	backup registers
BWC	backward compatibility (eMMC data transfer mode)
CAD	computer aided design
CCO	current controlled oscillator
ChaCha	a stream cipher
CM0+	Cortex-M0+, an Arm CPU
CM4	Cortex-M4, an Arm CPU
CMAC	cypher-based message authentication code
CMOS	complementary metal-oxide-semiconductor, a process technology for IC fabrication
CMRR	common-mode rejection ratio
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
CSD	CapSense Sigma-Delta
CSV	clock supervisor
CSX	Cypress mutual capacitance sensing method. See also CSD
CTI	cross trigger interface
DAC	digital-to-analog converter, see also IDAC, VDAC
DAP	debug access port
DDR	double data rate
DES	data encryption standard
DFT	design for test
DMA	direct memory access, see also TD
DNL	differential nonlinearity, see also INL
DSI	digital system interconnect
DU	data unit
DW	data wire, a DMA implementation

Acronym	Description
ECC	error correcting code
ECC	elliptic curve cryptography
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
EMI	electromagnetic interference
eMMC	embedded MultiMediaCard
ESD	electrostatic discharge
ETM	embedded trace macrocell
FIFO	first-in, first-out
FLL	frequency locked loop
FPU	floating-point unit
FS	full-speed
GND	Ground
GPIO	general-purpose input/output, applies to a PSoC pin
HMAC	Hash-based message authentication code
HSIOM	high-speed I/O matrix
I/O	input/output, see also GPIO, DIO, SIO, USBIO
I <sup>2</sup> C, or IIC	Inter-Integrated Circuit, a communications protocol
I <sup>2</sup> S	inter-IC sound
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
IOSS	input output subsystem
IoT	internet of things
IPC	inter-processor communication
IRQ	interrupt request
ISR	interrupt service routine
ITM	instrumentation trace macrocell
JTAG	Joint Test Action Group
LCD	liquid crystal display
LIN	Local Interconnect Network, a communications protocol
LP	low power
LS	low-speed
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVI	low-voltage interrupt
LVTTTL	low-voltage transistor-transistor logic

Acronym	Description
MAC	multiply-accumulate
MCU	microcontroller unit
MISO	master-in slave-out
MMIO	memory-mapped input output
MOSI	master-out slave-in
MPU	memory protection unit
MSL	moisture sensitivity level
MSPS	million samples per second
MTB	micro trace buffer
MUL	multiplier
NC	no connect
NMI	nonmaskable interrupt
NVIC	nested vectored interrupt controller
NVL	nonvolatile latch, see also WOL
OTP	one-time programmable
OVP	over voltage protection
OVT	overvoltage tolerant
PASS	programmable analog subsystem
PCB	printed circuit board
PCM	pulse code modulation
PDM	pulse density modulation
PHY	physical layer
PICU	port interrupt control unit
PLL	phase-locked loop
PMIC	power management integrated circuit
POR	power-on reset
PPU	peripheral protection unit
PRNG	pseudo random number generator
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
QD	quadrature decoder
QSPI	quad serial peripheral interface
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
ROM	read-only memory
RSA	Rivest–Shamir–Adleman, a public-key cryptography algorithm
RTC	real-time clock
RWW	read-while-write
RX	receive
S/H	sample and hold

Acronym	Description
SAR	successive approximation register
SARMUX	SAR ADC multiplexer bus
SC/CT	switched capacitor/continuous time
SCB	serial communication block
SCL	I <sup>2</sup> C serial clock
SD	Secure Digital
SDA	I <sup>2</sup> C serial data
SDHC	Secure Digital host controller
SDR	single data rate
Sflash	supervisory flash
SHA	secure hash algorithm
SINAD	signal to noise and distortion ratio
SMPU	shared memory protection unit
SNR	signal-to-noise ration
SOF	start of frame
SONOS	silicon-oxide-nitride-oxide-silicon, a flash memory technology
SPI	Serial Peripheral Interface, a communications protocol
SRAM	static random access memory
SROM	supervisory read-only memory
SRSS	system resources subsystem
SWD	serial wire debug, a test protocol
SWJ	serial wire JTAG
SWO	single wire output
SWV	single-wire viewer
TCPWM	timer, counter, pulse-width modulator
TDM	time division multiplexed
THD	total harmonic distortion
TQFP	thin quad flat package
TRM	technical reference manual
TRNG	true random number generator
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
ULP	ultra-low power
USB	Universal Serial Bus
WCO	watch crystal oscillator
WDT	watchdog timer
WIC	wakeup interrupt controller
WLCSP	wafer level chip scale package
XIP	execute-in-place
XRES	external reset input pin

## Document Conventions

### Units of Measure

Table 53. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
hr	hour
KHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
μA	microampere
μF	microfarad

Table 53. Units of Measure (continued)

Symbol	Unit of Measure
μH	microhenry
μs	microsecond
μV	microvolt
μW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
W	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt

## Revision History

Description Title: PSoC 6 MCU: CY8C62x5 Datasheet Document Number: 002-26168			
Revision	ECN	Submission Date	Description of Change
**	6441069	01/25/2019	New datasheet for the CY8C62X5, PSoC 62 with 512KB Flash, 256 KB SRAM, and up to 64 I/Os.
*A	6600705	06/21/2019	Changed datasheet status to Preliminary. Updated <a href="#">Pinouts</a> . Updated 68-QFN package outline drawing. Updated <a href="#">Ordering Information</a> .
*B	6671543	09/10/2019	Corrected typo in SIDLPA4. Updated the title. Updated <a href="#">SD Host Controller and eMMC Specifications</a> . Added the 49 WLCSP pin and package details. Added UDB in <a href="#">Acronyms</a> . Added <a href="#">Revision History</a> .
*C	6720641	10/31/2019	Removed reference to CY8C62x8.
*D	6757084	12/19/2019	Updated <a href="#">Features</a> . Updated <a href="#">Blocks and Functionality</a> and <a href="#">Functional Description</a> . Updated <a href="#">Pinouts</a> and <a href="#">Power Supply Considerations</a> .
*E	6839598	03/27/2020	Updated <a href="#">Features</a> and <a href="#">Functional Description</a> Updated <a href="#">Pinouts</a> Updated <a href="#">Ordering Information</a> . Updated <a href="#">Electrical Specifications</a> based on Characterization: Added 2Ms/sec specs to SAR specs, updated SMIF, ECO, and SDHC specs Updated <a href="#">Revision History</a> .
*F	6851682	04/10/2020	Changed datasheet status to Final. Updated SAR ADC 1 Msps references to 2 Msps. Removed reference to e.MMC DDR mode Edited <a href="#">12-bit SAR ADC AC Specifications</a> to split $V_{DDA}$ dependent specs into separate specs instead of having qualifying comments. Moved Supply Range specs from Description column to Details/Conditions column. Added 2 Msps supply current specs. Updated input impedance RC value to support 9RC 12-bit sampling at 2 Msps.
*G	6894902	06/16/2020	Updated <a href="#">Development Ecosystem</a> , <a href="#">GPIO</a> , and <a href="#">LCD</a> sections. Added <a href="#">External Crystal Oscillators</a> . Updated <a href="#">Revision History</a> .

Description Title: PSoC 6 MCU: CY8C62x5 Datasheet Document Number: 002-26168			
*H	6981432	11/16/2020	<p>Updated <a href="#">Flexible Clocking Options</a>, <a href="#">Block Diagram</a>, and <a href="#">CPUs</a>.</p> <p>Updated list of application notes and links in <a href="#">PSoC 6 MCU Resources</a>.</p> <p>Updated <a href="#">ModusToolbox Software</a>.</p> <p>Updated <a href="#">Quad-SPI (QSPI)/Serial Memory Interface (SMIF)</a>.</p> <p>Added <a href="#">InterProcessor Communication (IPC)</a>.</p> <p>Updated <a href="#">Analog Subsystem</a> diagram.</p> <p>Updated <a href="#">Direct Memory Access (DMA) Controllers</a>.</p> <p>Corrected error in VDDIO0 pin number in <a href="#">Table 8</a>.</p> <p>Updated VDDA bullet in <a href="#">Power Supply Considerations</a>.</p> <p>Updated the XRES bullet in <a href="#">Reset</a>, <a href="#">SID15 Description and Conditions</a>, and <a href="#">System Resources (Power-On-Reset specifications)</a></p> <p>Updated <a href="#">SID7A</a> conditions, <a href="#">SID7D</a> description, and <a href="#">SID8</a> conditions.</p> <p>Updated <a href="#">SD Host Controller and eMMC Specifications</a>.</p> <p>Integrated ECO erratum into <a href="#">External Crystal Oscillators</a>. Added <a href="#">ECO Usage Guidelines</a> table.</p>
*I	7139142	05/17/2021	<p>Updated Security terminology to Infineon standards.</p> <p>Changed BLE references to Bluetooth LE.</p> <p>Added <a href="#">Table 14</a> and <a href="#">Figure 33</a> in <a href="#">Electrical Specifications</a>.</p>
*J	7487079	12/06/2021	<p>Updated <a href="#">Figure 6</a>.</p> <p>Added note regarding unused USB pins in <a href="#">USB Full-Speed Device Interface</a>, <a href="#">Power Supply Considerations</a>, and <a href="#">Pinouts</a>.</p> <p>Updated <a href="#">SIDC1</a> description.</p> <p>Updated details/conditions for <a href="#">SID7A</a>.</p> <p>Updated <a href="#">SID325U</a>, <a href="#">SID328</a>, and <a href="#">SID329</a> description.</p>
*K	7750278	04/13/2022	Updated eFuse description in the <a href="#">Memory</a> section.
*L	7758801	05/06/2022	Corrected typo in <a href="#">Figure 11</a> , <a href="#">Figure 12</a> , <a href="#">Figure 13</a> , and <a href="#">Figure 14</a> .
*M	7788568	10/26/2022	<p>Added device identification and revision information in <a href="#">Features</a>.</p> <p>Added spec <a href="#">SID304P</a>.</p> <p>Updated <a href="#">PLL Specifications</a> and <a href="#">Clock System</a>.</p> <p>Updated <a href="#">Protection Units</a>.</p>

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